



MSP430F543x and MSP430F541x Mixed-Signal Microcontrollers

1 Device Overview

1.1 Features

- Low Supply Voltage Range: 2.2 V to 3.6 V
- Ultralow Power Consumption
 - Active Mode (AM): All System Clocks Active
 - 312 μ A/MHz at 8 MHz, 3.0 V, Flash Program Execution (Typical)
 - 140 μ A/MHz at 8 MHz, 3.0 V, RAM Program Execution (Typical)
 - Standby Mode (LPM3):
 - Real-Time Clock (RTC) With Crystal, Watchdog, and Supply Supervisor Operational, Full RAM Retention, Fast Wakeup: 2.6 μ A at 3.0 V (Typical)
 - Low-Power Oscillator (VLO), General-Purpose Counter, Watchdog, and Supply Supervisor Operational, Full RAM Retention, Fast Wakeup: 1.8 μ A at 3.0 V (Typical)
 - Off Mode (LPM4):
 - Full RAM Retention, Supply Supervisor Operational, Fast Wakeup: 1.69 μ A at 3.0 V (Typical)
- Wakeup From Standby Mode in Less Than 5 μ s
- 16-Bit RISC Architecture
 - Extended Memory
 - Up to 18-MHz System Clock
- Flexible Power Management System
 - Fully Integrated LDO With Programmable Regulated Core Supply Voltage
 - Supply Voltage Supervision, Monitoring, and Brownout
- Unified Clock System
 - FLL Control Loop for Frequency Stabilization
 - Low-Power Low-Frequency Internal Clock Source (VLO)
 - Low-Frequency Trimmed Internal Reference Source (REFO)
 - 32-kHz Crystals
 - High-Frequency Crystals up to 32 MHz
- 16-Bit Timer TA0, Timer_A With Five Capture/Compare Registers
- 16-Bit Timer TA1, Timer_A With Three Capture/Compare Registers
- 16-Bit Timer TB0, Timer_B With Seven Capture/Compare Shadow Registers
- Up to Four Universal Serial Communication Interfaces
 - USCI_A0, USCI_A1, USCI_A2, and USCI_A3 Each Support:
 - Enhanced UART Supports Automatic Baud-Rate Detection
 - IrDA Encoder and Decoder
 - Synchronous SPI
 - USCI_B0, USCI_B1, USCI_B2, and USCI_B3 Each Support:
 - I²C
 - Synchronous SPI
- 12-Bit Analog-to-Digital Converter (ADC)
 - Internal Reference
 - Sample-and-Hold
 - Autoscan Feature
 - 14 External Channels, 2 Internal Channels
- Hardware Multiplier Supporting 32-Bit Operations
- Serial Onboard Programming, No External Programming Voltage Needed
- Three-Channel Internal DMA
- Basic Timer With RTC Feature
- [Section 3](#) Summarizes the Available Family Members
- For Complete Module Descriptions, See the *MSP430x5xx and MSP430x6xx Family User's Guide* ([SLAU208](#))

1.2 Applications

- Analog and Digital Sensor Systems
- Digital Motor Control
- Remote Controls
- Thermostats
- Digital Timers
- Hand-Held Meters



1.3 Description

The Texas Instruments MSP430™ family of ultralow-power microcontrollers consists of several devices featuring different sets of peripherals targeted for various applications. The architecture, combined with five low-power modes, is optimized to achieve extended battery life in portable measurement applications. The device features a powerful 16-bit RISC CPU, 16-bit registers, and constant generators that contribute to maximum code efficiency. The digitally controlled oscillator (DCO) allows the device to wake up from low-power modes to active mode in less than 5 μ s.

The MSP430F543x and MSP430F541x series are microcontroller configurations with three 16-bit timers, a high-performance 12-bit analog-to-digital converter (ADC), up to four universal serial communication interfaces (USCIs), a hardware multiplier, DMA, a real-time clock (RTC) module with alarm capabilities, and up to 87 I/O pins.

Typical applications for this device include analog and digital sensor systems, digital motor control, remote controls, thermostats, digital timers, and hand-held meters.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE ⁽²⁾
MSP430F5438PZ	LQFP (100)	14 mm x 14 mm
MSP430F5437PN	LQFP (80)	12 mm x 12 mm
MSP430F5436PZ	LQFP (100)	14 mm x 14 mm
MSP430F5435PN	LQFP (80)	12 mm x 12 mm
MSP430F5419PZ	LQFP (100)	14 mm x 14 mm
MSP430F5418PN	LQFP (80)	12 mm x 12 mm

- (1) For the most current device, package, and ordering information, see the *Package Option Addendum* in [Section 8](#), or see the TI web site at www.ti.com.
- (2) The sizes shown here are approximations. For the package dimensions with tolerances, see the *Mechanical Data* in [Section 8](#).

1.4 Functional Block Diagrams

Figure 1-1 shows the functional block diagram for the devices in the PZ package.

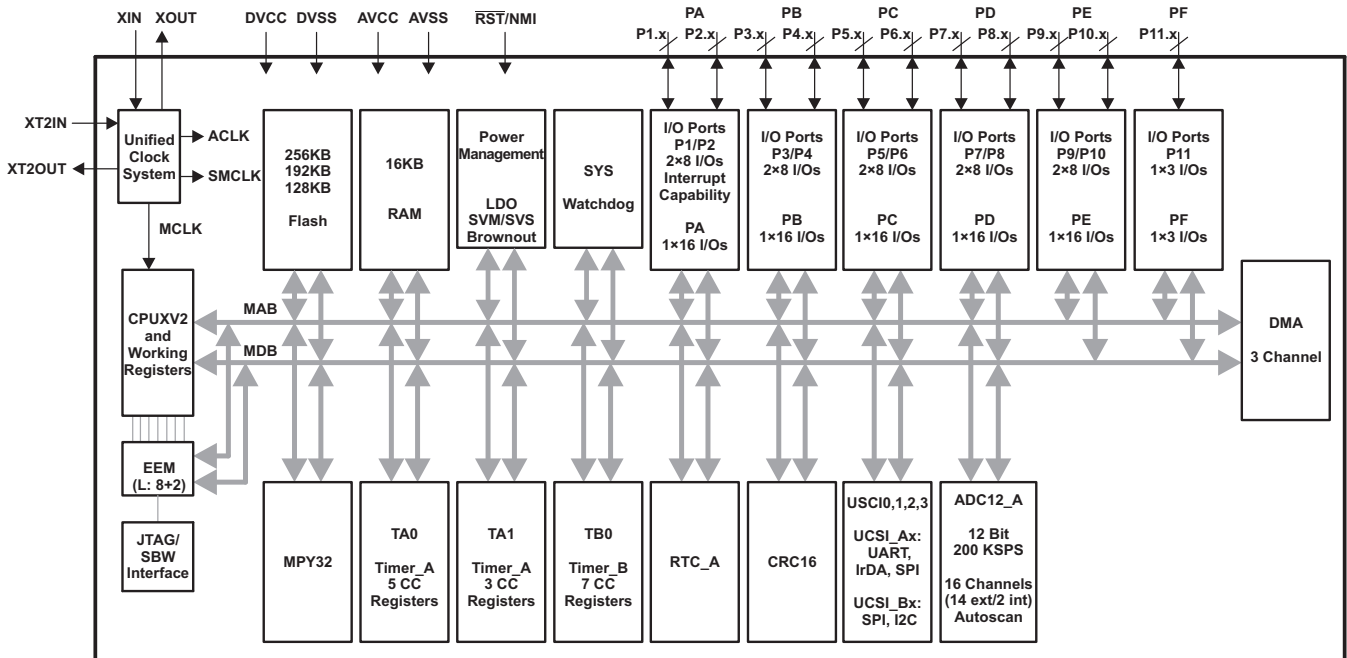


Figure 1-1. Functional Block Diagram, MSP430F5438IPZ, MSP430F5436IPZ, MSP430F5419IPZ

Figure 1-2 shows the functional block diagram of the devices in the PN package.

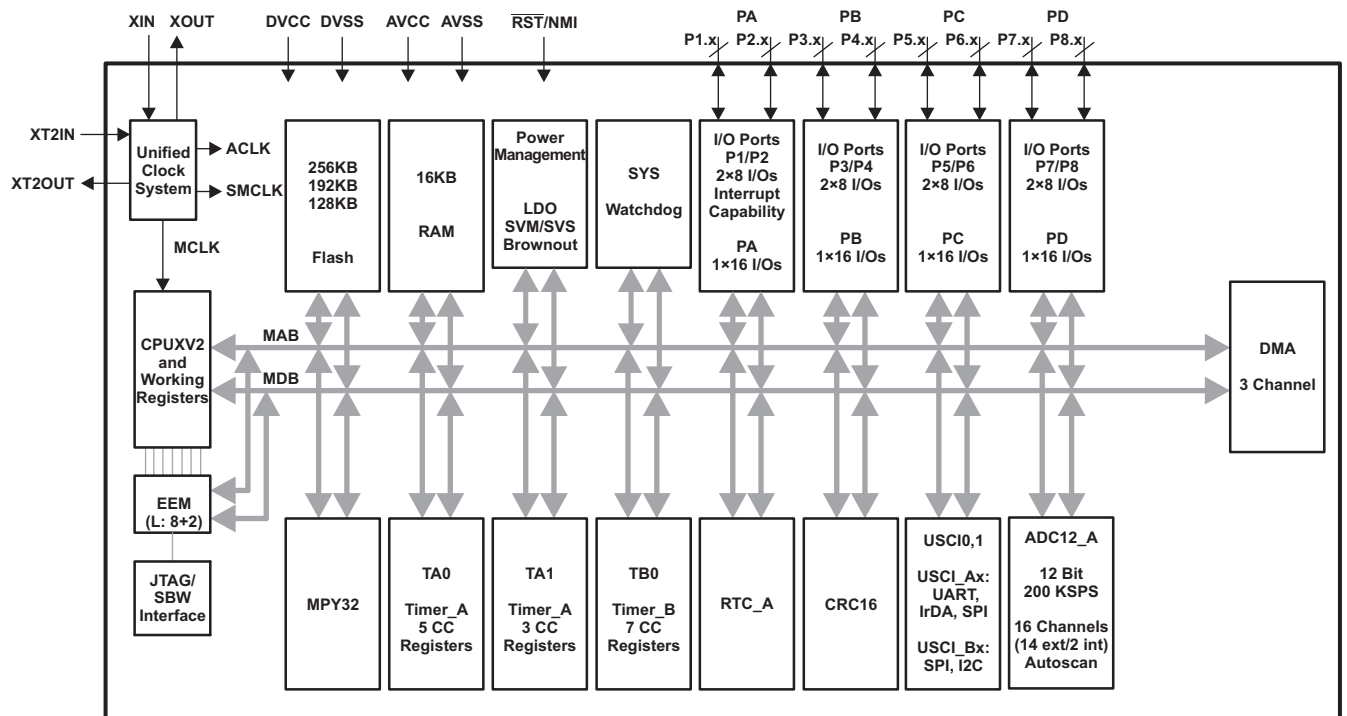


Figure 1-2. Functional Block Diagram, MSP430F5437IPN, MSP430F5435IPN, MSP430F5418IPN

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2 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision D (August 2013) to Revision E	Page
• Format changes throughout document, including addition of section numbering	1
• Added Section 1.4 and moved the functional block diagrams to it	3
• Added Section 5 and moved all electrical specifications to it	14
• Added Section 5.2 and moved T_{stg} to it	14
• Added note to CVCORE	14
• Moved Section 5.6	16
• Changed TYP value from 2 pF to 1 pF for $C_{L,eff}$ with test conditions of "XTS = 0, XCAPx = 0"	21
• Added "Factory memory" entries to Memory Organization (Table 6-2)	42
• Added Section 7 and moved <i>Development Tools Support</i> and <i>Device and Development Tool Nomenclature</i> sections to it	93
• Added Section 8	97

3 Device Comparison

Table 3-1 summarizes the available family members.

Table 3-1. Family Members⁽¹⁾⁽²⁾

Device	Flash (KB)	SRAM (KB)	Timer_A ⁽³⁾	Timer_B ⁽⁴⁾	USCI		ADC12_A (Ch)	I/O	Package Type
					Channel A: UART, IrDA, SPI	Channel B: SPI, I ² C			
MSP430F5438	256	16	5, 3	7	4	4	14 ext, 2 int	87	100 PZ
MSP430F5437	256	16	5, 3	7	2	2	14 ext, 2 int	67	80 PN
MSP430F5436	192	16	5, 3	7	4	4	14 ext, 2 int	87	100 PZ
MSP430F5435	192	16	5, 3	7	2	2	14 ext, 2 int	67	80 PN
MSP430F5419	128	16	5, 3	7	4	4	14 ext, 2 int	87	100 PZ
MSP430F5418	128	16	5, 3	7	2	2	14 ext, 2 int	67	80 PN

- (1) For the most current package and ordering information, see the *Package Option Addendum* in [Section 8](#), or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (3) Each number in the sequence represents an instantiation of Timer_A with its associated number of capture compare registers and PWM output generators available. For example, a number sequence of 3, 5 would represent two instantiations of Timer_A, the first instantiation having 3 and the second instantiation having 5 capture compare registers and PWM output generators, respectively.
- (4) Each number in the sequence represents an instantiation of Timer_B with its associated number of capture compare registers and PWM output generators available. For example, a number sequence of 3, 5 would represent two instantiations of Timer_B, the first instantiation having 3 and the second instantiation having 5 capture compare registers and PWM output generators, respectively.

4 Terminal Configuration and Functions

4.1 Pin Diagrams

Figure 4-1 shows the pin diagram for the MSP430F5438, MSP430F5436, and MSP430F5419 devices in the PZ package.

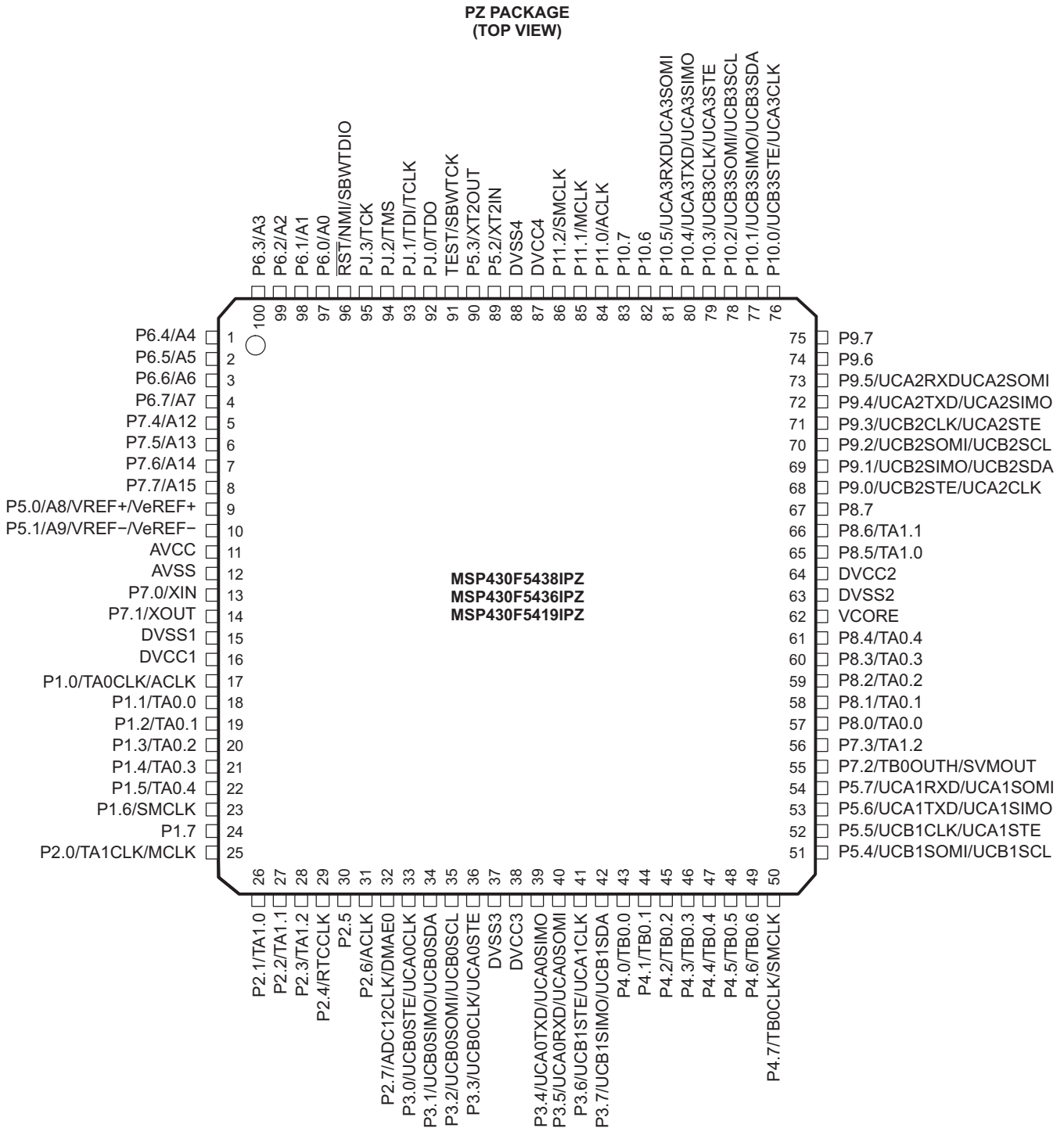


Figure 4-1. Pin Designation – MSP430F5438IPZ, MSP430F5436IPZ, MSP430F5419IPZ

Figure 4-2 shows the pin diagram for the MSP430F5437, MSP430F5435, and MSP430F5418 devices in the PN package.

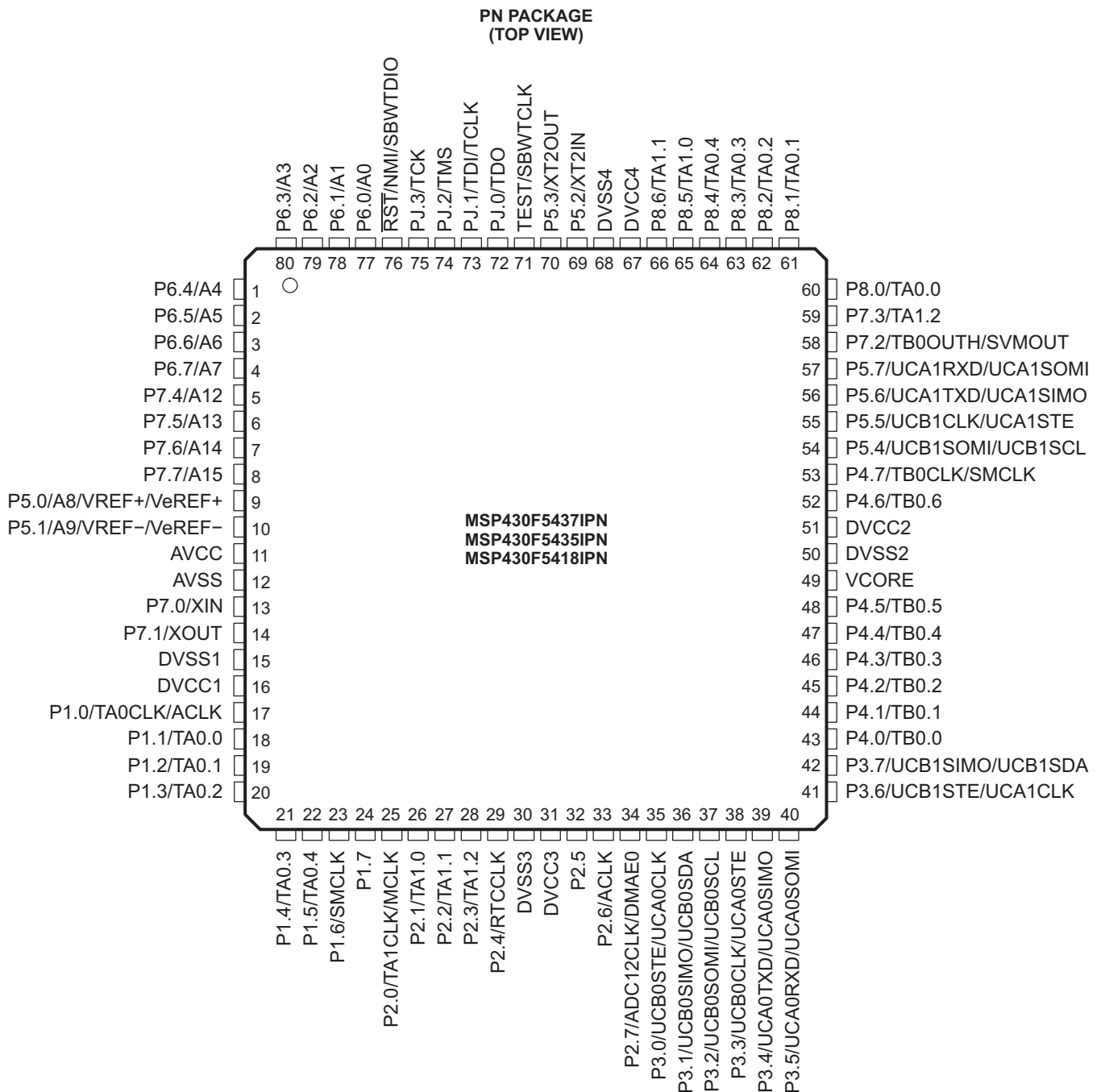


Figure 4-2. Pin Designation – MSP430F5437IPN, MSP430F5435IPN, MSP430F5418IPN

4.2 Signal Descriptions

Table 4-1 describes the signals for all device variants and package options.

Table 4-1. Terminal Functions

TERMINAL			I/O ⁽¹⁾	DESCRIPTION
NAME	NO.			
	PZ	PN		
P6.4/A4	1	1	I/O	General-purpose digital I/O Analog input A4 – ADC
P6.5/A5	2	2	I/O	General-purpose digital I/O Analog input A5 – ADC
P6.6/A6	3	3	I/O	General-purpose digital I/O Analog input A6 – ADC
P6.7/A7	4	4	I/O	General-purpose digital I/O Analog input A7 – ADC
P7.4/A12	5	5	I/O	General-purpose digital I/O Analog input A12 –ADC
P7.5/A13	6	6	I/O	General-purpose digital I/O Analog input A13 – ADC
P7.6/A14	7	7	I/O	General-purpose digital I/O Analog input A14 – ADC
P7.7/A15	8	8	I/O	General-purpose digital I/O Analog input A15 – ADC
P5.0/A8/VREF+/VeREF+	9	9	I/O	General-purpose digital I/O Analog input A8 – ADC Output of reference voltage to the ADC Input for an external reference voltage to the ADC
P5.1/A9/VREF-/VeREF-	10	10	I/O	General-purpose digital I/O Analog input A9 – ADC Negative terminal for the ADC's reference voltage for both sources, the internal reference voltage, or an external applied reference voltage
AVCC	11	11		Analog power supply
AVSS	12	12		Analog ground supply
P7.0/XIN	13	13	I/O	General-purpose digital I/O Input terminal for crystal oscillator XT1
P7.1/XOUT	14	14	I/O	General-purpose digital I/O Output terminal of crystal oscillator XT1
DVSS1	15	15		Digital ground supply
DVCC1	16	16		Digital power supply
P1.0/TA0CLK/ACLK	17	17	I/O	General-purpose digital I/O with port interrupt TA0 clock signal TACLK input ACLK output (divided by 1, 2, 4, 8, 16, or 32)
P1.1/TA0.0	18	18	I/O	General-purpose digital I/O with port interrupt TA0 CCR0 capture: CCI0A input, compare: Out0 output BSL transmit output
P1.2/TA0.1	19	19	I/O	General-purpose digital I/O with port interrupt TA0 CCR1 capture: CCI1A input, compare: Out1 output BSL receive input
P1.3/TA0.2	20	20	I/O	General-purpose digital I/O with port interrupt TA0 CCR2 capture: CCI2A input, compare: Out2 output
P1.4/TA0.3	21	21	I/O	General-purpose digital I/O with port interrupt TA0 CCR3 capture: CCI3A input compare: Out3 output
P1.5/TA0.4	22	22	I/O	General-purpose digital I/O with port interrupt TA0 CCR4 capture: CCI4A input, compare: Out4 output
P1.6/SMCLK	23	23	I/O	General-purpose digital I/O with port interrupt SMCLK output
P1.7	24	24	I/O	General-purpose digital I/O with port interrupt

(1) I = input, O = output, N/A = not available on this package offering

Table 4-1. Terminal Functions (continued)

TERMINAL			I/O ⁽¹⁾	DESCRIPTION
NAME	NO.			
	PZ	PN		
P2.0/TA1CLK/MCLK	25	25	I/O	General-purpose digital I/O with port interrupt TA1 clock signal TA1CLK input MCLK output
P2.1/TA1.0	26	26	I/O	General-purpose digital I/O with port interrupt TA1 CCR0 capture: CCI0A input, compare: Out0 output
P2.2/TA1.1	27	27	I/O	General-purpose digital I/O with port interrupt TA1 CCR1 capture: CCI1A input, compare: Out1 output
P2.3/TA1.2	28	28	I/O	General-purpose digital I/O with port interrupt TA1 CCR2 capture: CCI2A input, compare: Out2 output
P2.4/RTCCCLK	29	29	I/O	General-purpose digital I/O with port interrupt RTCCCLK output
P2.5	30	32	I/O	General-purpose digital I/O with port interrupt
P2.6/ACLK	31	33	I/O	General-purpose digital I/O with port interrupt ACLK output (divided by 1, 2, 4, 8, 16, or 32)
P2.7/ADC12CLK/DMAE0	32	34	I/O	General-purpose digital I/O with port interrupt Conversion clock output ADC DMA external trigger input
P3.0/UCB0STE/UCA0CLK	33	35	I/O	General-purpose digital I/O Slave transmit enable – USCI_B0 SPI mode Clock signal input – USCI_A0 SPI slave mode Clock signal output – USCI_A0 SPI master mode
P3.1/UCB0SIMO/UCB0SDA	34	36	I/O	General-purpose digital I/O Slave in, master out – USCI_B0 SPI mode I2C data – USCI_B0 I2C mode
P3.2/UCB0SOMI/UCB0SCL	35	37	I/O	General-purpose digital I/O Slave out, master in – USCI_B0 SPI mode I2C clock – USCI_B0 I2C mode
P3.3/UCB0CLK/UCA0STE	36	38	I/O	General-purpose digital I/O Clock signal input – USCI_B0 SPI slave mode Clock signal output – USCI_B0 SPI master mode Slave transmit enable – USCI_A0 SPI mode
DVSS3	37	30		Digital ground supply
DVCC3	38	31		Digital power supply
P3.4/UCA0TXD/UCA0SIMO	39	39	I/O	General-purpose digital I/O Transmit data – USCI_A0 UART mode Slave in, master out – USCI_A0 SPI mode
P3.5/UCA0RXD/UCA0SOMI	40	40	I/O	General-purpose digital I/O Receive data – USCI_A0 UART mode Slave out, master in – USCI_A0 SPI mode
P3.6/UCB1STE/UCA1CLK	41	41	I/O	General-purpose digital I/O Slave transmit enable – USCI_B1 SPI mode Clock signal input – USCI_A1 SPI slave mode Clock signal output – USCI_A1 SPI master mode
P3.7/UCB1SIMO/UCB1SDA	42	42	I/O	General-purpose digital I/O Slave in, master out – USCI_B1 SPI mode I2C data – USCI_B1 I2C mode
P4.0/TB0.0	43	43	I/O	General-purpose digital I/O TB0 capture CCR0: CCI0A/CCI0B input, compare: Out0 output
P4.1/TB0.1	44	44	I/O	General-purpose digital I/O TB0 capture CCR1: CCI1A/CCI1B input, compare: Out1 output
P4.2/TB0.2	45	45	I/O	General-purpose digital I/O TB0 capture CCR2: CCI2A/CCI2B input, compare: Out2 output
P4.3/TB0.3	46	46	I/O	General-purpose digital I/O TB0 capture CCR3: CCI3A/CCI3B input, compare: Out3 output
P4.4/TB0.4	47	47	I/O	General-purpose digital I/O TB0 capture CCR4: CCI4A/CCI4B input, compare: Out4 output

Table 4-1. Terminal Functions (continued)

TERMINAL		NO.	I/O ⁽¹⁾	DESCRIPTION	
NAME	PZ				PN
P4.6/TB0.6	49	52	I/O	General-purpose digital I/O TB0 capture CCR6: CCI6A/CCI6B input, compare: Out6 output	
P4.7/TB0CLK/SMCLK	50	53	I/O	General-purpose digital I/O TB0 clock input SMCLK output	
P5.4/UCB1SOMI/UCB1SCL	51	54	I/O	General-purpose digital I/O Slave out, master in – USCI_B1 SPI mode I2C clock – USCI_B1 I2C mode	
P5.5/UCB1CLK/UCA1STE	52	55	I/O	General-purpose digital I/O Clock signal input – USCI_B1 SPI slave mode Clock signal output – USCI_B1 SPI master mode Slave transmit enable – USCI_A1 SPI mode	
P5.6/UCA1TXD/UCA1SIMO	53	56	I/O	General-purpose digital I/O Transmit data – USCI_A1 UART mode Slave in, master out – USCI_A1 SPI mode	
P5.7/UCA1RXD/UCA1SOMI	54	57	I/O	General-purpose digital I/O Receive data – USCI_A1 UART mode Slave out, master in – USCI_A1 SPI mode	
P7.2/TB0OUTH/SVMOUT	55	58	I/O	General-purpose digital I/O Switch all PWM outputs high impedance – Timer TB0 SVM output	
P7.3/TA1.2	56	59	I/O	General-purpose digital I/O TA1 CCR2 capture: CCI2B input, compare: Out2 output	
P8.0/TA0.0	57	60	I/O	General-purpose digital I/O TA0 CCR0 capture: CCI0B input, compare: Out0 output	
P8.1/TA0.1	58	61	I/O	General-purpose digital I/O TA0 CCR1 capture: CCI1B input, compare: Out1 output	
P8.2/TA0.2	59	62	I/O	General-purpose digital I/O TA0 CCR2 capture: CCI2B input, compare: Out2 output	
P8.3/TA0.3	60	63	I/O	General-purpose digital I/O TA0 CCR3 capture: CCI3B input, compare: Out3 output	
P8.4/TA0.4	61	64	I/O	General-purpose digital I/O TA0 CCR4 capture: CCI4B input, compare: Out4 output	
VCORE ⁽²⁾	62	49		Regulated core power supply output (internal use only, no external current loading)	
DVSS2	63	50		Digital ground supply	
DVCC2	64	51		Digital power supply	
P8.5/TA1.0	65	65	I/O	General-purpose digital I/O TA1 CCR0 capture: CCI0B input, compare: Out0 output	
P8.6/TA1.1	66	66	I/O	General-purpose digital I/O TA1 CCR1 capture: CCI1B input, compare: Out1 output	
P8.7	67	N/A	I/O	General-purpose digital I/O	
P9.0/UCB2STE/UCA2CLK	68	N/A	I/O	General-purpose digital I/O Slave transmit enable – USCI_B2 SPI mode Clock signal input – USCI_A2 SPI slave mode Clock signal output – USCI_A2 SPI master mode	
P9.1/UCB2SIMO/UCB2SDA	69	N/A	I/O	General-purpose digital I/O Slave in, master out – USCI_B2 SPI mode I2C data – USCI_B2 I2C mode	
P9.2/UCB2SOMI/UCB2SCL	70	N/A	I/O	General-purpose digital I/O Slave out, master in – USCI_B2 SPI mode I2C clock – USCI_B2 I2C mode	

(2) VCORE is for internal use only. No external current loading is possible. VCORE should only be connected to the recommended capacitor value, C_{VCORE}.

Table 4-1. Terminal Functions (continued)

TERMINAL		NO.	I/O ⁽¹⁾	DESCRIPTION
NAME	PZ			
P9.3/UCB2CLK/UCA2STE	71	N/A	I/O	General-purpose digital I/O Clock signal input – USCI_B2 SPI slave mode Clock signal output – USCI_B2 SPI master mode Slave transmit enable – USCI_A2 SPI mode
P9.4/UCA2TXD/UCA2SIMO	72	N/A	I/O	General-purpose digital I/O Transmit data – USCI_A2 UART mode Slave in, master out – USCI_A2 SPI mode
P9.5/UCA2RXD/UCA2SOMI	73	N/A	I/O	General-purpose digital I/O Receive data – USCI_A2 UART mode Slave out, master in – USCI_A2 SPI mode
P9.6	74	N/A	I/O	General-purpose digital I/O
P9.7	75	N/A	I/O	General-purpose digital I/O
P10.0/UCB3STE/UCA3CLK	76	N/A	I/O	General-purpose digital I/O Slave transmit enable – USCI_B3 SPI mode Clock signal input – USCI_A3 SPI slave mode Clock signal output – USCI_A3 SPI master mode
P10.1/UCB3SIMO/UCB3SDA	77	N/A	I/O	General-purpose digital I/O Slave in, master out – USCI_B3 SPI mode I2C data – USCI_B3 I2C mode
P10.2/UCB3SOMI/UCB3SCL	78	N/A	I/O	General-purpose digital I/O Slave out, master in – USCI_B3 SPI mode I2C clock – USCI_B3 I2C mode
P10.3/UCB3CLK/UCA3STE	79	N/A	I/O	General-purpose digital I/O Clock signal input – USCI_B3 SPI slave mode Clock signal output – USCI_B3 SPI master mode Slave transmit enable – USCI_A3 SPI mode
P10.4/UCA3TXD/UCA3SIMO	80	N/A	I/O	General-purpose digital I/O Transmit data – USCI_A3 UART mode Slave in, master out – USCI_A3 SPI mode
P10.5/UCA3RXD/UCA3SOMI	81	N/A	I/O	General-purpose digital I/O Receive data – USCI_A3 UART mode Slave out, master in – USCI_A3 SPI mode
P10.6	82	N/A	I/O	General-purpose digital I/O
P10.7	83	N/A	I/O	General-purpose digital I/O
P11.0/ACLK	84	N/A	I/O	General-purpose digital I/O ACLK output (divided by 1, 2, 4, 8, 16, or 32)
P11.1/MCLK	85	N/A	I/O	General-purpose digital I/O MCLK output
P11.2/SMCLK	86	N/A	I/O	General-purpose digital I/O SMCLK output
DVCC4	87	67		Digital power supply
DVSS4	88	68		Digital ground supply
P5.2/XT2IN	89	69	I/O	General-purpose digital I/O Input terminal for crystal oscillator XT2
P5.3/XT2OUT	90	70	I/O	General-purpose digital I/O Output terminal of crystal oscillator XT2
TEST/SBWTK ⁽³⁾	91	71	I	Test mode pin – select digital I/O on JTAG pins Spy-bi-wire input clock
PJ.0/TDO ⁽⁴⁾	92	72	I/O	General-purpose digital I/O Test data output port
PJ.1/TDI/TCLK ⁽⁴⁾	93	73	I/O	General-purpose digital I/O Test data input or test clock input

(3) See [Section 6.5](#) and [Section 6.6](#) for use with BSL and JTAG functions

(4) See [Section 6.6](#) for use with JTAG function.

Table 4-1. Terminal Functions (continued)

TERMINAL			I/O ⁽¹⁾	DESCRIPTION
NAME	NO.			
	PZ	PN		
PJ.2/TMS ⁽⁴⁾	94	74	I/O	General-purpose digital I/O Test mode select
PJ.3/TCK ⁽⁴⁾	95	75	I/O	General-purpose digital I/O Test clock
$\overline{\text{RST}}$ /NMI/SBWDIO ⁽³⁾	96	76	I/O	Reset input active low Non-maskable interrupt input Spy-bi-wire data input/output
P6.0/A0	97	77	I/O	General-purpose digital I/O Analog input A0 – ADC
P6.1/A1	98	78	I/O	General-purpose digital I/O Analog input A1 – ADC
P6.2/A2	99	79	I/O	General-purpose digital I/O Analog input A2 – ADC
P6.3/A3	100	80	I/O	General-purpose digital I/O Analog input A3 – ADC
Reserved	N/A	N/A		

5 Specifications

5.1 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

Voltage V_{CC} applied at supply pins DVCC/AVCC to supply pins DVSS/AVSS	-0.3 V to 4.1 V
Voltage applied to any pin (excluding V _{CORE}) ⁽²⁾	-0.3 V to $V_{CC} + 0.3$ V
Diode current at any device pin	±2 mA
Maximum operating junction temperature, T_J	95°C

- Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- All voltages referenced to V_{SS} . V_{CORE} is for internal device use only. No external dc loading or voltage should be applied.

5.2 Handling Ratings

		MIN	MAX	UNIT
T_{stg}	Storage temperature range ⁽¹⁾	-55	150	°C

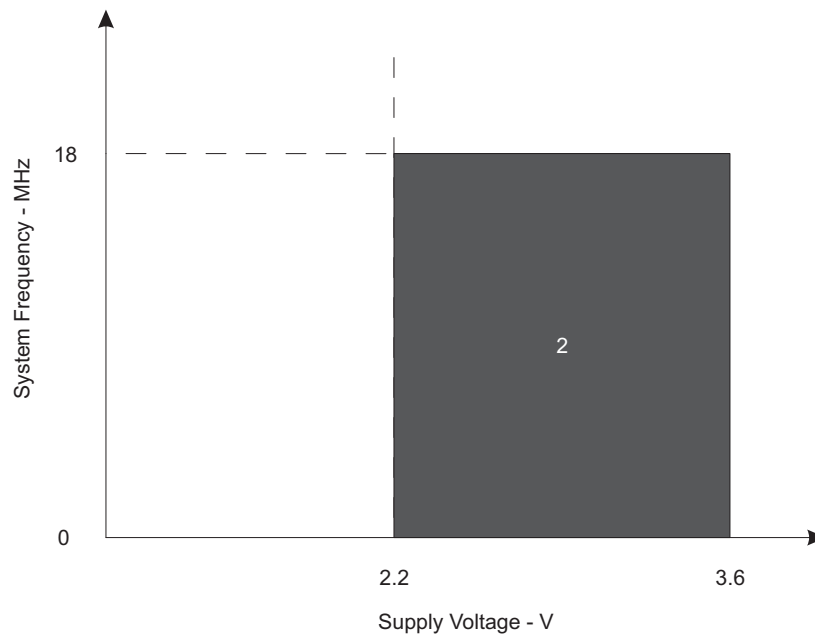
- Higher temperature may be applied during board soldering according to the current JEDEC J-STD-020 specification with peak reflow temperatures not higher than classified on the device label on the shipping boxes or reels.

5.3 Recommended Operating Conditions

Typical values are specified at $V_{CC} = 3.3$ V and $T_A = 25$ °C (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage during program execution and flash programming ($V_{CC} = DV_{CC1/2/3/4} = AV_{CC}$) ⁽¹⁾⁽²⁾		2.2		3.6	V
V_{SS}	Supply voltage ($V_{SS} = DV_{SS1/2/3/4} = DV_{SS} = AV_{SS}$)			0		V
T_A	Operating free-air temperature	I version	-40		85	°C
T_J	Operating junction temperature	I version	-40		85	°C
CVCORE	Recommended capacitor at V _{CORE} ⁽³⁾			470		nF
CDVCC/ CVCORE	Capacitor ratio of DVCC to V _{CORE}			10		
f_{SYSTEM}	Processor frequency (maximum MCLK frequency) ^{(4) (5)} (see Figure 5-1)	PMMCOREVx = 2, 2.2 V ≤ V_{CC} ≤ 3.6 V		0	18	MHz

- It is recommended to power AV_{CC} and DV_{CC} from the same source. A maximum difference of 0.3 V between AV_{CC} and DV_{CC} can be tolerated during power up and operation.
- The minimum supply voltage is defined by the supervisor SVS levels when it is enabled. See the [Section 5.23](#) threshold parameters for the exact values and further details.
- A capacitor tolerance of ±20% or better is required.
- The MSP430 CPU is clocked directly with MCLK. Both the high and low phase of MCLK must not exceed the pulse width of the specified maximum frequency.
- Modules may have a different maximum input clock specification. See the specification of the respective module in this data sheet.



The numbers within the fields denote the supported PMMCOREVx settings.

Figure 5-1. Frequency vs Supply Voltage

5.4 Active Mode Supply Current Into V_{CC} Excluding External Current

over recommended operating free-air temperature (unless otherwise noted)^{(1) (2) (3)}

PARAMETER	EXECUTION MEMORY	V_{CC}	PMMCOREVx	Frequency ($f_{DCO} = f_{MCLK} = f_{SMCLK}$)								UNIT
				1 MHz		4 MHz		8 MHz		16 MHz		
				TYP	MAX	TYP	MAX	TYP	MAX	TYP	MAX	
$I_{AM, Flash}$	Flash	3.0 V	2	0.37	0.45	1.27	1.47	2.50	2.84	5.00	5.56	mA
$I_{AM, RAM}$	RAM	3.0 V	2	0.20	0.29	0.60	0.72	1.12	1.27	2.20	2.60	mA

- All inputs are tied to 0 V or to V_{CC} . Outputs do not source or sink any current.
- The currents are characterized with a Micro Crystal MS1V-T1K crystal with a load capacitance of 12.5 pF. The internal and external load capacitance are chosen to closely match the required 12.5 pF.
- Characterized with program executing worst case JMP \$.
 $f_{ACLK} = 32786$ Hz, $f_{DCO} = f_{MCLK} = f_{SMCLK}$ at specified frequency.
XTS = CPUOFF = SCG0 = SCG1 = OSCOFF = SMCLKOFF = 0.

5.5 Low-Power Mode Supply Currents (Into V_{CC}) Excluding External Current

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)^{(1) (2)}

PARAMETER	V_{CC}	PMMCOREVx	-40 °C		25 °C		55 °C		85 °C		UNIT
			TYP	MAX	TYP	MAX	TYP	MAX	TYP	MAX	
$I_{LPM0, 1MHz}$ Low-power mode 0 ⁽³⁾ (4)	3.0 V	2	86	98	86	98	86	98	86	98	μA
I_{LPM2} Low-power mode 2 ⁽⁵⁾ (4)	3.0 V	2	8.0	15.6	8.0	15.6	8.0	15.6	8.0	15.6	μA
$I_{LPM3, XT1LF}$ Low-power mode 3, crystal mode ⁽⁶⁾ (4)	3.0 V	2	2.3		2.6	3.37	4.5		7.9	15.6	μA
$I_{LPM3, VLO}$ Low-power mode 3, VLO mode ⁽⁷⁾ (4)	3.0 V	2	1.39		1.80	2.30	2.95		6.9	14.6	μA
I_{LPM4} Low-power mode 4 ⁽⁸⁾ (4)	3.0 V	2	1.26		1.69	2.2	3.6		6.8	14.5	μA

- All inputs are tied to 0 V or to V_{CC} . Outputs do not source or sink any current.
- The currents are characterized with a Micro Crystal MS1V-T1K crystal with a load capacitance of 12.5 pF. The internal and external load capacitance are chosen to closely match the required 12.5 pF.
- Current for watchdog timer clocked by SMCLK included. ACLK = low frequency crystal operation (XTS = 0, XT1DRIVEx = 0). CPUOFF = 1, SCG0 = 0, SCG1 = 0, OSCOFF = 0 (LPM0); $f_{ACLK} = 32768$ Hz, $f_{MCLK} = 0$ MHz, $f_{SMCLK} = f_{DCO} = 1$ MHz
- Current for brownout included. High and low side supervisor and monitors disabled (SVSH, SVMH, SVSL, SVML). RAM retention enabled.
- Current for watchdog timer and RTC clocked by ACLK included. ACLK = low frequency crystal operation (XTS = 0, XT1DRIVEx = 0). CPUOFF = 1, SCG0 = 0, SCG1 = 1, OSCOFF = 0 (LPM2); $f_{ACLK} = 32768$ Hz, $f_{MCLK} = 0$ MHz, $f_{SMCLK} = f_{DCO} = 0$ MHz; DCO setting = 1 MHz operation, DCO bias generator enabled.
- Current for watchdog timer and RTC clocked by ACLK included. ACLK = low frequency crystal operation (XTS = 0, XT1DRIVEx = 0). CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 0 (LPM3); $f_{ACLK} = 32768$ Hz, $f_{MCLK} = f_{SMCLK} = f_{DCO} = 0$ MHz
- Current for watchdog timer and RTC clocked by ACLK included. For this condition, the VLO must be selected as the source for ACLK, MCLK, and SMCLK otherwise additional current will be drawn due to the REFO oscillator. ACLK = MCLK = SMCLK = VLO. CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 0 (LPM3); $f_{ACLK} = f_{VLO}$, $f_{MCLK} = f_{SMCLK} = f_{VLO} = 0$ MHz
- CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 1 (LPM4); $f_{DCO} = f_{ACLK} = f_{MCLK} = f_{SMCLK} = 0$ MHz

5.6 Thermal Packaging Characteristics

			VALUE	UNIT	
θ_{JA}	Junction-to-ambient thermal resistance, still air	Low-K board (JESD51-3)	LQFP (PZ)	50.1	°C/W
			LQFP (PN)	57.9	
		High-K board (JESD51-7)	LQFP (PZ)	40.8	
			LQFP (PN)	37.9	
θ_{JC}	Junction-to-case thermal resistance	LQFP (PZ)	8.9	°C/W	
		LQFP (PN)	10.3		

5.7 Schmitt-Trigger Inputs – General Purpose I/O⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage		1.8 V	0.80		1.40	V
			3 V	1.50		2.10	
V _{IT-}	Negative-going input threshold voltage		1.8 V	0.45		1.00	V
			3 V	0.75		1.65	
V _{hys}	Input voltage hysteresis (V _{IT+} – V _{IT-})		1.8 V	0.3		0.8	V
			3 V	0.4		1.0	
R _{Pull}	Pullup or pulldown resistor ⁽²⁾	For pullup: V _{IN} = V _{SS} For pulldown: V _{IN} = V _{CC}		20	35	50	kΩ
C _I	Input capacitance	V _{IN} = V _{SS} or V _{CC}			5		pF

(1) Same parametrics apply to clock input pin when crystal bypass mode is used on XT1 (XIN) or XT2 (XT2IN).

(2) Also applies to $\overline{\text{RST}}$ pin when pullup or pulldown resistor is enabled.

5.8 Inputs – Ports P1 and P2⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	MAX	UNIT
t _(int)	External interrupt timing ⁽²⁾	Port P1, P2: P1.x to P2.x, External trigger pulse width to set interrupt flag	2.2 V, 3 V	20		ns

(1) Some devices may contain additional ports with interrupts. See the block diagram and terminal function descriptions.

(2) An external signal sets the interrupt flag every time the minimum interrupt pulse width t_(int) is met. It may be set by trigger signals shorter than t_(int).

5.9 Leakage Current – General Purpose I/O

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	MAX	UNIT
I _{Ikg(Px.x)}	High-impedance leakage current	(1) (2)	1.8 V/3 V		±50	nA

(1) The leakage current is measured with V_{SS} or V_{CC} applied to the corresponding pin(s), unless otherwise noted.

(2) The leakage of the digital port pins is measured individually. The port pin is selected for input and the pullup or pulldown resistor is disabled.

5.10 Outputs – General Purpose I/O (Full Drive Strength)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	MAX	UNIT
V _{OH}	High-level output voltage	I _(OHmax) = -3 mA ⁽¹⁾	1.8 V	V _{CC} - 0.25	V _{CC}	V
		I _(OHmax) = -10 mA ⁽²⁾		V _{CC} - 0.60	V _{CC}	
		I _(OHmax) = -5 mA ⁽¹⁾	3 V	V _{CC} - 0.25	V _{CC}	
		I _(OHmax) = -15 mA ⁽²⁾		V _{CC} - 0.60	V _{CC}	
V _{OL}	Low-level output voltage	I _(OLmax) = 3 mA ⁽¹⁾	1.8 V	V _{SS}	V _{SS} + 0.25	V
		I _(OLmax) = 10 mA ⁽²⁾		V _{SS}	V _{SS} + 0.60	
		I _(OLmax) = 5 mA ⁽¹⁾	3 V	V _{SS}	V _{SS} + 0.25	
		I _(OLmax) = 15 mA ⁽²⁾		V _{SS}	V _{SS} + 0.60	

- (1) The maximum total current, I_(OHmax) and I_(OLmax), for all outputs combined should not exceed ±48 mA to hold the maximum voltage drop specified.
- (2) The maximum total current, I_(OHmax) and I_(OLmax), for all outputs combined should not exceed ±100 mA to hold the maximum voltage drop specified.

5.11 Outputs – General Purpose I/O (Reduced Drive Strength)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	MAX	UNIT
V _{OH}	High-level output voltage	I _(OHmax) = -1 mA ⁽²⁾	1.8 V	V _{CC} - 0.25	V _{CC}	V
		I _(OHmax) = -3 mA ⁽³⁾		V _{CC} - 0.60	V _{CC}	
		I _(OHmax) = -2 mA ⁽²⁾	3.0 V	V _{CC} - 0.25	V _{CC}	
		I _(OHmax) = -6 mA ⁽³⁾		V _{CC} - 0.60	V _{CC}	
V _{OL}	Low-level output voltage	I _(OLmax) = 1 mA ⁽²⁾	1.8 V	V _{SS}	V _{SS} + 0.25	V
		I _(OLmax) = 3 mA ⁽³⁾		V _{SS}	V _{SS} + 0.60	
		I _(OLmax) = 2 mA ⁽²⁾	3.0 V	V _{SS}	V _{SS} + 0.25	
		I _(OLmax) = 6 mA ⁽³⁾		V _{SS}	V _{SS} + 0.60	

- (1) Selecting reduced drive strength may reduce EMI.
- (2) The maximum total current, I_(OHmax) and I_(OLmax), for all outputs combined, should not exceed ±48 mA to hold the maximum voltage drop specified.
- (3) The maximum total current, I_(OHmax) and I_(OLmax), for all outputs combined, should not exceed ±100 mA to hold the maximum voltage drop specified.

5.12 Output Frequency – General Purpose I/O

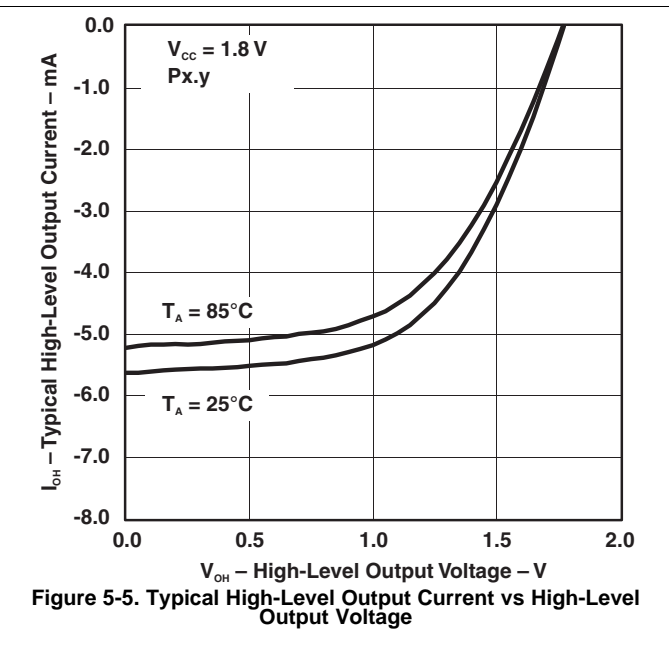
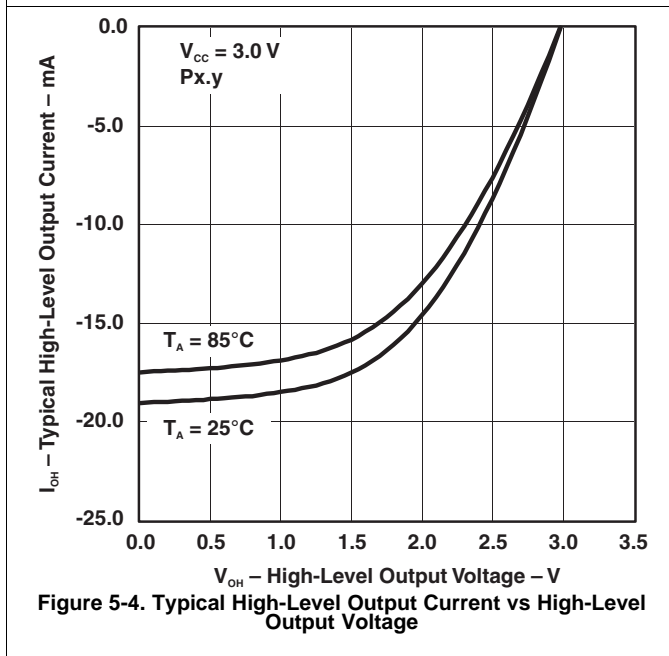
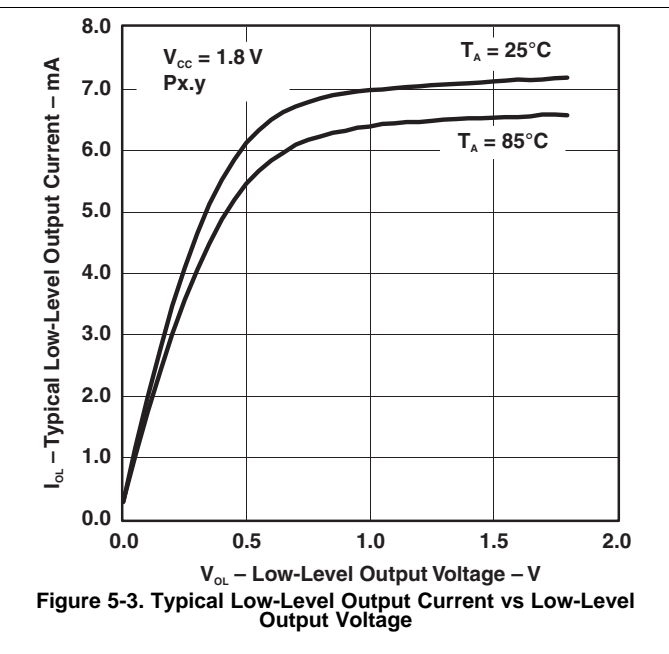
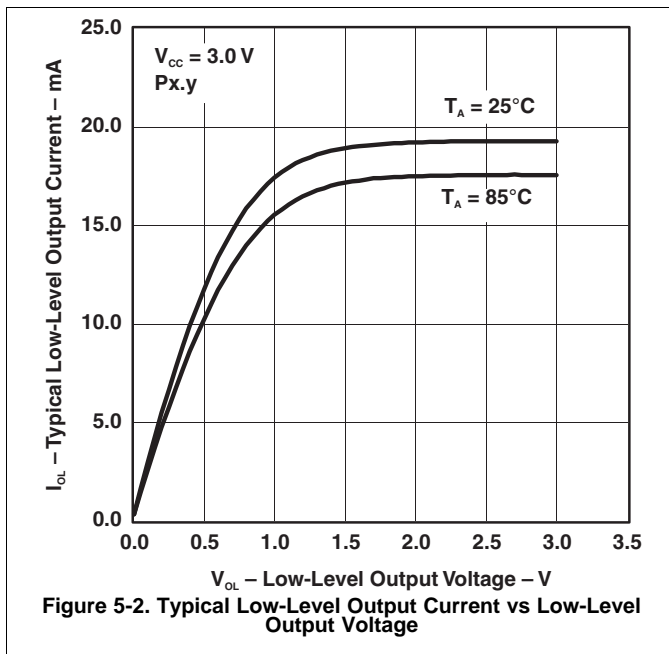
over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
f _{Px,y}	Port output frequency (with load)	P1.6/SMCLK (1) (2)	V _{CC} = 3 V PMMCOREVx = 2	25	MHz
f _{Port_CLK}	Clock output frequency	P1.0/TA0CLK/ACLK P1.6/SMCLK P2.0/TA1CLK/MCLK C _L = 20 pF ⁽²⁾	V _{CC} = 3 V PMMCOREVx = 2	25	MHz

- (1) A resistive divider with 2 × R1 between V_{CC} and V_{SS} is used as load. The output is connected to the center tap of the divider. For full drive strength, R1 = 550 Ω. For reduced drive strength, R1 = 1.6 kΩ. C_L = 20 pF is connected to the output to V_{SS}.
- (2) The output voltage reaches at least 10% and 90% V_{CC} at the specified toggle frequency.

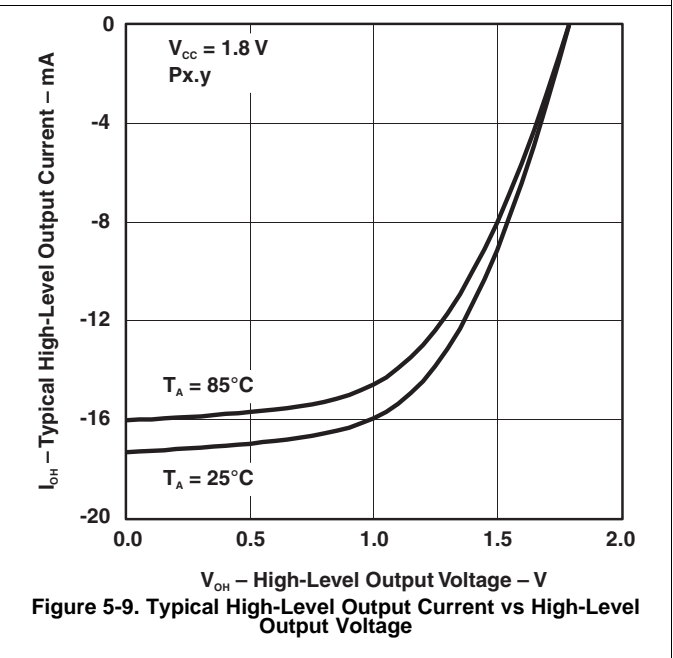
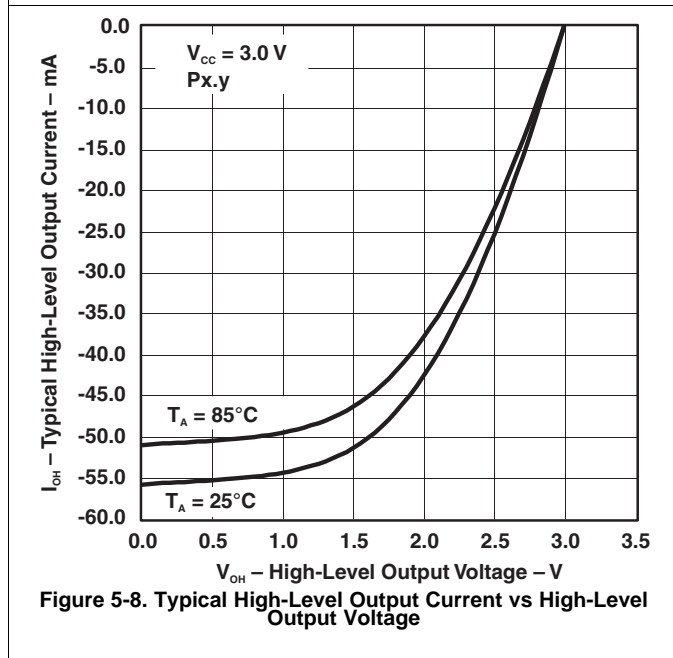
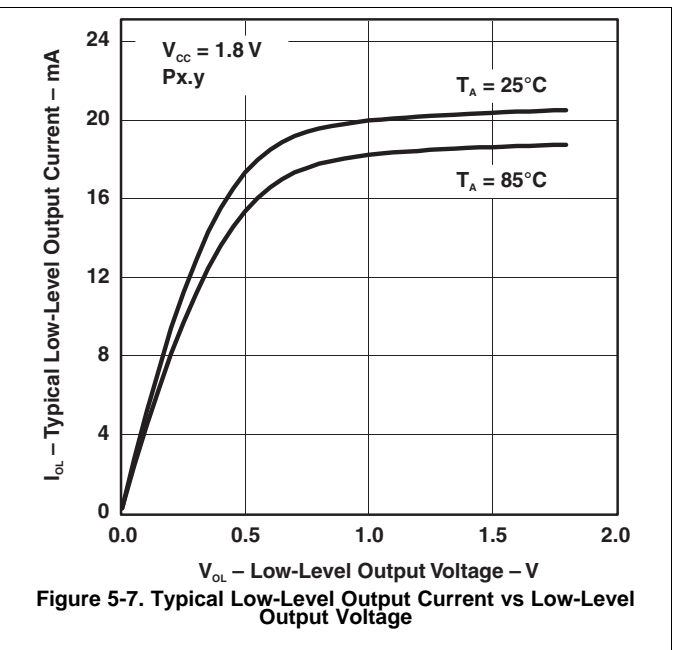
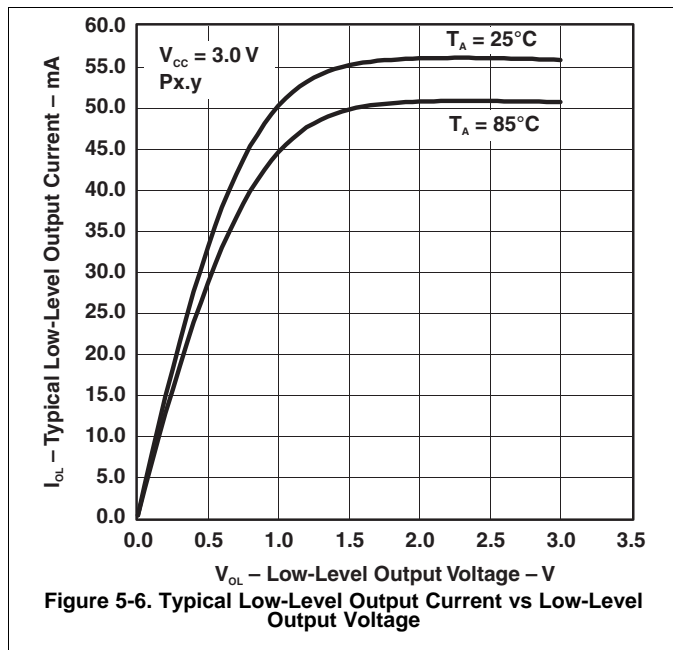
5.13 Typical Characteristics – Outputs, Reduced Drive Strength (PxDS.y = 0)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)



5.14 Typical Characteristics – Outputs, Full Drive Strength (PxDS.y = 1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)



5.15 Crystal Oscillator, XT1, Low-Frequency Mode⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT	
$\Delta I_{DVCC,LF}$	Differential XT1 oscillator crystal current consumption from lowest drive setting, LF mode	3.0 V		0.075		μA	
	$f_{OSC} = 32768$ Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 1, T _A = 25°C						
	$f_{OSC} = 32768$ Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 2, T _A = 25°C						
	$f_{OSC} = 32768$ Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 3, T _A = 25°C			0.290			
$f_{XT1,LF0}$	XT1 oscillator crystal frequency, LF mode			32768		Hz	
$f_{XT1,LF,SW}$	XT1 oscillator logic-level square-wave input frequency, LF mode		10	32.768	50	kHz	
OA_{LF}	Oscillation allowance for LF crystals ⁽⁴⁾			210		k Ω	
							XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 0, $f_{XT1,LF} = 32768$ Hz, C _{L,eff} = 6 pF
	XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 1, $f_{XT1,LF} = 32768$ Hz, C _{L,eff} = 12 pF			300			
$C_{L,eff}$	Integrated effective load capacitance, LF mode ⁽⁵⁾					pF	
							XTS = 0, XCAP _x = 0 ⁽⁶⁾
							XTS = 0, XCAP _x = 1
							XTS = 0, XCAP _x = 2
	XTS = 0, XCAP _x = 3			12.0			
	Duty cycle, LF mode		30%		70%		
$f_{Fault,LF}$	Oscillator fault frequency, LF mode ⁽⁷⁾		10		10000	Hz	
$t_{START,LF}$	Startup time, LF mode	3.0 V		1000		ms	
							$f_{OSC} = 32768$ Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 0, T _A = 25°C, C _{L,eff} = 6 pF
	$f_{OSC} = 32768$ Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 3, T _A = 25°C, C _{L,eff} = 12 pF			500			

- (1) To improve EMI on the XT1 oscillator, the following guidelines should be observed.
 - Keep the trace between the device and the crystal as short as possible.
 - Design a good ground plane around the oscillator pins.
 - Prevent crosstalk from other clock or data lines into oscillator pins XIN and XOUT.
 - Avoid running PCB traces underneath or adjacent to the XIN and XOUT pins.
 - Use assembly materials and techniques to avoid any parasitic load on the oscillator XIN and XOUT pins.
 - If conformal coating is used, make sure that it does not induce capacitive or resistive leakage between the oscillator pins.
- (2) When XT1BYPASS is set, XT1 circuits are automatically powered down. Input signal is a digital square wave with parametrics defined in the [Schmitt-Trigger Inputs](#) section of this data sheet.
- (3) Maximum frequency of operation of the entire device cannot be exceeded.
- (4) Oscillation allowance is based on a safety factor of 5 for recommended crystals. The oscillation allowance is a function of the XT1DRIVE_x settings and the effective load. In general, comparable oscillator allowance can be achieved based on the following guidelines, but should be evaluated based on the actual crystal selected for the application:
 - For XT1DRIVE_x = 0, C_{L,eff} ≤ 6 pF.
 - For XT1DRIVE_x = 1, 6 pF ≤ C_{L,eff} ≤ 9 pF.
 - For XT1DRIVE_x = 2, 6 pF ≤ C_{L,eff} ≤ 10 pF.
 - For XT1DRIVE_x = 3, C_{L,eff} ≥ 6 pF.
- (5) Includes parasitic bond and package capacitance (approximately 2 pF per pin). Because the PCB adds additional capacitance, it is recommended to verify the correct load by measuring the ACLK frequency. For a correct setup, the effective load capacitance should always match the specification of the used crystal.
- (6) Requires external capacitors at both terminals. Values are specified by crystal manufacturers.
- (7) Frequencies below the MIN specification set the fault flag. Frequencies above the MAX specification do not set the fault flag. Frequencies that are between MIN and MAX might set the flag.
- (8) Measured with logic-level input frequency but also applies to operation with crystals.

5.16 Crystal Oscillator, XT1, High-Frequency Mode⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
I _{DVCC, HF}	XT1 oscillator crystal current HF mode	f _{OSC} = 4 MHz, XTS = 1, XOSCOFF = 0, XT1BYPASS = 0, XT1DRIVE _x = 0, T _A = 25°C	3.0 V		200		μA
		f _{OSC} = 12 MHz, XTS = 1, XOSCOFF = 0, XT1BYPASS = 0, XT1DRIVE _x = 1, T _A = 25°C			260		
		f _{OSC} = 20 MHz, XTS = 1, XOSCOFF = 0, XT1BYPASS = 0, XT1DRIVE _x = 2, T _A = 25°C			325		
		f _{OSC} = 32 MHz, XTS = 1, XOSCOFF = 0, XT1BYPASS = 0, XT1DRIVE _x = 3, T _A = 25°C			450		
f _{XT1, HF0}	XT1 oscillator crystal frequency, HF mode 0	XTS = 1, XT1BYPASS = 0, XT1DRIVE _x = 0 ⁽²⁾		4		8	MHz
f _{XT1, HF1}	XT1 oscillator crystal frequency, HF mode 1	XTS = 1, XT1BYPASS = 0, XT1DRIVE _x = 1 ⁽²⁾		8		16	MHz
f _{XT1, HF2}	XT1 oscillator crystal frequency, HF mode 2	XTS = 1, XT1BYPASS = 0, XT1DRIVE _x = 2 ⁽²⁾		16		24	MHz
f _{XT1, HF3}	XT1 oscillator crystal frequency, HF mode 3	XTS = 1, XT1BYPASS = 0, XT1DRIVE _x = 3 ⁽²⁾		24		32	MHz
f _{XT1, HF, SW}	XT1 oscillator logic-level square-wave input frequency, HF mode, bypass mode	XTS = 1, XT1BYPASS = 1 ⁽³⁾ ⁽²⁾		1.5		32	MHz
O _{AHF}	Oscillation allowance for HF crystals ⁽⁴⁾	XTS = 1, XT1BYPASS = 0, XT1DRIVE _x = 0, f _{XT1, HF} = 6 MHz, C _{L, eff} = 15 pF			450		Ω
		XTS = 1, XT1BYPASS = 0, XT1DRIVE _x = 1, f _{XT1, HF} = 12 MHz, C _{L, eff} = 15 pF			320		
		XTS = 1, XT1BYPASS = 0, XT1DRIVE _x = 2, f _{XT1, HF} = 20 MHz, C _{L, eff} = 15 pF			200		
		XTS = 1, XT1BYPASS = 0, XT1DRIVE _x = 3, f _{XT1, HF} = 32 MHz, C _{L, eff} = 15 pF			200		
t _{START, HF}	Startup time, HF mode	f _{OSC} = 6 MHz, XTS = 1, XT1BYPASS = 0, XT1DRIVE _x = 0, T _A = 25°C, C _{L, eff} = 15 pF	3.0 V		0.5		ms
		f _{OSC} = 20 MHz, XTS = 1, XT1BYPASS = 0, XT1DRIVE _x = 2, T _A = 25°C, C _{L, eff} = 15 pF				0.3	

- (1) To improve EMI on the XT1 oscillator the following guidelines should be observed.
 - Keep the traces between the device and the crystal as short as possible.
 - Design a good ground plane around the oscillator pins.
 - Prevent crosstalk from other clock or data lines into oscillator pins XIN and XOUT.
 - Avoid running PCB traces underneath or adjacent to the XIN and XOUT pins.
 - Use assembly materials and techniques to avoid any parasitic load on the oscillator XIN and XOUT pins.
 - If conformal coating is used, make sure that it does not induce capacitive or resistive leakage between the oscillator pins.
- (2) This represents the maximum frequency that can be input to the device externally. Maximum frequency achievable on the device operation is based on the frequencies present on ACLK, MCLK, and SMCLK cannot be exceed for a given range of operation.
- (3) When XT1BYPASS is set, XT1 circuits are automatically powered down. Input signal is a digital square wave with parametrics defined in the [Schmitt-Trigger Inputs](#) section of this data sheet.
- (4) Oscillation allowance is based on a safety factor of 5 for recommended crystals.

Crystal Oscillator, XT1, High-Frequency Mode⁽¹⁾ (continued)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
C _{L,eff}	Integrated effective load capacitance, HF mode ⁽⁵⁾ ⁽⁶⁾	XTS = 1			1		pF
	Duty cycle, HF mode	XTS = 1, Measured at ACLK, f _{XT1,HF2} = 20 MHz		40%	50%	60%	
f _{Fault,HF}	Oscillator fault frequency, HF mode ⁽⁷⁾	XTS = 1 ⁽⁸⁾		30		300	kHz

- (5) Includes parasitic bond and package capacitance (approximately 2 pF per pin). Because the PCB adds additional capacitance, it is recommended to verify the correct load by measuring the ACLK frequency. For a correct setup, the effective load capacitance should always match the specification of the used crystal.
- (6) Requires external capacitors at both terminals. Values are specified by crystal manufacturers.
- (7) Frequencies below the MIN specification set the fault flag. Frequencies above the MAX specification do not set the fault flag. Frequencies that are between MIN and MAX might set the flag.
- (8) Measured with logic-level input frequency but also applies to operation with crystals.

5.17 Crystal Oscillator, XT2

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾ ⁽²⁾

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
I _{DVCC,XT2}	XT2 oscillator crystal current consumption	f _{OSC} = 4 MHz, XT2OFF = 0, XT2BYPASS = 0, XT2DRIVE _x = 0, T _A = 25°C	3.0 V		200		μA
		f _{OSC} = 12 MHz, XT2OFF = 0, XT2BYPASS = 0, XT2DRIVE _x = 1, T _A = 25°C			260		
		f _{OSC} = 20 MHz, XT2OFF = 0, XT2BYPASS = 0, XT2DRIVE _x = 2, T _A = 25°C			325		
		f _{OSC} = 32 MHz, XT2OFF = 0, XT2BYPASS = 0, XT2DRIVE _x = 3, T _A = 25°C			450		
f _{XT2,HF0}	XT2 oscillator crystal frequency, mode 0	XT2DRIVE _x = 0, XT2BYPASS = 0 ⁽³⁾		4		8	MHz
f _{XT2,HF1}	XT2 oscillator crystal frequency, mode 1	XT2DRIVE _x = 1, XT2BYPASS = 0 ⁽³⁾		8		16	MHz
f _{XT2,HF2}	XT2 oscillator crystal frequency, mode 2	XT2DRIVE _x = 2, XT2BYPASS = 0 ⁽³⁾		16		24	MHz
f _{XT2,HF3}	XT2 oscillator crystal frequency, mode 3	XT2DRIVE _x = 3, XT2BYPASS = 0 ⁽³⁾		24		32	MHz
f _{XT2,HF,SW}	XT2 oscillator logic-level square-wave input frequency, bypass mode	XT2BYPASS = 1 ⁽⁴⁾ ⁽³⁾		1.5		32	MHz

- (1) Requires external capacitors at both terminals. Values are specified by crystal manufacturers.
- (2) To improve EMI on the XT2 oscillator the following guidelines should be observed.
- Keep the traces between the device and the crystal as short as possible.
 - Design a good ground plane around the oscillator pins.
 - Prevent crosstalk from other clock or data lines into oscillator pins XT2IN and XT2OUT.
 - Avoid running PCB traces underneath or adjacent to the XT2IN and XT2OUT pins.
 - Use assembly materials and techniques to avoid any parasitic load on the oscillator XT2IN and XT2OUT pins.
 - If conformal coating is used, make sure that it does not induce capacitive or resistive leakage between the oscillator pins.
- (3) This represents the maximum frequency that can be input to the device externally. Maximum frequency achievable on the device operation is based on the frequencies present on ACLK, MCLK, and SMCLK cannot be exceeded for a given range of operation.
- (4) When XT2BYPASS is set, the XT2 circuit is automatically powered down. Input signal is a digital square wave with parametrics defined in the [Schmitt-Trigger Inputs](#) section of this datasheet.

Crystal Oscillator, XT2 (continued)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)^{(1) (2)}

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
O _{AHF} Oscillation allowance for HF crystals ⁽⁵⁾	XT2DRIVE _x = 0, XT2BYPASS = 0, f _{XT2,HF0} = 6 MHz, C _{L,eff} = 15 pF	3.0 V		450		Ω
	XT2DRIVE _x = 1, XT2BYPASS = 0, f _{XT2,HF1} = 12 MHz, C _{L,eff} = 15 pF			320		
	XT2DRIVE _x = 2, XT2BYPASS = 0, f _{XT2,HF2} = 20 MHz, C _{L,eff} = 15 pF			200		
	XT2DRIVE _x = 3, XT2BYPASS = 0, f _{XT2,HF3} = 32 MHz, C _{L,eff} = 15 pF			200		
t _{START,HF} Startup time	f _{OSC} = 6 MHz XT2BYPASS = 0, XT2DRIVE _x = 0, T _A = 25°C, C _{L,eff} = 15 pF	3.0 V		0.5		ms
	f _{OSC} = 20 MHz XT2BYPASS = 0, XT2DRIVE _x = 2, T _A = 25°C, C _{L,eff} = 15 pF			0.3		
C _{L,eff} Integrated effective load capacitance, HF mode ^{(6) (1)}				1		pF
Duty cycle	Measured at ACLK, f _{XT2,HF2} = 20 MHz		40%	50%	60%	
f _{Fault,HF} Oscillator fault frequency ⁽⁷⁾	XT2BYPASS = 1 ⁽⁸⁾		30		300	kHz

(5) Oscillation allowance is based on a safety factor of 5 for recommended crystals.

(6) Includes parasitic bond and package capacitance (approximately 2 pF per pin).

Because the PCB adds additional capacitance, it is recommended to verify the correct load by measuring the ACLK frequency. For a correct setup, the effective load capacitance should always match the specification of the used crystal.

(7) Frequencies below the MIN specification set the fault flag. Frequencies above the MAX specification do not set the fault flag. Frequencies that are between MIN and MAX might set the flag.

(8) Measured with logic-level input frequency but also applies to operation with crystals.

5.18 Internal Very-Low-Power Low-Frequency Oscillator (VLO)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{VLO} VLO frequency	Measured at ACLK	1.8 V to 3.6 V	6	9.4	14	kHz
df _{VLO} /dT VLO frequency temperature drift	Measured at ACLK ⁽¹⁾	1.8 V to 3.6 V		0.5		%/°C
df _{VLO} /dV _{CC} VLO frequency supply voltage drift	Measured at ACLK ⁽²⁾	1.8 V to 3.6 V		4		%/V
Duty cycle	Measured at ACLK	1.8 V to 3.6 V	40%	50%	60%	

(1) Calculated using the box method: (MAX(-40 to 85°C) – MIN(-40 to 85°C)) / MIN(-40 to 85°C) / (85°C – (-40°C))

(2) Calculated using the box method: (MAX(1.8 to 3.6 V) – MIN(1.8 to 3.6 V)) / MIN(1.8 to 3.6 V) / (3.6 V – 1.8 V)

5.19 Internal Reference, Low-Frequency Oscillator (REFO)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
I _{REFO} REFO oscillator current consumption	T _A = 25°C	1.8 V to 3.6 V		3		μA
f _{REFO} REFO frequency calibrated	Measured at ACLK	1.8 V to 3.6 V		32768		Hz
	REFO absolute tolerance calibrated	Full temperature range	1.8 V to 3.6 V		±3.5%	
	T _A = 25°C	3 V			±1.5%	
df _{REFO} /dT REFO frequency temperature drift	Measured at ACLK ⁽¹⁾	1.8 V to 3.6 V		0.01		%/°C
df _{REFO} /dV _{CC} REFO frequency supply voltage drift	Measured at ACLK ⁽²⁾	1.8 V to 3.6 V		1.0		%/V
Duty cycle	Measured at ACLK	1.8 V to 3.6 V	40%	50%	60%	
t _{START} REFO startup time	40%/60% duty cycle	1.8 V to 3.6 V		25		μs

(1) Calculated using the box method: (MAX(-40 to 85°C) – MIN(-40 to 85°C)) / MIN(-40 to 85°C) / (85°C – (-40°C))

(2) Calculated using the box method: (MAX(1.8 to 3.6 V) – MIN(1.8 to 3.6 V)) / MIN(1.8 to 3.6 V) / (3.6 V – 1.8 V)

5.20 DCO Frequency

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_{DCO(0,0)}$	DCO frequency (0, 0) ⁽¹⁾	DCORSELx = 0, DCOx = 0, MODx = 0	0.07	0.20	MHz
$f_{DCO(0,31)}$	DCO frequency (0, 31) ⁽¹⁾	DCORSELx = 0, DCOx = 31, MODx = 0	0.70	1.70	MHz
$f_{DCO(1,0)}$	DCO frequency (1, 0) ⁽¹⁾	DCORSELx = 1, DCOx = 0, MODx = 0	0.15	0.36	MHz
$f_{DCO(1,31)}$	DCO frequency (1, 31) ⁽¹⁾	DCORSELx = 1, DCOx = 31, MODx = 0	1.47	3.45	MHz
$f_{DCO(2,0)}$	DCO frequency (2, 0) ⁽¹⁾	DCORSELx = 2, DCOx = 0, MODx = 0	0.32	0.75	MHz
$f_{DCO(2,31)}$	DCO frequency (2, 31) ⁽¹⁾	DCORSELx = 2, DCOx = 31, MODx = 0	3.17	7.38	MHz
$f_{DCO(3,0)}$	DCO frequency (3, 0) ⁽¹⁾	DCORSELx = 3, DCOx = 0, MODx = 0	0.64	1.51	MHz
$f_{DCO(3,31)}$	DCO frequency (3, 31) ⁽¹⁾	DCORSELx = 3, DCOx = 31, MODx = 0	6.07	14.0	MHz
$f_{DCO(4,0)}$	DCO frequency (4, 0) ⁽¹⁾	DCORSELx = 4, DCOx = 0, MODx = 0	1.3	3.2	MHz
$f_{DCO(4,31)}$	DCO frequency (4, 31) ⁽¹⁾	DCORSELx = 4, DCOx = 31, MODx = 0	12.3	28.2	MHz
$f_{DCO(5,0)}$	DCO frequency (5, 0) ⁽¹⁾	DCORSELx = 5, DCOx = 0, MODx = 0	2.5	6.0	MHz
$f_{DCO(5,31)}$	DCO frequency (5, 31) ⁽¹⁾	DCORSELx = 5, DCOx = 31, MODx = 0	23.7	54.1	MHz
$f_{DCO(6,0)}$	DCO frequency (6, 0) ⁽¹⁾	DCORSELx = 6, DCOx = 0, MODx = 0	4.6	10.7	MHz
$f_{DCO(6,31)}$	DCO frequency (6, 31) ⁽¹⁾	DCORSELx = 6, DCOx = 31, MODx = 0	39.0	88.0	MHz
$f_{DCO(7,0)}$	DCO frequency (7, 0) ⁽¹⁾	DCORSELx = 7, DCOx = 0, MODx = 0	8.5	19.6	MHz
$f_{DCO(7,31)}$	DCO frequency (7, 31) ⁽¹⁾	DCORSELx = 7, DCOx = 31, MODx = 0	60	135	MHz
$S_{DCORSEL}$	Frequency step between range DCORSEL and DCORSEL + 1	$S_{RSEL} = f_{DCO(DCORSEL+1,DCO)} / f_{DCO(DCORSEL,DCO)}$	1.2	2.3	ratio
S_{DCO}	Frequency step between tap DCO and DCO + 1	$S_{DCO} = f_{DCO(DCORSEL,DCO+1)} / f_{DCO(DCORSEL,DCO)}$	1.02	1.12	ratio
	Duty cycle	Measured at SMCLK	40%	50%	60%
df_{DCO}/dT	DCO frequency temperature drift ⁽²⁾	$f_{DCO} = 1$ MHz		0.1	%/°C
df_{DCO}/dV_{CC}	DCO frequency voltage drift ⁽³⁾	$f_{DCO} = 1$ MHz		1.9	%/V

- (1) When selecting the proper DCO frequency range (DCORSELx), the target DCO frequency, f_{DCO} , should be set to reside within the range of $f_{DCO(n,0),MAX} \leq f_{DCO} \leq f_{DCO(n,31),MIN}$, where $f_{DCO(n,0),MAX}$ represents the maximum frequency specified for the DCO frequency, range n, tap 0 (DCOx = 0) and $f_{DCO(n,31),MIN}$ represents the minimum frequency specified for the DCO frequency, range n, tap 31 (DCOx = 31). This makes sure that the target DCO frequency resides within the range selected. It should also be noted that if the actual f_{DCO} frequency for the selected range causes the FLL or the application to select tap 0 or 31, the DCO fault flag is set to report that the selected range is at its minimum or maximum tap setting.
- (2) Calculated using the box method: $(MAX(-40 \text{ to } 85^\circ\text{C}) - MIN(-40 \text{ to } 85^\circ\text{C})) / MIN(-40 \text{ to } 85^\circ\text{C}) / (85^\circ\text{C} - (-40^\circ\text{C}))$
- (3) Calculated using the box method: $(MAX(2.2 \text{ to } 3.6 \text{ V}) - MIN(2.2 \text{ to } 3.6 \text{ V})) / MIN(2.2 \text{ to } 3.6 \text{ V}) / (3.6 \text{ V} - 2.2 \text{ V})$

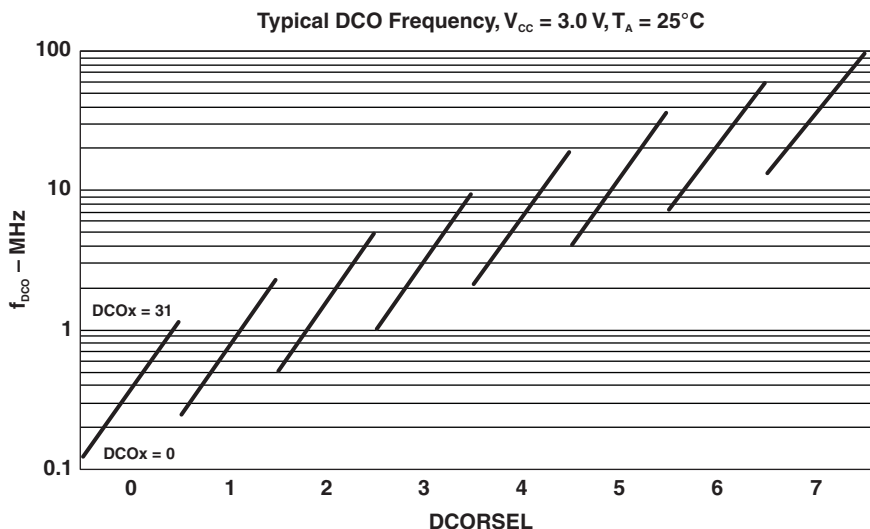


Figure 5-10. Typical DCO frequency

5.21 PMM, Brown-Out Reset (BOR)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{(DVCC_BOR_IT-)}$	BOR _H on voltage, DV _{CC} falling level	$ dDV_{CC}/dt < 3 \text{ V/s}$			1.55	V
$V_{(DVCC_BOR_IT+)}$	BOR _H off voltage, DV _{CC} rising level	$ dDV_{CC}/dt < 3 \text{ V/s}$	0.80	1.30	1.65	V
$V_{(DVCC_BOR_hys)}$	BOR _H hysteresis		100		250	mV
$V_{(VCORE_BOR_IT-)}$	BOR _L on voltage, V _{CORE} falling level	DV _{CC} = 1.8 V to 3.6 V	0.69		0.83	V
$V_{(VCORE_BOR_IT+)}$	BOR _L off voltage, V _{CORE} rising level	DV _{CC} = 1.8 V to 3.6 V	0.83		1.05	V
$V_{(VCORE_BOR_hys)}$	BOR _L hysteresis		70		200	mV
t_{RESET}	Pulse duration required at $\overline{\text{RST}}/\text{NMI}$ pin to accept a reset		2			μs

5.22 PMM, Core Voltage

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{\text{CORE2(AM)}}$	Core voltage, active mode, PMMCOREV = 2	$2.2 \text{ V} \leq DV_{CC} \leq 3.6 \text{ V}, 0 \text{ mA} \leq I(V_{\text{CORE}}) \leq 21 \text{ mA}$	1.60	1.81	1.89	V
$V_{\text{CORE2(LPM)}}$	Core voltage, low-current mode, PMMCOREV = 2	$2.2 \text{ V} \leq DV_{CC} \leq 3.6 \text{ V}, 0 \mu\text{A} \leq I(V_{\text{CORE}}) \leq 30 \mu\text{A}$	1.68	1.89	1.98	V
PSRR(DC,AM)	Power-supply rejection ratio, active mode	DV _{CC} = 2.2 V/3.6 V, I(V _{CORE}) = 0 mA, PMMCOREV = 2		60		dB
		DV _{CC} = 2.2 V/3.6 V, I(V _{CORE}) = 21 mA, PMMCOREV = 2		60		
PSRR(DC,LPM)	Power-supply rejection ratio, low-current mode	DV _{CC} = 2.2 V/3.6 V, I(V _{CORE}) = 0 mA, PMMCOREV = 2		50		dB
		DV _{CC} = 2.4 V/3.6 V, I(V _{CORE}) = 30 μA, PMMCOREV = 2		50		

5.23 PMM, SVS High Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(SVSH)}$	SVS current consumption	SVSHE = 0, DV _{CC} = 3.6 V		0		nA
		SVSHE = 1, DV _{CC} = 3.6 V, SVSHFP = 0		200		nA
		SVSHE = 1, DV _{CC} = 3.6 V, SVSHFP = 1		2.0		μA
$V_{(SVSH_IT-)}$	SVS _H on voltage level	SVSHE = 1, SVSHRVL = 0	1.59	1.64	1.69	V
		SVSHE = 1, SVSHRVL = 1	1.79	1.84	1.91	
		SVSHE = 1, SVSHRVL = 2	1.98	2.04	2.11	
		SVSHE = 1, SVSHRVL = 3	2.10	2.16	2.23	
$V_{(SVSH_IT+)}$	SVS _H off voltage level	SVSHE = 1, SVSMHRRRL = 0	1.62	1.74	1.81	V
		SVSHE = 1, SVSMHRRRL = 1	1.88	1.94	2.01	
		SVSHE = 1, SVSMHRRRL = 2	2.07	2.14	2.21	
		SVSHE = 1, SVSMHRRRL = 3	2.20	2.26	2.33	
		SVSHE = 1, SVSMHRRRL = 4		2.40		
		SVSHE = 1, SVSMHRRRL = 5		2.70		
		SVSHE = 1, SVSMHRRRL = 6		3.00		
		SVSHE = 1, SVSMHRRRL = 7		3.00		
$t_{pd(SVSH)}$	SVS _H propagation delay	SVSHE = 1, dV _{DVCC} /dt = 10 mV/μs, SVSHFP = 1		2.5		μs
		SVSHE = 1, dV _{DVCC} /dt = 1 mV/μs, SVSHFP = 0		20		
$t_{(SVSH)}$	SVS _H on or off delay time	SVSHE = 0 → 1, dV _{DVCC} /dt = 10 mV/μs, SVSHFP = 1		12.5		μs
		SVSHE = 0 → 1, dV _{DVCC} /dt = 1 mV/μs, SVSHFP = 0		100		
dV _{DVCC} /dt	DV _{CC} rise time		0		1000	V/s

5.24 PMM, SVM High Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(SVMH)}$	SVM _H current consumption	SVMHE = 0, DV _{CC} = 3.6 V		0		nA
		SVMHE = 1, DV _{CC} = 3.6 V, SVMHFP = 0		200		nA
		SVMHE = 1, DV _{CC} = 3.6 V, SVMHFP = 1		2.0		μA
$V_{(SVMH)}$	SVM _H on or off voltage level	SVMHE = 1, SVSMHRRRL = 0	1.65	1.74	1.86	V
		SVMHE = 1, SVSMHRRRL = 1	1.85	1.94	2.02	
		SVMHE = 1, SVSMHRRRL = 2	2.02	2.14	2.22	
		SVMHE = 1, SVSMHRRRL = 3	2.18	2.26	2.35	
		SVMHE = 1, SVSMHRRRL = 4		2.40		
		SVMHE = 1, SVSMHRRRL = 5		2.70		
		SVMHE = 1, SVSMHRRRL = 6		3.00		
		SVMHE = 1, SVSMHRRRL = 7		3.00		
		SVMHE = 1, SVMHOVPE = 1		3.75		
$t_{pd(SVMH)}$	SVM _H propagation delay	SVMHE = 1, dV _{DVCC} /dt = 10 mV/μs, SVMHFP = 1		2.5		μs
		SVMHE = 1, dV _{DVCC} /dt = 1 mV/μs, SVMHFP = 0		20		
$t_{(SVMH)}$	SVM _H on or off delay time	SVMHE = 0 → 1, dV _{DVCC} /dt = 10 mV/μs, SVMHFP = 1		12.5		μs
		SVMHE = 0 → 1, dV _{DVCC} /dt = 1 mV/μs, SVMHFP = 0		100		

5.25 PMM, SVS Low Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(SVSL)}$	SVS _L current consumption	SVSLE = 0, PMMCOREV = 2		0		nA
		SVSLE = 1, PMMCOREV = 2, SVSLFP = 0		200		nA
		SVSLE = 1, PMMCOREV = 2, SVSLFP = 1		2.0		μA
$V_{(SVSL_IT-)}$	SVS _L on voltage level	SVSLE = 1, SVSLRVL = 0	1.20	1.27	1.32	V
		SVSLE = 1, SVSLRVL = 1	1.39	1.47	1.52	
		SVSLE = 1, SVSLRVL = 2	1.60	1.67	1.72	
		SVSLE = 1, SVSLRVL = 3	1.70	1.77	1.82	
$V_{(SVSL_IT+)}$	SVS _L off voltage level	SVSLE = 1, SVSMLRRL = 0	1.29	1.34	1.39	V
		SVSLE = 1, SVSMLRRL = 1	1.49	1.54	1.59	
		SVSLE = 1, SVSMLRRL = 2	1.69	1.74	1.79	
		SVSLE = 1, SVSMLRRL = 3, 4, 5, 6, 7	1.79	1.84	1.89	
$V_{(SVSL_HYS)}$	SVS _L hysteresis	SVSLE = 1, SVSMLRRL = 0		70		mV
		SVSLE = 1, SVSMLRRL = 1		70		
		SVSLE = 1, SVSMLRRL = 2		70		
		SVSLE = 1, SVSMLRRL = 3		70		
$t_{pd(SVSL)}$	SVS _L propagation delay	SVSLE = 1, $dV_{CORE}/dt = 10 \text{ mV}/\mu\text{s}$, SVSLFP = 1		2.5		μs
		SVSLE = 1, $dV_{CORE}/dt = 1 \text{ mV}/\mu\text{s}$, SVSLFP = 0		20		
$t_{(SVSL)}$	SVS _L on or off delay time	SVSLE = 0 → 1, $dV_{CORE}/dt = 10 \text{ mV}/\mu\text{s}$, SVSLFP = 1		12.5		μs
		SVSLE = 0 → 1, $dV_{CORE}/dt = 1 \text{ mV}/\mu\text{s}$, SVSLFP = 0		100		

5.26 PMM, SVM Low Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(SVML)}$	SVM _L current consumption	SVMLE = 0, PMMCOREV = 2		0		nA
		SVMLE = 1, PMMCOREV = 2, SVMLFP = 0		200		nA
		SVMLE = 1, PMMCOREV = 2, SVMLFP = 1		2.0		μA
$V_{(SVML)}$	SVM _L on or off voltage level	SVMLE = 1, SVSMLRRL = 0	1.28	1.34	1.40	V
		SVMLE = 1, SVSMLRRL = 1	1.49	1.54	1.60	
		SVMLE = 1, SVSMLRRL = 2	1.68	1.74	1.79	
		SVMLE = 1, SVSMLRRL = 3, 4, 5, 6, 7	1.76	1.84	1.90	
		SVMLE = 1, SVSMLOVPE = 1		2.02		
$t_{pd(SVML)}$	SVM _L propagation delay	SVMLE = 1, $dV_{CORE}/dt = 10 \text{ mV}/\mu\text{s}$, SVMLFP = 1		2.5		μs
		SVMLE = 1, $dV_{CORE}/dt = 1 \text{ mV}/\mu\text{s}$, SVMLFP = 0		20		
$t_{(SVML)}$	SVM _L on or off delay time	SVMLE = 0 → 1, $dV_{CORE}/dt = 10 \text{ mV}/\mu\text{s}$, SVMLFP = 1		12.5		μs
		SVMLE = 0 → 1, $dV_{CORE}/dt = 1 \text{ mV}/\mu\text{s}$, SVMLFP = 0		100		

5.27 Wake-Up From Low Power Modes

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
t _{WAKE-UP-FAST}	Wake-up time from LPM2, LPM3, or LPM4 to active mode ⁽¹⁾	PMMCOREV = SVSMLRRL = 2, SVSLFP = 1	2.2 V, 3 V			5	μs
t _{WAKE-UP-SLOW}	Wake-up time from LPM2, LPM3, or LPM4 to active mode ⁽²⁾	PMMCOREV = SVSMLRRL = 2, SVSLFP = 0	2.2 V, 3 V		150		μs

- (1) This value represents the time from the wakeup event to the first active edge of MCLK. The wakeup time depends on the performance mode of the low side supervisor (SVS_L) and low side monitor (SVM_L). Fastest wakeup times are possible with SVS_L and SVM_L in full performance mode or disabled when operating in AM, LPM0, and LPM1. Various options are available for SVS_L and SVM_L while operating in LPM2, LPM3, and LPM4. See the *Power Management Module and Supply Voltage Supervisor* chapter in the *MSP430x5xx and MSP430x6xx Family User's Guide* (SLAU208).
- (2) This value represents the time from the wakeup event to the first active edge of MCLK. The wakeup time depends on the performance mode of the low side supervisor (SVS_L) and low side monitor (SVM_L). In this case, the SVS_L and SVM_L are in normal mode (low current) mode when operating in AM, LPM0, and LPM1. Various options are available for SVS_L and SVM_L while operating in LPM2, LPM3, and LPM4. See the *Power Management Module and Supply Voltage Supervisor* chapter in the *MSP430x5xx and MSP430x6xx Family User's Guide* (SLAU208).

5.28 Timer_A

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{TA}	Timer_A input clock frequency	Internal: SMCLK, ACLK External: TACLK Duty cycle = 50% ± 10%	1.8 V, 3 V			25	MHz
t _{TA,cap}	Timer_A capture timing	All capture inputs, Minimum pulse duration required for capture	1.8 V, 3 V	20			ns

5.29 Timer_B

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{TB}	Timer_B input clock frequency	Internal: SMCLK, ACLK External: TBCLK Duty cycle = 50% ± 10%	1.8 V, 3 V			25	MHz
t _{TB,cap}	Timer_B capture timing	All capture inputs, Minimum pulse duration required for capture	1.8 V, 3 V	20			ns

5.30 USCI (UART Mode) Recommended Operating Conditions

PARAMETER		CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{USCI}	USCI input clock frequency	Internal: SMCLK, ACLK External: UCLK Duty cycle = 50% ± 10%				f _{SYSTEM}	MHz
f _{BITCLK}	BITCLK clock frequency (equals baud rate in Mbaud)					1	MHz

5.31 USCI (UART Mode)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
t _r	UART receive deglitch time ⁽¹⁾		2.2 V	50		600	ns
			3 V	50		600	

(1) Pulses on the UART receive input (UCxRX) shorter than the UART receive deglitch time are suppressed. To make sure that pulses are correctly recognized, their duration should exceed the maximum specification of the deglitch time.

5.32 USCI (SPI Master Mode) Recommended Operating Conditions

PARAMETER		CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{USCI}	USCI input clock frequency	Internal: SMCLK, ACLK Duty cycle = 50% ± 10%				f _{SYSTEM}	MHz

5.33 USCI (SPI Master Mode)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

(see Note ⁽¹⁾, [Figure 5-11](#) and [Figure 5-12](#))

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{USCI}	USCI input clock frequency	SMCLK, ACLK Duty cycle = 50% ± 10%				f _{SYSTEM}	MHz
t _{SU,MI}	SOMI input data setup time		2.2 V	65			ns
			3 V	50			
t _{HD,MI}	SOMI input data hold time		2.2 V	0			ns
			3 V	0			
t _{VALID,MO}	SIMO output data valid time ⁽²⁾	UCLK edge to SIMO valid, C _L = 20 pF	2.2 V			25	ns
			3 V			20	
t _{HD,MO}	SIMO output data hold time ⁽³⁾	C _L = 20 pF	2.2 V				ns
			3 V				

- (1) $f_{UCxCLK} = 1/2t_{LO/HI}$ with $t_{LO/HI} \geq \max(t_{VALID,MO(USCI)} + t_{SU,SI(Slave)}, t_{SU,MI(USCI)} + t_{VALID,SO(Slave)})$.
For the slave's parameters $t_{SU,SI(Slave)}$ and $t_{VALID,SO(Slave)}$ refer to the SPI parameters of the attached slave.
- (2) Specifies the time to drive the next valid data to the SIMO output after the output changing UCLK clock edge. Refer to the timing diagrams in [Figure 5-11](#) and [Figure 5-12](#).
- (3) Specifies how long data on the SIMO output is valid after the output changing UCLK clock edge. Negative values indicate that the data on the SIMO output can become invalid before the output changing clock edge observed on UCLK. Refer to the timing diagrams in [Figure 5-11](#) and [Figure 5-12](#).

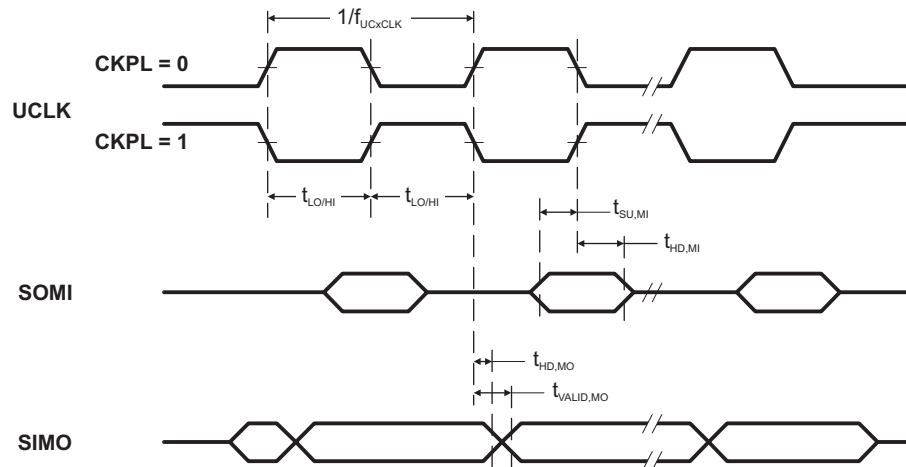


Figure 5-11. SPI Master Mode, CKPH = 0

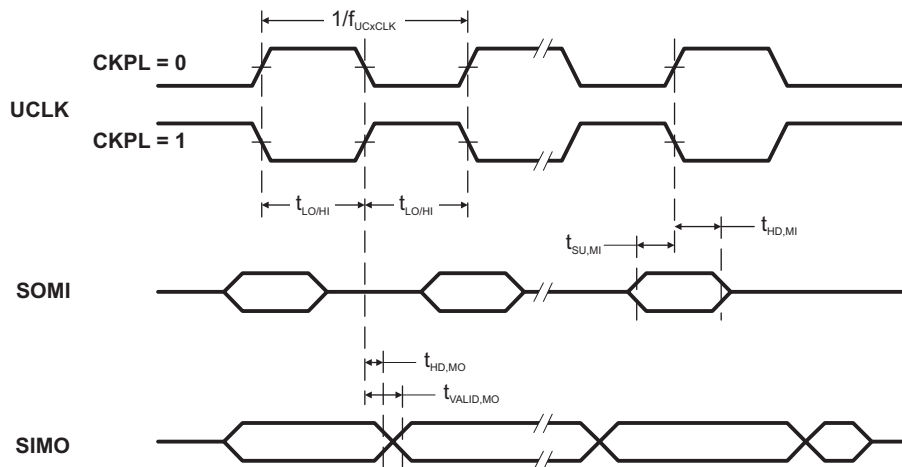


Figure 5-12. SPI Master Mode, CKPH = 1

5.34 USCI (SPI Slave Mode)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)
(see Note ⁽¹⁾, Figure 5-13 and Figure 5-14)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
t _{STE,LEAD}	STE lead time, STE low to clock	2.2 V, 3 V		40		ns
t _{STE,LAG}	STE lag time, Last clock to STE high	2.2 V, 3 V	10			ns
t _{STE,ACC}	STE access time, STE low to SOMI data out	2.2 V, 3 V		40		ns
t _{STE,DIS}	STE disable time, STE high to SOMI high impedance	2.2 V, 3 V		40		ns
t _{SU,SI}	SIMO input data setup time	2.2 V	20			ns
		3 V	15			
t _{HD,SI}	SIMO input data hold time	2.2 V	10			ns
		3 V	10			
t _{VALID,SO}	SOMI output data valid time ⁽²⁾	2.2 V			62	ns
		3 V			50	
t _{HD,SO}	SOMI output data hold time ⁽³⁾	2.2 V	0			ns
		3 V	0			

- (1) $f_{UCxCLK} = 1/2 \times t_{LO/HI}$ with $t_{LO/HI} \geq \max(t_{VALID,MO(Master)} + t_{SU,SI(USCI)}, t_{SU,MI(Master)} + t_{VALID,SO(USCI)})$.
For the master's parameters $t_{SU,MI(Master)}$ and $t_{VALID,MO(Master)}$, see the SPI parameters of the attached slave.
- (2) Specifies the time to drive the next valid data to the SOMI output after the output changing UCLK clock edge. Refer to the timing diagrams in Figure 5-11 and Figure 5-12.
- (3) Specifies how long data on the SOMI output is valid after the output changing UCLK clock edge. Refer to the timing diagrams in Figure 5-11 and Figure 5-12.

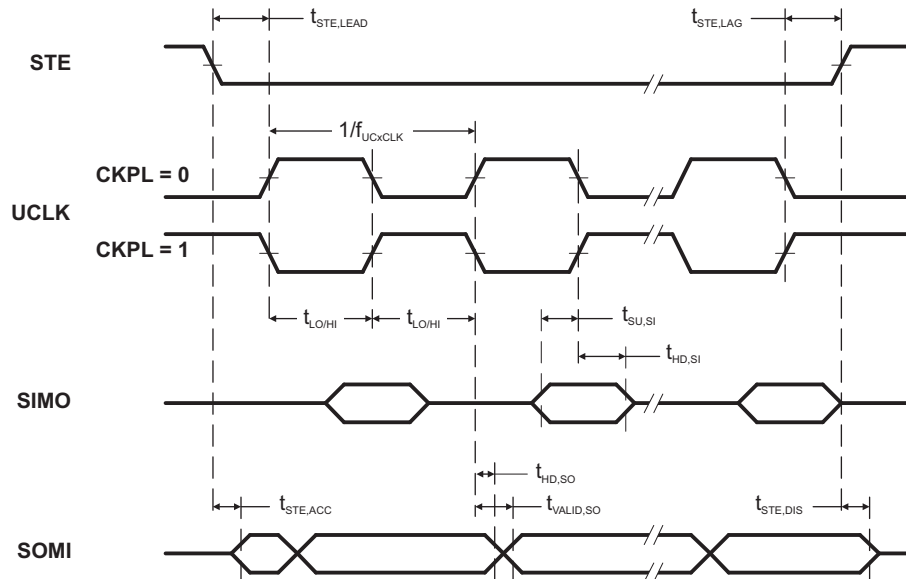


Figure 5-13. SPI Slave Mode, CKPH = 0

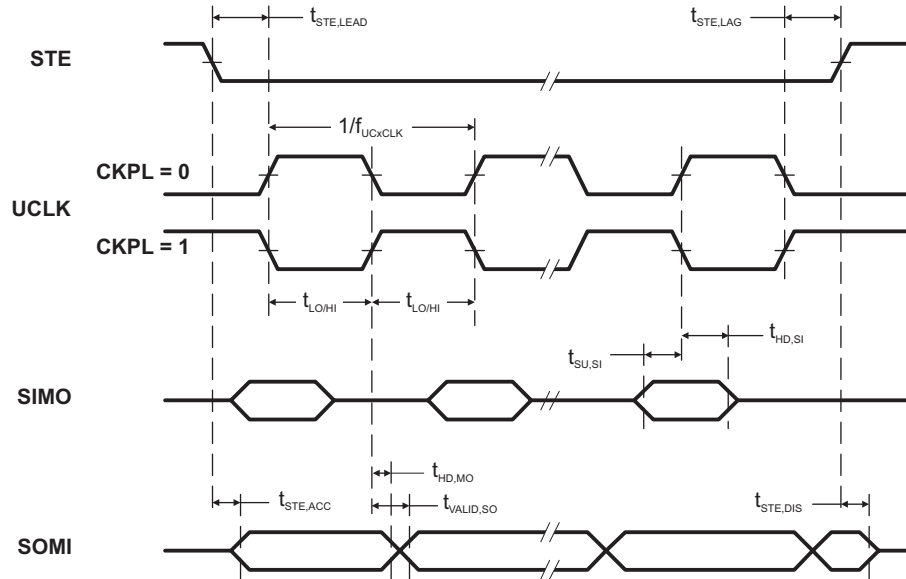


Figure 5-14. SPI Slave Mode, CKPH = 1

5.35 USCI (I2C Mode)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5-15)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{USCI}	USCI input clock frequency	Internal: SMCLK, ACLK External: UCLK Duty cycle = 50% ± 10%				f _{SYSTEM}	MHz
f _{SCL}	SCL clock frequency		2.2 V, 3 V	0		400	kHz
t _{HD,STA}	Hold time (repeated) START	f _{SCL} ≤ 100 kHz f _{SCL} > 100 kHz	2.2 V, 3 V	4.0 0.6			μs
t _{SU,STA}	Setup time for a repeated START	f _{SCL} ≤ 100 kHz f _{SCL} > 100 kHz	2.2 V, 3 V	4.7 0.6			μs
t _{HD,DAT}	Data hold time		2.2 V, 3 V	0			ns
t _{SU,DAT}	Data setup time		2.2 V, 3 V	250			ns
t _{SU,STO}	Setup time for STOP	f _{SCL} ≤ 100 kHz f _{SCL} > 100 kHz	2.2 V, 3 V	4.0 0.6			μs
t _{SP}	Pulse width of spikes suppressed by input filter		2.2 V 3 V	50 50		600 600	ns

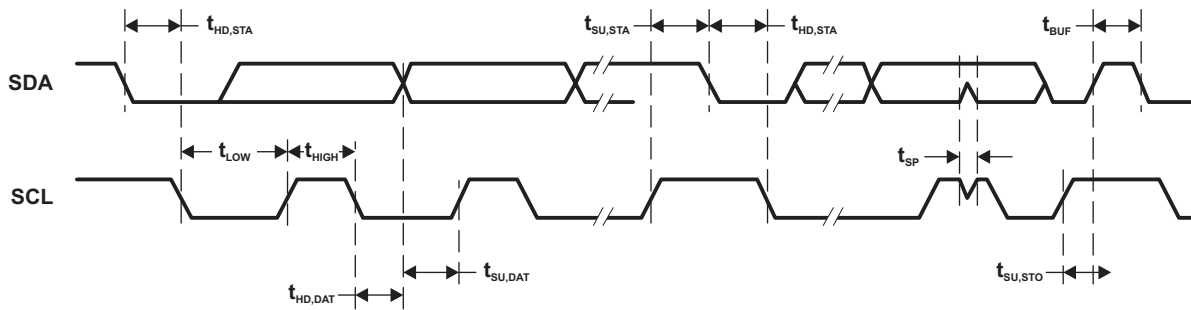


Figure 5-15. I2C Mode Timing

5.36 12-Bit ADC, Power Supply and Input Range Conditions

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
AV _{CC}	Analog supply voltage	AV _{CC} and DV _{CC} are connected together, AV _{SS} and DV _{SS} are connected together, V _(AVSS) = V _(DVSS) = 0 V		2.2		3.6	V
V _(Ax)	Analog input voltage range ⁽²⁾	All ADC12 pins: P6.0 to P6.7, P7.4 to P7.7, P5.0, and P5.1 terminals		0		AV _{CC}	V
I _{ADC12_A}	Operating supply current into AV _{CC} terminal ⁽³⁾	f _{ADC12CLK} = 5.0 MHz, ADC12ON = 1, REFON = 0, SHT0 = 0, SHT1 = 0, ADC12DIV = 0	2.2 V		125	155	μA
			3 V		150	220	
I _{REF+}	Operating supply current into AV _{CC} terminal ⁽⁴⁾	ADC12ON = 0, REFON = 1, REF2_5V = 1	3 V		150	190	μA
			2.2 V, 3 V		150	180	
C _I	Input capacitance	Only one terminal Ax can be selected at one time	2.2 V		20	25	pF
R _I	Input MUX ON resistance	0 V ≤ V _{Ax} ≤ AV _{CC}		10	200	1900	Ω

(1) The leakage current is specified by the digital I/O input leakage.

(2) The analog input voltage range must be within the selected reference voltage range V_{R+} to V_{R-} for valid conversion results. If the reference voltage is supplied by an external source or if the internal reference voltage is used and REFOUT = 1, then decoupling capacitors are required. See [Section 5.37](#) and [Section 5.38](#).

(3) The internal reference supply current is not included in current consumption parameter I_{ADC12}.

(4) The internal reference current is supplied via terminal AV_{CC}. Consumption is independent of the ADC12ON control bit, unless a conversion is active. The REFON bit enables to settle the built-in reference before starting an A/D conversion. No external load.

5.37 12-Bit ADC, External Reference

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{eREF+}	Positive external reference voltage input	V _{eREF+} > V _{REF-} /V _{eREF-} ⁽²⁾		1.4		AV _{CC}	V
V _{REF-} /V _{eREF-}	Negative external reference voltage input	V _{eREF+} > V _{REF-} /V _{eREF-} ⁽³⁾		0		1.2	V
(V _{eREF+} – V _{REF-} /V _{eREF-})	Differential external reference voltage input	V _{eREF+} > V _{REF-} /V _{eREF-} ⁽⁴⁾		1.4		AV _{CC}	V
I _{VeREF+}	Static input current	0 V ≤ V _{eREF+} ≤ V _{AVCC}	2.2 V, 3 V			±1	μA
I _{VREF-/VeREF-}	Static input current	0 V ≤ V _{eREF-} ≤ V _{AVCC}	2.2 V, 3 V			±1	μA
C _{VREF+/-}	Capacitance at VREF+ or VREF- terminal			(5)10			μF

(1) The external reference is used during conversion to charge and discharge the capacitance array. The input capacitance, C_i, is also the dynamic load for an external reference during conversion. The dynamic impedance of the reference supply should follow the recommendations on analog-source impedance to allow the charge to settle for 12-bit accuracy.

(2) The accuracy limits the minimum positive external reference voltage. Lower reference voltage levels may be applied with reduced accuracy requirements.

(3) The accuracy limits the maximum negative external reference voltage. Higher reference voltage levels may be applied with reduced accuracy requirements.

(4) The accuracy limits minimum external differential reference voltage. Lower differential reference voltage levels may be applied with reduced accuracy requirements.

(5) Two decoupling capacitors, 10μF and 100nF, should be connected to VREF to decouple the dynamic current required for an external reference source if it is used for the ADC12_A. See also the *MSP430x5xx and MSP430x6xx Family User's Guide* ([SLAU208](#)).

5.38 12-Bit ADC, Built-In Reference

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{REF+}	Positive built-in reference voltage output	REF2_5V = 1 for 2.5 V, I _{VREF+} (max) ≤ I _{VREF+} ≤ I _{VREF+} (min)	3 V	2.35	2.45	2.53	V
		REF2_5V = 0 for 1.5 V, I _{VREF+} (max) ≤ I _{VREF+} ≤ I _{VREF+} (min)	2.2 V, 3 V	1.41	1.47	1.53	
AV _{CC(min)}	AV _{CC} minimum voltage, Positive built-in reference active	REF2_5V = 0		2.2			V
		REF2_5V = 1		2.8			
I _{VREF+}	Load current out of VREF+ terminal		2.2 V			-1	mA
			3 V			-1	
I _{L(VREF+)}	Load-current regulation, VREF+ terminal	I _{VREF+} = +10 μA–1000 μA, Analog input voltage ~0.75 V, REF2_5V = 0	2.2 V			±2	LSB
			3 V			±2	
		I _{VREF+} = +10 μA–1000 μA, Analog input voltage ~1.25 V, REF2_5V = 1	3 V			±2	
C _{VREF+}	Capacitance at VREF+ terminal	REFON = REFOUT = 1 ⁽¹⁾	2.2 V, 3 V	20		100	pF
T _{REF+}	Temperature coefficient of built-in reference ⁽²⁾	REF2_5V = 0, I _{VREF+} is a constant in the range of 0 mA ≤ I _{VREF+} ≤ -1 mA	2.2 V, 3 V		30		ppm/ °C
		REF2_5V = 1, I _{VREF+} is a constant in the range of 0 mA ≤ I _{VREF+} ≤ -1 mA	3 V		30		
t _{SETTLE}	Settling time of reference voltage ⁽³⁾	V _{REF+} = 1.5 V, V _{AVCC} = 2.2 V, REFOUT = 0, REFON = 0 → 1			20		μs
		V _{REF+} = 2.5 V, V _{AVCC} = 2.8 V, REFOUT = 0, REFON = 0 → 1			20		
		V _{REF+} = 1.5 V, V _{AVCC} = 2.2 V, C _{VREF} = C _{VREF(max)} , REFOUT = 1, REFON = 0 → 1			35		
		V _{REF+} = 2.5 V, V _{AVCC} = 2.8 V, C _{VREF} = C _{VREF(max)} , REFOUT = 1, REFON = 0 → 1			35		

- (1) Two decoupling capacitors, 10 μF and 100 nF, should be connected to VREF to decouple the dynamic current required for an external reference source if it is used for the ADC12_A. See also the *MSP430x5xx and MSP430x6xx Family User's Guide* ([SLAU208](#)).
- (2) Calculated using the box method: (MAX(-40 to 85°C) – MIN(-40 to 85°C)) / MIN(-40 to 85°C)/(85°C – (-40°C))
- (3) The condition is that the error in a conversion started after t_{REFON} is less than ±0.5 LSB. The settling time depends on the external capacitive load.

5.39 12-Bit ADC, Timing Parameters

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{ADC12CLK}		For specified performance of ADC12 linearity parameters	2.2 V, 3 V	0.45	4.8	5.4	MHz
f _{ADC12OSC}	Internal ADC12 oscillator ⁽¹⁾	ADC12DIV = 0, f _{ADC12CLK} = f _{ADC12OSC}	2.2 V, 3 V	4.2	4.65	5.0	MHz
t _{CONVERT}	Conversion time	REFON = 0, Internal oscillator, f _{ADC12OSC} = 4.2 MHz to 5.4 MHz	2.2 V, 3 V	2.4		3.1	μs
		External f _{ADC12CLK} from ACLK, MCLK or SMCLK, ADC12SSEL ≠ 0			(2)		
t _{ADC12ON}	Turn on settling time of the ADC	See ⁽³⁾				100	ns
t _{Sample}	Sampling time	R _S = 400 Ω, R _I = 1000 Ω, C _I = 30 pF, τ = [R _S + R _I] × C _I ⁽⁴⁾	2.2 V, 3 V	1000			ns

(1) The ADC12OSC is sourced directly from MODOSC inside the UCS.

(2) 13 × ADC12DIV × 1/f_{ADC12CLK}

(3) The condition is that the error in a conversion started after t_{ADC12ON} is less than ±0.5 LSB. The reference and input signal are already settled.

(4) Approximately ten Tau (τ) are needed to get an error of less than ±0.5 LSB:

$$t_{\text{sample}} = \ln(2^{n+1}) \times (R_S + R_I) \times C_I + 800 \text{ ns, where } n = \text{ADC resolution} = 12, R_S = \text{external source resistance}$$

5.40 12-Bit ADC, Linearity Parameters

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
E _I	Integral linearity error	1.4 V ≤ (V _{eREF+} - V _{REF-/V_{eREF-}})min ≤ 1.6 V	2.2 V, 3 V			±2	LSB
		1.6 V < (V _{eREF+} - V _{REF-/V_{eREF-}})min ≤ V _{AVCC}				±1.7	
E _D	Differential linearity error	(V _{eREF+} - V _{REF-/V_{eREF-}})min ≤ (V _{eREF+} - V _{REF-/V_{eREF-}}), C _{VREF+} = 20 pF	2.2 V, 3 V			±1	LSB
E _O	Offset error	(V _{eREF+} - V _{REF-/V_{eREF-}})min ≤ (V _{eREF+} - V _{REF-/V_{eREF-}}), Internal impedance of source R _S < 100 Ω, C _{VREF+} = 20 pF	2.2 V, 3 V		±1	±3.5	LSB
E _G	Gain error	(V _{eREF+} - V _{REF-/V_{eREF-}})min ≤ (V _{eREF+} - V _{REF-/V_{eREF-}}), C _{VREF+} = 20 pF	2.2 V, 3 V		±1.1	±2	LSB
E _T	Total unadjusted error	(V _{eREF+} - V _{REF-/V_{eREF-}})min ≤ (V _{eREF+} - V _{REF-/V_{eREF-}}), C _{VREF+} = 20 pF	2.2 V, 3 V		±2	±5	LSB

5.41 12-Bit ADC, Temperature Sensor and Built-In V_{MID}

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
I_{SENSOR}	Operating supply current into AVCC terminal ⁽¹⁾	REFON = 0, INCH = 0Ah, ADC12ON = N/A, $T_A = 25^\circ\text{C}$	2.2 V	150			μA
			3 V	150			
V_{SENSOR}	See ⁽²⁾	ADC12ON = 1, INCH = 0Ah, $T_A = 0^\circ\text{C}$	2.2 V	894			mV
			3 V	894			
TC_{SENSOR}		ADC12ON = 1, INCH = 0Ah	2.2 V	3.66			mV/ $^\circ\text{C}$
			3 V	3.66			
$t_{SENSOR(sample)}$	Sample time required if channel 10 is selected ⁽³⁾	ADC12ON = 1, INCH = 0Ah, Error of conversion result ≤ 1 LSB	2.2 V	30			μs
			3 V	30			
V_{MID}	AVCC divider at channel 11	ADC12ON = 1, INCH = 0Bh, V_{MID} is approximately $0.5 \times V_{AVCC}$	2.2 V	1.1			V
			3 V	1.5			
$t_{VMID(sample)}$	Sample time required if channel 11 is selected ⁽⁴⁾	ADC12ON = 1, INCH = 0Bh, Error of conversion result ≤ 1 LSB	2.2 V, 3 V	1000			ns

- (1) The sensor current I_{SENSOR} is consumed if (ADC12ON = 1 and REFON = 1) or (ADC12ON = 1 and INCH = 0Ah and sample signal is high). When REFON = 1, I_{SENSOR} is already included in I_{REF+} .
- (2) The temperature sensor offset can be significant. A single-point calibration is recommended to minimize the offset error of the built-in temperature sensor.
- (3) The typical equivalent impedance of the sensor is 51 k Ω . The sample time required includes the sensor-on time $t_{SENSOR(on)}$.
- (4) The on-time $t_{VMID(on)}$ is included in the sampling time $t_{VMID(sample)}$; no additional on time is needed.

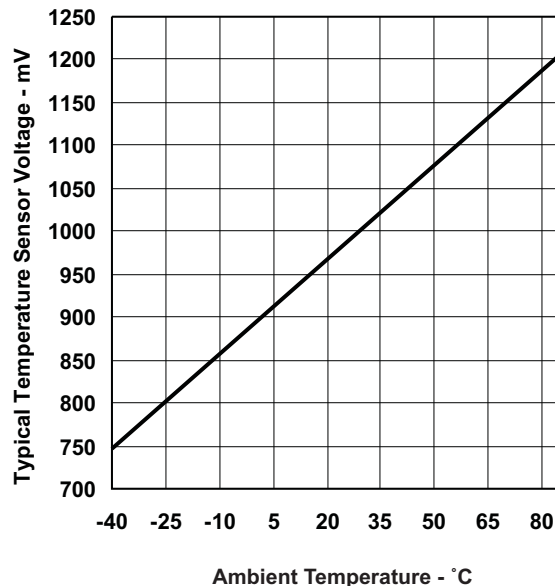


Figure 5-16. Typical Temperature Sensor Voltage

5.42 Flash Memory

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DV _{CC(PGM/ERASE)}	Program and erase supply voltage		1.8		3.6	V
I _{PGM}	Average supply current from DV _{CC} during program			3	5	mA
I _{ERASE}	Average supply current from DV _{CC} during erase			6	11	mA
I _{MERASE} , I _{BANK}	Average supply current from DV _{CC} during mass erase or bank erase			6	11	mA
t _{CPT}	Cumulative program time	See ⁽¹⁾			16	ms
	Program and erase endurance		10 ⁴	10 ⁵		cycles
t _{Retention}	Data retention duration	T _J = 25°C	100			years
t _{Word}	Word or byte program time	See ⁽²⁾	64		85	μs
t _{Block, 0}	Block program time for first byte or word	See ⁽²⁾	49		65	μs
t _{Block, 1–(N–1)}	Block program time for each additional byte or word, except for last byte or word	See ⁽²⁾	37		49	μs
t _{Block, N}	Block program time for last byte or word	See ⁽²⁾	55		73	μs
t _{Erase}	Erase time for segment, mass erase, and bank erase when available.	See ⁽²⁾	23		32	ms
f _{MCLK,MGR}	MCLK frequency in marginal read mode (FCTL4.MGR0 = 1 or FCTL4.MGR1 = 1)		0		1	MHz

- (1) The cumulative program time must not be exceeded when writing to a 128-byte flash block. This parameter applies to all programming methods: individual word or byte write and block write modes.
(2) These values are hardwired into the flash controller's state machine.

5.43 JTAG and Spy-Bi-Wire Interface

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{SBW}	Spy-Bi-Wire input frequency	2.2 V, 3 V	0		20	MHz
t _{SBW,Low}	Spy-Bi-Wire low clock pulse duration	2.2 V, 3 V	0.025		15	μs
t _{SBW,En}	Spy-Bi-Wire enable time (TEST high to acceptance of first clock edge) ⁽¹⁾	2.2 V, 3 V			1	μs
t _{SBW,Rst}	Spy-Bi-Wire return to normal operation time		15		100	μs
f _{TCK}	TCK input frequency for 4-wire JTAG ⁽²⁾	2.2 V	0		5	MHz
		3 V	0		10	MHz
R _{internal}	Internal pulldown resistance on TEST	2.2 V, 3 V	45	60	80	kΩ

- (1) Tools accessing the Spy-Bi-Wire interface need to wait for the t_{SBW,En} time after pulling the TEST/SBWTCK pin high before applying the first SBWTCK clock edge.
(2) f_{TCK} may be restricted to meet the timing requirements of the module selected.

6 Short-Form Description

6.1 CPU

The MSP430 CPU has a 16-bit RISC architecture that is highly transparent to the application. All operations, other than program-flow instructions, are performed as register operations in conjunction with seven addressing modes for source operand and four addressing modes for destination operand.

The CPU is integrated with 16 registers that provide reduced instruction execution time. The register-to-register operation execution time is one cycle of the CPU clock.

Four of the registers, R0 to R3, are dedicated as program counter, stack pointer, status register, and constant generator, respectively. The remaining registers are general-purpose registers.

Peripherals are connected to the CPU using data, address, and control buses, and can be handled with all instructions.

The instruction set consists of the original 51 instructions with three formats and seven address modes and additional instructions for the expanded address range. Each instruction can operate on word and byte data.

Program Counter	PC/R0
Stack Pointer	SP/R1
Status Register	SR/CG1/R2
Constant Generator	CG2/R3
General-Purpose Register	R4
General-Purpose Register	R5
General-Purpose Register	R6
General-Purpose Register	R7
General-Purpose Register	R8
General-Purpose Register	R9
General-Purpose Register	R10
General-Purpose Register	R11
General-Purpose Register	R12
General-Purpose Register	R13
General-Purpose Register	R14
General-Purpose Register	R15

6.2 Operating Modes

The MSP430 has one active mode and five software selectable low-power modes of operation. An interrupt event can wake up the device from any of the low-power modes, service the request, and restore back to the low-power mode on return from the interrupt program.

The following six operating modes can be configured by software:

- Active mode (AM)
 - All clocks are active
- Low-power mode 0 (LPM0)
 - CPU is disabled
 - ACLK and SMCLK remain active, MCLK is disabled
 - FLL loop control remains active
- Low-power mode 1 (LPM1)
 - CPU is disabled
 - FLL loop control is disabled
 - ACLK and SMCLK remain active, MCLK is disabled
- Low-power mode 2 (LPM2)
 - CPU is disabled
 - MCLK and FLL loop control and DCOCLK are disabled
 - DCO's dc-generator remains enabled
 - ACLK remains active
- Low-power mode 3 (LPM3)
 - CPU is disabled
 - MCLK, FLL loop control, and DCOCLK are disabled
 - DCO's dc generator is disabled
 - ACLK remains active
- Low-power mode 4 (LPM4)
 - CPU is disabled
 - ACLK is disabled
 - MCLK, FLL loop control, and DCOCLK are disabled
 - DCO's dc generator is disabled
 - Crystal oscillator is stopped
 - Complete data retention

6.3 Interrupt Vector Addresses

The interrupt vectors and the power-up start address are located in the address range 0FFFFh to 0FF80h. The vector contains the 16-bit address of the appropriate interrupt-handler instruction sequence.

Table 6-1. Interrupt Sources, Flags, and Vectors

INTERRUPT SOURCE	INTERRUPT FLAG	SYSTEM INTERRUPT	WORD ADDRESS	PRIORITY
System Reset Power-Up External Reset Watchdog Timeout, Password Violation Flash Memory Password Violation PMM Password Violation	WDTIFG, KEYV (SYSRSTIV) ^{(1) (2)}	Reset	0FFFEh	63, highest
System NMI PMM Vacant Memory Access JTAG Mailbox	SVMLIFG, SVMHIFG, DLYLIFG, DLYHIFG, VLRIFG, VLRHIFG, VMAIFG, JMBNIFG, JMBOUTIFG (SYSSNIV) ⁽¹⁾	(Non)maskable	0FFFCh	62
User NMI NMI Oscillator Fault Flash Memory Access Violation	NMIIFG, OFIFG, ACCVIFG (SYSUNIV) ^{(1) (2)}	(Non)maskable	0FFFAh	61
TB0	TBCCR0 CCIFG0 ⁽³⁾	Maskable	0FFF8h	60
TB0	TBCCR1 CCIFG1 ... TBCCR6 CCIFG6, TBIFG (TBIV) ^{(1) (3)}	Maskable	0FFF6h	59
Watchdog Timer_A Interval Timer Mode	WDTIFG	Maskable	0FFF4h	58
USCI_A0 Receive or Transmit	UCA0RXIFG, UCA0TXIFG (UCA0IV) ^{(1) (3)}	Maskable	0FFF2h	57
USCI_B0 Receive or Transmit	UCB0RXIFG, UCB0TXIFG (UCB0IV) ^{(1) (3)}	Maskable	0FFF0h	56
ADC12_A	ADC12IFG0 ... ADC12IFG15 (ADC12IV) ^{(1) (3)}	Maskable	0FFEEh	55
TA0	TA0CCR0 CCIFG0 ⁽³⁾	Maskable	0FFECCh	54
TA0	TA0CCR1 CCIFG1 ... TA0CCR4 CCIFG4, TA0IFG (TA0IV) ^{(1) (3)}	Maskable	0FFEAh	53
USCI_A2 Receive or Transmit	UCA2RXIFG, UCA2TXIFG (UCA2IV) ^{(1) (3)}	Maskable	0FFE8h	52
USCI_B2 Receive or Transmit	UCB2RXIFG, UCB2TXIFG (UCB2IV) ^{(1) (3)}	Maskable	0FFE6h	51
DMA	DMA0IFG, DMA1IFG, DMA2IFG (DMAIV) ^{(1) (3)}	Maskable	0FFE4h	50
TA1	TA1CCR0 CCIFG0 ⁽³⁾	Maskable	0FFE2h	49
TA1	TA1CCR1 CCIFG1 ... TA1CCR2 CCIFG2, TA1IFG (TA1IV) ^{(1) (3)}	Maskable	0FFE0h	48
I/O Port P1	P1IFG.0 to P1IFG.7 (P1IV) ^{(1) (3)}	Maskable	0FFDEh	47
USCI_A1 Receive or Transmit	UCA1RXIFG, UCA1TXIFG (UCA1IV) ^{(1) (3)}	Maskable	0FFDCh	46
USCI_B1 Receive or Transmit	UCB1RXIFG, UCB1TXIFG (UCB1IV) ^{(1) (3)}	Maskable	0FFDAh	45
USCI_A3 Receive or Transmit	UCA3RXIFG, UCA3TXIFG (UCA3IV) ^{(1) (3)}	Maskable	0FFD8h	44
USCI_B3 Receive or Transmit	UCB3RXIFG, UCB3TXIFG (UCB3IV) ^{(1) (3)}	Maskable	0FFD6h	43
I/O Port P2	P2IFG.0 to P2IFG.7 (P2IV) ^{(1) (3)}	Maskable	0FFD4h	42
RTC_A	RTCRDYIFG, RTCTEVIFG, RTCAIFG, RT0PSIFG, RT1PSIFG (RTCIV) ^{(1) (3)}	Maskable	0FFD2h	41
Reserved	Reserved ⁽⁴⁾		0FFD0h	40
			⋮	⋮
			0FF80h	0, lowest

(1) Multiple source flags

(2) A reset is generated if the CPU tries to fetch instructions from within peripheral space or vacant memory space.

(Non)maskable: the individual interrupt-enable bit can disable an interrupt event, but the general-interrupt enable cannot disable it.

(3) Interrupt flags are located in the module.

(4) Reserved interrupt vectors at addresses are not used in this device and can be used for regular program code if necessary. To maintain compatibility with other devices, it is recommended to reserve these locations.

6.4 Memory Organization

Table 6-2 summarizes the memory organization of all device variants.

Table 6-2. Memory Organization

		MSP430F5419 MSP430F5418	MSP430F5436 MSP430F5435	MSP430F5438 MSP430F5437
Memory (flash) Main: interrupt vector Main: code memory	Total Size Flash Flash	128 KB 00FFFFh–00FF80h 025BFFh–005C00h	192 KB 00FFFFh–00FF80h 035BFFh–005C00h	256 KB 00FFFFh–00FF80h 045BFFh–005C00h
Main: code memory	Bank D	N/A	23 KB 035BFFh–030000h	64 KB 03FFFFh–030000h
	Bank C	23 KB 025BFFh–020000h	64 KB 02FFFFh–020000h	64 KB 02FFFFh–020000h
	Bank B	64 KB 01FFFFh–010000h	64 KB 01FFFFh–010000h	64 KB 01FFFFh–010000h
	Bank A	41 KB 00FFFFh–005C00h	41 KB 00FFFFh–005C00h	64 KB 045BFFh–040000h 00FFFFh–005C00h
RAM	Size	16 KB	16 KB	16 KB
	Sector 3	4 KB 005BFFh–004C00h	4 KB 005BFFh–004C00h	4 KB 005BFFh–004C00h
	Sector 2	4 KB 004BFFh–003C00h	4 KB 004BFFh–003C00h	4 KB 004BFFh–003C00h
	Sector 1	4 KB 003BFFh–002C00h	4 KB 003BFFh–002C00h	4 KB 003BFFh–002C00h
	Sector 0	4 KB 002BFFh–001C00h	4 KB 002BFFh–001C00h	4 KB 002BFFh–001C00h
Factory memory (Boot code)	Size	256 B 001BFFh–001B00h	256 B 001BFFh–001B00h	256 B 001BFFh–001B00h
Factory memory (TLV)	Size	256 B 001AFFh–001A00h	256 B 001AFFh–001A00h	256 B 001AFFh–001A00h
Information memory (flash)	Info A	128 B 0019FFh–001980h	128 B 0019FFh–001980h	128 B 0019FFh–001980h
	Info B	128 B 00197Fh–001900h	128 B 00197Fh–001900h	128 B 00197Fh–001900h
	Info C	128 B 0018FFh–001880h	128 B 0018FFh–001880h	128 B 0018FFh–001880h
	Info D	128 B 00187Fh–001800h	128 B 00187Fh–001800h	128 B 00187Fh–001800h
Bootstrap loader (BSL) ⁽¹⁾ memory (flash)	BSL 3	512 B 0017FFh–001600h	512 B 0017FFh–001600h	512 B 0017FFh–001600h
	BSL 2	512 B 0015FFh–001400h	512 B 0015FFh–001400h	512 B 0015FFh–001400h
	BSL 1	512 B 0013FFh–001200h	512 B 0013FFh–001200h	512 B 0013FFh–001200h
	BSL 0	512 B 0011FFh–001000h	512 B 0011FFh–001000h	512 B 0011FFh–001000h
Peripherals	Size	4KB 000FFFh–000000h	4KB 000FFFh–000000h	4KB 000FFFh–000000h

(1) The BSL area contains a Texas Instruments provided BSL and cannot be modified.

6.5 Bootstrap Loader (BSL)

The BSL enables users to program the flash memory or RAM using a UART serial interface. Access to the device memory via the BSL is protected by an user-defined password. Usage of the BSL requires four pins as shown in [Table 6-3](#). BSL entry requires a specific entry sequence on the $\overline{\text{RST}}/\text{NMI}/\text{SBWTDIO}$ and $\text{TEST}/\text{SBWTCK}$ pins. For a complete description of the features of the BSL and its implementation, see the *MSP430 Programming Via the Bootstrap Loader User's Guide* ([SLAU319](#)). For further details on interfacing to development tools and device programmers, see the *MSP430 Hardware Tools User's Guide* ([SLAU278](#)).

Table 6-3. BSL Pin Requirements and Functions

DEVICE SIGNAL	BSL FUNCTION
$\overline{\text{RST}}/\text{NMI}/\text{SBWTDIO}$	Entry sequence signal
$\text{TEST}/\text{SBWTCK}$	Entry sequence signal
P1.1	Data transmit
P1.2	Data receive
VCC	Power supply
VSS	Ground supply

6.6 JTAG Operation

6.6.1 JTAG Standard Interface

The MSP430 family supports the standard JTAG interface which requires four signals for sending and receiving data. The JTAG signals are shared with general-purpose I/O. The $\text{TEST}/\text{SBWTCK}$ pin is used to enable the JTAG signals. In addition to these signals, the $\overline{\text{RST}}/\text{NMI}/\text{SBWTDIO}$ is required to interface with MSP430 development tools and device programmers. The JTAG pin requirements are shown in [Table 6-4](#). For a complete description of the features of the JTAG interface and its implementation, see *MSP430 Programming Via the JTAG Interface* ([SLAU320](#)). For further details on interfacing to development tools and device programmers, see the *MSP430 Hardware Tools User's Guide* ([SLAU278](#)).

Table 6-4. JTAG Pin Requirements and Functions

DEVICE SIGNAL	DIRECTION	FUNCTION
PJ.3/TCK	IN	JTAG clock input
PJ.2/TMS	IN	JTAG state control
PJ.1/TDI/TCLK	IN	JTAG data input, TCLK input
PJ.0/TDO	OUT	JTAG data output
$\text{TEST}/\text{SBWTCK}$	IN	Enable JTAG pins
$\overline{\text{RST}}/\text{NMI}/\text{SBWTDIO}$	IN	External reset
VCC		Power supply
VSS		Ground supply

6.6.2 Spy-Bi-Wire Interface

In addition to the standard JTAG interface, the MSP430 family supports the two wire Spy-Bi-Wire interface. Spy-Bi-Wire can be used to interface with MSP430 development tools and device programmers. The Spy-Bi-Wire interface pin requirements are shown in [Table 6-5](#). For a complete description of the features of the JTAG interface and its implementation, see *MSP430 Programming Via the JTAG Interface* ([SLAU320](#)). For further details on interfacing to development tools and device programmers, see the *MSP430 Hardware Tools User's Guide* ([SLAU278](#)).

Table 6-5. Spy-Bi-Wire Pin Requirements and Functions

DEVICE SIGNAL	DIRECTION	FUNCTION
TEST/SBWTCK	IN	Spy-Bi-Wire clock input
$\overline{\text{RST}}$ /NMI/SBWDIO	IN, OUT	Spy-Bi-Wire data input/output
VCC		Power supply
VSS		Ground supply

6.7 Flash Memory ([Link to User's Guide](#))

The flash memory can be programmed via the JTAG port, Spy-Bi-Wire (SBW), the BSL, or in-system by the CPU. The CPU can perform single-byte, single-word, and long-word writes to the flash memory. Features of the flash memory include:

- Flash memory has n segments of main memory and four segments of information memory (A to D) of 128 bytes each. Each segment in main memory is 512 bytes in size.
- Segments 0 to n may be erased in one step, or each segment may be individually erased.
- Segments A to D can be erased individually. Segments A to D are also called *information memory*.
- Segment A can be locked separately.

6.8 RAM Memory ([Link to User's Guide](#))

The RAM memory is made up of n sectors. Each sector can be completely powered down to save leakage, however all data is lost. Features of the RAM memory include:

- RAM memory has n sectors. The size of a sector can be found in [Memory Organization](#).
- Each sector 0 to n can be complete disabled, however data retention is lost.
- Each sector 0 to n automatically enters low power retention mode when possible.
- For Devices that contain USB memory, the USB memory can be used as normal RAM if USB is not required.

6.9 Peripherals

Peripherals are connected to the CPU through data, address, and control buses and can be handled using all instructions. For complete module descriptions, see the *MSP430x5xx and MSP430F6xx Family User's Guide* ([SLAU208](#)).

6.9.1 Digital I/O ([Link to User's Guide](#))

There are up to ten 8-bit I/O ports implemented: For 100-pin options, P1 through P10 are complete. P11 contains three individual I/O ports. For 80-pin options, P1 through P7 are complete. P8 contains seven individual I/O ports. P9 through P11 do not exist. Port PJ contains four individual I/O ports, common to all devices.

- All individual I/O bits are independently programmable.
- Any combination of input, output, and interrupt conditions is possible.
- Pullup or pulldown on all ports is programmable.
- Drive strength on all ports is programmable.
- Edge-selectable interrupt and LPM5 wakeup input capability is available for all bits of ports P1 and P2.
- Read/write access to port-control registers is supported by all instructions.
- Ports can be accessed byte-wise (P1 through P11) or word-wise in pairs (PA through PF).

6.9.2 Oscillator and System Clock ([Link to User's Guide](#))

The clock system in the MSP430x5xx family of devices is supported by the Unified Clock System (UCS) module that includes support for a 32-kHz watch crystal oscillator (XT1 LF mode), an internal very-low-power low-frequency oscillator (VLO), an internal trimmed low-frequency oscillator (REFO), an integrated internal digitally controlled oscillator (DCO), and a high-frequency crystal oscillator (XT1 HF mode or XT2). The UCS module is designed to meet the requirements of both low system cost and low power consumption. The UCS module features digital frequency locked loop (FLL) hardware that, in conjunction with a digital modulator, stabilizes the DCO frequency to a programmable multiple of the selected FLL reference frequency. The internal DCO provides a fast turn-on clock source and stabilizes in less than 5 μ s. The UCS module provides the following clock signals:

- Auxiliary clock (ACLK), sourced from a 32-kHz watch crystal, a high-frequency crystal, the internal low-frequency oscillator (VLO), the trimmed low-frequency oscillator (REFO), or the internal digitally controlled oscillator DCO.
- Main clock (MCLK), the system clock used by the CPU. MCLK can be sourced by same sources made available to ACLK.
- Sub-Main clock (SMCLK), the subsystem clock used by the peripheral modules. SMCLK can be sourced by same sources made available to ACLK.
- ACLK/n, the buffered output of ACLK, ACLK/2, ACLK/4, ACLK/8, ACLK/16, ACLK/32.

6.9.3 Power Management Module (PMM) ([Link to User's Guide](#))

The PMM includes an integrated voltage regulator that supplies the core voltage to the device and contains programmable output levels to provide for power optimization. The PMM also includes supply voltage supervisor (SVS) and supply voltage monitoring (SVM) circuitry, as well as brownout protection. The brownout circuit is implemented to provide the proper internal reset signal to the device during power-on and power-off. The SVS/SVM circuitry detects if the supply voltage drops below a user-selectable level and supports both supply voltage supervision (the device is automatically reset) and supply voltage monitoring (SVM, the device is not automatically reset). SVS and SVM circuitry is available on the primary supply and core supply.

6.9.4 Hardware Multiplier ([Link to User's Guide](#))

The multiplication operation is supported by a dedicated peripheral module. The module performs operations with 32-bit, 24-bit, 16-bit, and 8-bit operands. The module is capable of supporting signed and unsigned multiplication as well as signed and unsigned multiply and accumulate operations.

6.9.5 Real-Time Clock (RTC_A) ([Link to User's Guide](#))

The RTC_A module can be used as a general-purpose 32-bit counter (counter mode) or as an integrated real-time clock (RTC) (calendar mode). In counter mode, the RTC_A also includes two independent 8-bit timers that can be cascaded to form a 16-bit timer/counter. Both timers can be read and written by software. Calendar mode integrates an internal calendar which compensates for months with less than 31 days and includes leap year correction. The RTC_A also supports flexible alarm functions and offset-calibration hardware.

6.9.6 Watchdog Timer (WDT_A) ([Link to User's Guide](#))

The primary function of the watchdog timer (WDT_A) module is to perform a controlled system restart after a software problem occurs. If the selected time interval expires, a system reset is generated. If the watchdog function is not needed in an application, the module can be configured as an interval timer and can generate interrupts at selected time intervals.

6.9.7 System Module (SYS) ([Link to User's Guide](#))

The SYS module handles many of the system functions within the device. These include power on reset and power up clear handling, NMI source selection and management, reset interrupt vector generators, boot strap loader entry mechanisms, as well as, configuration management (device descriptors). It also includes a data exchange mechanism via JTAG called a JTAG mailbox that can be used in the application.

Table 6-6. System Module Interrupt Vector Registers

INTERRUPT VECTOR REGISTER	ADDRESS	INTERRUPT EVENT	VALUE	PRIORITY
SYSRSTIV, System Reset	019Eh	No interrupt pending	00h	
		Brownout (BOR)	02h	Highest
		$\overline{\text{RST}}$ /NMI (POR)	04h	
		PMMSWBOR (BOR)	06h	
		Reserved	08h	
		Security violation (BOR)	0Ah	
		SVSL (POR)	0Ch	
		SVSH (POR)	0Eh	
		SVML_OVP (POR)	10h	
		SVMH_OVP (POR)	12h	
		PMMSWPOR (POR)	14h	
		WDT timeout (PUC)	16h	
		WDT password violation (PUC)	18h	
		KEYV flash password violation (PUC)	1Ah	
		Reserved	1Ch	
		Peripheral area fetch (PUC)	1Eh	
		PMM password violation (PUC)	20h	
Reserved	22h to 3Eh	Lowest		
SYSSNIV, System NMI	019Ch	No interrupt pending	00h	
		SVMLIFG	02h	Highest
		SVMHIFG	04h	
		SVSMLDLYIFG	06h	
		SVSMHDLYIFG	08h	
		VMAIFG	0Ah	
		JMBINIFG	0Ch	
		JMBOUTIFG	0Eh	
		SVMLVLRIFG	10h	
		SVMHVLRFIFG	12h	
		Reserved	14h to 1Eh	Lowest
		SYSUNIV, User NMI	019Ah	No interrupt pending
NMIFG	02h			Highest
OFIFG	04h			
ACCVIFG	06h			
Reserved	08h			
Reserved	0Ah to 1Eh			Lowest

6.9.8 DMA Controller [\(Link to User's Guide\)](#)

The DMA controller allows movement of data from one memory address to another without CPU intervention. For example, the DMA controller can be used to move data from the ADC12_A conversion memory to RAM. Using the DMA controller can increase the throughput of peripheral modules. The DMA controller reduces system power consumption by allowing the CPU to remain in sleep mode, without having to awaken to move data to or from a peripheral.

Table 6-7. DMA Trigger Assignments ⁽¹⁾

Trigger	Channel		
	0	1	2
0	DMAREQ	DMAREQ	DMAREQ
1	TA0CCR0 CCIFG	TA0CCR0 CCIFG	TA0CCR0 CCIFG
2	TA0CCR2 CCIFG	TA0CCR2 CCIFG	TA0CCR2 CCIFG
3	TA1CCR0 CCIFG	TA1CCR0 CCIFG	TA1CCR0 CCIFG
4	TA1CCR2 CCIFG	TA1CCR2 CCIFG	TA1CCR2 CCIFG
5	TB0CCR0 CCIFG	TB0CCR0 CCIFG	TB0CCR0 CCIFG
6	TB0CCR2 CCIFG	TB0CCR2 CCIFG	TB0CCR2 CCIFG
7	Reserved	Reserved	Reserved
8	Reserved	Reserved	Reserved
9	Reserved	Reserved	Reserved
10	Reserved	Reserved	Reserved
11	Reserved	Reserved	Reserved
12	Reserved	Reserved	Reserved
13	Reserved	Reserved	Reserved
14	Reserved	Reserved	Reserved
15	Reserved	Reserved	Reserved
16	UCA0RXIFG	UCA0RXIFG	UCA0RXIFG
17	UCA0TXIFG	UCA0TXIFG	UCA0TXIFG
18	UCB0RXIFG	UCB0RXIFG	UCB0RXIFG
19	UCB0TXIFG	UCB0TXIFG	UCB0TXIFG
20	UCA1RXIFG	UCA1RXIFG	UCA1RXIFG
21	UCA1TXIFG	UCA1TXIFG	UCA1TXIFG
22	UCB1RXIFG	UCB1RXIFG	UCB1RXIFG
23	UCB1TXIFG	UCB1TXIFG	UCB1TXIFG
24	ADC12IFGx	ADC12IFGx	ADC12IFGx
25	Reserved	Reserved	Reserved
26	Reserved	Reserved	Reserved
27	Reserved	Reserved	Reserved
28	Reserved	Reserved	Reserved
29	MPY ready	MPY ready	MPY ready
30	DMA2IFG	DMA0IFG	DMA1IFG
31	DMAE0	DMAE0	DMAE0

(1) Reserved DMA triggers may be used by other devices in the family. Reserved DMA triggers will not cause any DMA trigger event when selected.

6.9.9 Universal Serial Communication Interface (USCI) (Links to User's Guide: [UART Mode](#), [SPI Mode](#), [I2C Mode](#))

The USCI modules are used for serial data communication. The USCI module supports synchronous communication protocols such as SPI (3 or 4 pin) and I²C, and asynchronous communication protocols such as UART, enhanced UART with automatic baudrate detection, and IrDA. Each USCI module contains two portions, A and B.

The USCI_An module provides support for SPI (3 pin or 4 pin), UART, enhanced UART, or IrDA.

The USCI_Bn module provides support for SPI (3 pin or 4 pin) or I2C.

The MSP430F5438, MSP430F5436, and MSP430F5419 include four complete USCI modules (n = 0 to 3). The MSP430F5437, MSP430F5435, and MSP430F5418 include two complete USCI modules (n = 0 to 1).

6.9.10 TA0 (Link to User's Guide)

TA0 is a 16-bit timer/counter (Timer_A type) with five capture/compare registers. It can support multiple capture/compares, PWM outputs, and interval timing. It also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each of the capture/compare registers.

Table 6-8. TA0 Signal Connections

INPUT PIN NUMBER		DEVICE INPUT SIGNAL	MODULE INPUT SIGNAL	MODULE BLOCK	MODULE OUTPUT SIGNAL	DEVICE OUTPUT SIGNAL	OUTPUT PIN NUMBER	
PZ	PN						PZ	PN
17-P1.0	17-P1.0	TA0CLK	TACLK	Timer	NA	NA		
		ACLK	ACLK					
		SMCLK	SMCLK					
17-P1.0	17-P1.0	TA0CLK	$\overline{\text{TACLK}}$					
18-P1.1	18-P1.1	TA0.0	CC10A	CCR0	TA0	TA0.0	18-P1.1	18-P1.1
57-P8.0	60-P8.0	TA0.0	CC10B				57-P8.0	60-P8.0
		DV _{SS}	GND				ADC12 (internal) ADC12SHSx = {1}	ADC12 (internal) ADC12SHSx = {1}
		DV _{CC}	V _{CC}					
19-P1.2	19-P1.2	TA0.1	CC11A	CCR1	TA1	TA0.1	19-P1.2	19-P1.2
58-P8.1	61-P8.1	TA0.1	CC11B				58-P8.1	61-P8.1
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
20-P1.3	20-P1.3	TA0.2	CC12A	CCR2	TA2	TA0.2	20-P1.3	20-P1.3
59-P8.2	62-P8.2	TA0.2	CC12B				59-P8.2	62-P8.2
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
21-P1.4	21-P1.4	TA0.3	CC13A	CCR3	TA3	TA0.3	21-P1.4	21-P1.4
60-P8.3	63-P8.3	TA0.3	CC13B				60-P8.3	63-P8.3
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
22-P1.5	22-P1.5	TA0.4	CC14A	CCR4	TA4	TA0.4	22-P1.5	22-P1.5
61-P8.4	64-P8.4	TA0.4	CC14B				61-P8.4	64-P8.4
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					

6.9.11 TA1 [\(Link to User's Guide\)](#)

TA1 is a 16-bit timer/counter (Timer_A type) with three capture/compare registers. It can support multiple capture/comparers, PWM outputs, and interval timing. It also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each of the capture/compare registers.

Table 6-9. TA1 Signal Connections

INPUT PIN NUMBER		DEVICE INPUT SIGNAL	MODULE INPUT SIGNAL	MODULE BLOCK	MODULE OUTPUT SIGNAL	DEVICE OUTPUT SIGNAL	OUTPUT PIN NUMBER	
PZ	PN						PZ	PN
25-P2.0	25-P2.0	TA1CLK	TACLK	Timer	NA	NA		
		ACLK	ACLK					
		SMCLK	SMCLK					
25-P2.0	25-P2.0	TA1CLK	$\overline{\text{TACLK}}$					
26-P2.1	26-P2.1	TA1.0	CCI0A	CCR0	TA0	TA1.0	26-P2.1	26-P2.1
65-P8.5	65-P8.5	TA1.0	CCI0B				65-P8.5	65-P8.5
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
27-P2.2	27-P2.2	TA1.1	CCI1A	CCR1	TA1	TA1.1	27-P2.2	27-P2.2
66-P8.6	66-P8.6	TA1.1	CCI1B				66-P8.6	66-P8.6
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
28-P2.3	28-P2.3	TA1.2	CCI2A	CCR2	TA2	TA1.2	28-P2.3	28-P2.3
56-P7.3	59-P7.3	TA1.2	CCI2B				56-P7.3	59-P7.3
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					

6.9.12 TB0 [\(Link to User's Guide\)](#)

TB0 is a 16-bit timer/counter (Timer_B type) with seven capture/compare registers. It can support multiple capture/comparers, PWM outputs, and interval timing. It also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each of the capture/compare registers.

Table 6-10. TB0 Signal Connections

INPUT PIN NUMBER		DEVICE INPUT SIGNAL	MODULE INPUT SIGNAL	MODULE BLOCK	MODULE OUTPUT SIGNAL	DEVICE OUTPUT SIGNAL	OUTPUT PIN NUMBER	
PZ	PN						PZ	PN
50-P4.7	53-P4.7	TB0CLK	TBCLK	Timer	NA	NA		
		ACLK	ACLK					
		SMCLK	SMCLK					
50-P4.7	53-P4.7	TB0CLK	TBCLK					
43-P4.0	43-P4.0	TB0.0	CCI0A	CCR0	TB0	TB0.0	43-P4.0	43-P4.0
43-P4.0	43-P4.0	TB0.0	CCI0B				ADC12 (internal) ADC12SHSx = {2}	ADC12 (internal) ADC12SHSx = {2}
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
44-P4.1	44-P4.1	TB0.1	CCI1A	CCR1	TB1	TB0.1	44-P4.1	44-P4.1
44-P4.1	44-P4.1	TB0.1	CCI1B				ADC12 (internal) ADC12SHSx = {3}	ADC12 (internal) ADC12SHSx = {3}
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
45-P4.2	45-P4.2	TB0.2	CCI2A	CCR2	TB2	TB0.2	45-P4.2	45-P4.2
45-P4.2	45-P4.2	TB0.2	CCI2B					
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
46-P4.3	46-P4.3	TB0.3	CCI3A	CCR3	TB3	TB0.3	46-P4.3	46-P4.3
46-P4.3	46-P4.3	TB0.3	CCI3B					
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
47-P4.4	47-P4.4	TB0.4	CCI4A	CCR4	TB4	TB0.4	47-P4.4	47-P4.4
47-P4.4	47-P4.4	TB0.4	CCI4B					
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
48-P4.5	48-P4.5	TB0.5	CCI5A	CCR5	TB5	TB0.5	48-P4.5	48-P4.5
48-P4.5	48-P4.5	TB0.5	CCI5B					
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					
49-P4.6	52-P4.6	TB0.6	CCI6A	CCR6	TB6	TB0.6	49-P4.6	52-P4.6
		ACLK (internal)	CCI6B					
		DV _{SS}	GND					
		DV _{CC}	V _{CC}					

6.9.13 **ADC12_A** ([Link to User's Guide](#))

The ADC12_A module supports fast, 12-bit analog-to-digital conversions. The module implements a 12-bit SAR core, sample select control, reference generator and a 16 word conversion-and-control buffer. The conversion-and-control buffer allows up to 16 independent ADC samples to be converted and stored without any CPU intervention.

6.9.14 **CRC16** ([Link to User's Guide](#))

The CRC16 module produces a signature based on a sequence of entered data values and can be used for data checking purposes. The CRC16 module signature is based on the CRC-CCITT standard.

6.9.15 **Embedded Emulation Module (EEM) (L Version)** ([Link to User's Guide](#))

The Embedded Emulation Module (EEM) supports real-time in-system debugging. The L version of the EEM implemented on all devices has the following features:

- Eight hardware triggers or breakpoints on memory access
- Two hardware trigger or breakpoint on CPU register write access
- Up to ten hardware triggers can be combined to form complex triggers or breakpoints
- Two cycle counters
- Sequencer
- State storage
- Clock control on module level

6.9.16 Peripheral File Map

Table 6-11. Peripherals

MODULE NAME	BASE ADDRESS	OFFSET ADDRESS RANGE
Special Functions (see Table 6-12)	0100h	000h-01Fh
PMM (see Table 6-13)	0120h	000h-00Fh
Flash Control (see Table 6-14)	0140h	000h-00Fh
CRC16 (see Table 6-15)	0150h	000h-007h
RAM Control (see Table 6-16)	0158h	000h-001h
Watchdog (see Table 6-17)	015Ch	000h-001h
UCS (see Table 6-18)	0160h	000h-01Fh
SYS (see Table 6-19)	0180h	000h-01Fh
Port P1, P2 (see Table 6-20)	0200h	000h-01Fh
Port P3, P4 (see Table 6-21)	0220h	000h-00Bh
Port P5, P6 (see Table 6-22)	0240h	000h-00Bh
Port P7, P8 (see Table 6-23)	0260h	000h-00Bh
Port P9, P10 (see Table 6-24) ⁽¹⁾	0280h	000h-00Bh
Port P11 (see Table 6-25) ⁽¹⁾	02A0h	000h-00Ah
Port PJ (see Table 6-26)	0320h	000h-01Fh
TA0 (see Table 6-27)	0340h	000h-02Eh
TA1 (see Table 6-28)	0380h	000h-02Eh
TB0 (see Table 6-29)	03C0h	000h-02Eh
Real-Time Clock (RTC_A) (see Table 6-30)	04A0h	000h-01Bh
32-bit Hardware Multiplier (see Table 6-31)	04C0h	000h-02Fh
DMA General Control (see Table 6-32)	0500h	000h-00Fh
DMA Channel 0 (see Table 6-32)	0510h	000h-00Ah
DMA Channel 1 (see Table 6-32)	0520h	000h-00Ah
DMA Channel 2 (see Table 6-32)	0530h	000h-00Ah
USCI_A0 (see Table 6-33)	05C0h	000h-01Fh
USCI_B0 (see Table 6-34)	05E0h	000h-01Fh
USCI_A1 (see Table 6-35)	0600h	000h-01Fh
USCI_B1 (see Table 6-36)	0620h	000h-01Fh
USCI_A2 (see Table 6-37) ⁽¹⁾	0640h	000h-01Fh
USCI_B2 (see Table 6-38) ⁽¹⁾	0660h	000h-01Fh
USCI_A3 (see Table 6-39) ⁽¹⁾	0680h	000h-01Fh
USCI_B3 (see Table 6-40) ⁽¹⁾	06A0h	000h-01Fh
ADC12_A (see Table 6-41)	0700h	000h-03Eh

(1) Not available on F5437, F5435, F5418 devices

Table 6-12. Special Function Registers (Base Address: 0100h)

REGISTER DESCRIPTION	REGISTER	OFFSET
SFR interrupt enable	SFRIE1	00h
SFR interrupt flag	SFRIFG1	02h
SFR reset pin control	SFRRPCR	04h

Table 6-13. PMM Registers (Base Address: 0120h)

REGISTER DESCRIPTION	REGISTER	OFFSET
PMM Control 0	PMMCTL0	00h
PMM control 1	PMMCTL1	02h
SVS high side control	SVSMHCTL	04h
SVS low side control	SVSMLCTL	06h
PMM interrupt flags	PMMIFG	0Ch
PMM interrupt enable	PMMIE	0Eh

Table 6-14. Flash Control Registers (Base Address: 0140h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Flash control 1	FCTL1	00h
Flash control 3	FCTL3	04h
Flash control 4	FCTL4	06h

Table 6-15. CRC16 Registers (Base Address: 0150h)

REGISTER DESCRIPTION	REGISTER	OFFSET
CRC data input	CRC16DI	00h
CRC result	CRC16NIRE	04h

Table 6-16. RAM Control Registers (Base Address: 0158h)

REGISTER DESCRIPTION	REGISTER	OFFSET
RAM control 0	RCCTL0	00h

Table 6-17. Watchdog Registers (Base Address: 015Ch)

REGISTER DESCRIPTION	REGISTER	OFFSET
Watchdog timer control	WDTCTL	00h

Table 6-18. UCS Registers (Base Address: 0160h)

REGISTER DESCRIPTION	REGISTER	OFFSET
UCS control 0	UCSCTL0	00h
UCS control 1	UCSCTL1	02h
UCS control 2	UCSCTL2	04h
UCS control 3	UCSCTL3	06h
UCS control 4	UCSCTL4	08h
UCS control 5	UCSCTL5	0Ah
UCS control 6	UCSCTL6	0Ch
UCS control 7	UCSCTL7	0Eh
UCS control 8	UCSCTL8	10h

Table 6-19. SYS Registers (Base Address: 0180h)

REGISTER DESCRIPTION	REGISTER	OFFSET
System control	SYSCTL	00h
Bootstrap loader configuration area	SYSBSLC	02h
JTAG mailbox control	SYSJMBC	06h
JTAG mailbox input 0	SYSJMBI0	08h
JTAG mailbox input 1	SYSJMBI1	0Ah
JTAG mailbox output 0	SYSJMBO0	0Ch
JTAG mailbox output 1	SYSJMBO1	0Eh
Bus Error vector generator	SYSBERRIV	18h
User NMI vector generator	SYSUNIV	1Ah
System NMI vector generator	SYSSNIV	1Ch
Reset vector generator	SYSRSTIV	1Eh

Table 6-20. Port P1, P2 Registers (Base Address: 0200h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P1 input	P1IN	00h
Port P1 output	P1OUT	02h
Port P1 direction	P1DIR	04h
Port P1 pullup/pulldown enable	P1REN	06h
Port P1 drive strength	P1DS	08h
Port P1 selection	P1SEL	0Ah
Port P1 interrupt vector word	P1IV	0Eh
Port P1 interrupt edge select	P1IES	18h
Port P1 interrupt enable	P1IE	1Ah
Port P1 interrupt flag	P1IFG	1Ch
Port P2 input	P2IN	01h
Port P2 output	P2OUT	03h
Port P2 direction	P2DIR	05h
Port P2 pullup/pulldown enable	P2REN	07h
Port P2 drive strength	P2DS	09h
Port P2 selection	P2SEL	0Bh
Port P2 interrupt vector word	P2IV	1Eh
Port P2 interrupt edge select	P2IES	19h
Port P2 interrupt enable	P2IE	1Bh
Port P2 interrupt flag	P2IFG	1Dh

Table 6-21. Port P3, P4 Registers (Base Address: 0220h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P3 input	P3IN	00h
Port P3 output	P3OUT	02h
Port P3 direction	P3DIR	04h
Port P3 pullup/pulldown enable	P3REN	06h
Port P3 drive strength	P3DS	08h
Port P3 selection	P3SEL	0Ah
Port P4 input	P4IN	01h
Port P4 output	P4OUT	03h
Port P4 direction	P4DIR	05h
Port P4 pullup/pulldown enable	P4REN	07h
Port P4 drive strength	P4DS	09h
Port P4 selection	P4SEL	0Bh

Table 6-22. Port P5, P6 Registers (Base Address: 0240h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P5 input	P5IN	00h
Port P5 output	P5OUT	02h
Port P5 direction	P5DIR	04h
Port P5 pullup/pulldown enable	P5REN	06h
Port P5 drive strength	P5DS	08h
Port P5 selection	P5SEL	0Ah
Port P6 input	P6IN	01h
Port P6 output	P6OUT	03h
Port P6 direction	P6DIR	05h
Port P6 pullup/pulldown enable	P6REN	07h
Port P6 drive strength	P6DS	09h
Port P6 selection	P6SEL	0Bh

Table 6-23. Port P7, P8 Registers (Base Address: 0260h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P7 input	P7IN	00h
Port P7 output	P7OUT	02h
Port P7 direction	P7DIR	04h
Port P7 pullup/pulldown enable	P7REN	06h
Port P7 drive strength	P7DS	08h
Port P7 selection	P7SEL	0Ah
Port P8 input	P8IN	01h
Port P8 output	P8OUT	03h
Port P8 direction	P8DIR	05h
Port P8 pullup/pulldown enable	P8REN	07h
Port P8 drive strength	P8DS	09h
Port P8 selection	P8SEL	0Bh

Table 6-24. Port P9, P10 Registers (Base Address: 0280h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P9 input	P9IN	00h
Port P9 output	P9OUT	02h
Port P9 direction	P9DIR	04h
Port P9 pullup/pulldown enable	P9REN	06h
Port P9 drive strength	P9DS	08h
Port P9 selection	P9SEL	0Ah
Port P10 input	P10IN	01h
Port P10 output	P10OUT	03h
Port P10 direction	P10DIR	05h
Port P10 pullup/pulldown enable	P10REN	07h
Port P10 drive strength	P10DS	09h
Port P10 selection	P10SEL	0Bh

Table 6-25. Port P11 Registers (Base Address: 02A0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P11 input	P11IN	00h
Port P11 output	P11OUT	02h
Port P11 direction	P11DIR	04h
Port P11 pullup/pulldown enable	P11REN	06h
Port P11 drive strength	P11DS	08h
Port P11 selection	P11SEL	0Ah

Table 6-26. Port J Registers (Base Address: 0320h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port PJ input	PJIN	00h
Port PJ output	PJOUT	02h
Port PJ direction	PJDIR	04h
Port PJ pullup/pulldown enable	PJREN	06h
Port PJ drive strength	PJDS	08h

Table 6-27. TA0 Registers (Base Address: 0340h)

REGISTER DESCRIPTION	REGISTER	OFFSET
TA0 control	TA0CTL	00h
Capture/compare control 0	TA0CCTL0	02h
Capture/compare control 1	TA0CCTL1	04h
Capture/compare control 2	TA0CCTL2	06h
Capture/compare control 3	TA0CCTL3	08h
Capture/compare control 4	TA0CCTL4	0Ah
TA0 counter register	TA0R	10h
Capture/compare register 0	TA0CCR0	12h
Capture/compare register 1	TA0CCR1	14h
Capture/compare register 2	TA0CCR2	16h
Capture/compare register 3	TA0CCR3	18h
Capture/compare register 4	TA0CCR4	1Ah
TA0 expansion register 0	TA0EX0	20h
TA0 interrupt vector	TA0IV	2Eh

Table 6-28. TA1 Registers (Base Address: 0380h)

REGISTER DESCRIPTION	REGISTER	OFFSET
TA1 control	TA1CTL	00h
Capture/compare control 0	TA1CCTL0	02h
Capture/compare control 1	TA1CCTL1	04h
Capture/compare control 2	TA1CCTL2	06h
TA1 counter register	TA1R	10h
Capture/compare register 0	TA1CCR0	12h
Capture/compare register 1	TA1CCR1	14h
Capture/compare register 2	TA1CCR2	16h
TA1 expansion register 0	TA1EX0	20h
TA1 interrupt vector	TA1IV	2Eh

Table 6-29. TB0 Registers (Base Address: 03C0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
TB0 control	TB0CTL	00h
Capture/compare control 0	TB0CCTL0	02h
Capture/compare control 1	TB0CCTL1	04h
Capture/compare control 2	TB0CCTL2	06h
Capture/compare control 3	TB0CCTL3	08h
Capture/compare control 4	TB0CCTL4	0Ah
Capture/compare control 5	TB0CCTL5	0Ch
Capture/compare control 6	TB0CCTL6	0Eh
TB0 register	TB0R	10h
Capture/compare register 0	TB0CCR0	12h
Capture/compare register 1	TB0CCR1	14h
Capture/compare register 2	TB0CCR2	16h
Capture/compare register 3	TB0CCR3	18h
Capture/compare register 4	TB0CCR4	1Ah
Capture/compare register 5	TB0CCR5	1Ch
Capture/compare register 6	TB0CCR6	1Eh
TB0 expansion register 0	TB0EX0	20h
TB0 interrupt vector	TB0IV	2Eh

Table 6-30. Real-Time Clock Registers (Base Address: 04A0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
RTC control 0	RTCCTL0	00h
RTC control 1	RTCCTL1	01h
RTC control 2	RTCCTL2	02h
RTC control 3	RTCCTL3	03h
RTC prescaler 0 control	RTCPS0CTL	08h
RTC prescaler 1 control	RTCPS1CTL	0Ah
RTC prescaler 0	RTCPS0	0Ch
RTC prescaler 1	RTCPS1	0Dh
RTC interrupt vector word	RTCIV	0Eh
RTC seconds/counter register 1	RTCSEC/RTCNT1	10h
RTC minutes/counter register 2	RTCMIN/RTCNT2	11h
RTC hours/counter register 3	RTCHOUR/RTCNT3	12h
RTC day of week/counter register 4	RTCADOW/RTCNT4	13h
RTC days	RTCDAY	14h
RTC month	RTCMON	15h
RTC year low	RTCYEARL	16h
RTC year high	RTCYEARH	17h
RTC alarm minutes	RTCAMIN	18h
RTC alarm hours	RTCAHOUR	19h
RTC alarm day of week	RTCADOW	1Ah
RTC alarm days	RTCADAY	1Bh

Table 6-31. 32-bit Hardware Multiplier Registers (Base Address: 04C0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
16-bit operand 1 – multiply	MPY	00h
16-bit operand 1 – signed multiply	MPYS	02h
16-bit operand 1 – multiply accumulate	MAC	04h
16-bit operand 1 – signed multiply accumulate	MACS	06h
16-bit operand 2	OP2	08h
16 × 16 result low word	RESLO	0Ah
16 × 16 result high word	RESHI	0Ch
16 × 16 sum extension register	SUMEXT	0Eh
32-bit operand 1 – multiply low word	MPY32L	10h
32-bit operand 1 – multiply high word	MPY32H	12h
32-bit operand 1 – signed multiply low word	MPYS32L	14h
32-bit operand 1 – signed multiply high word	MPYS32H	16h
32-bit operand 1 – multiply accumulate low word	MAC32L	18h
32-bit operand 1 – multiply accumulate high word	MAC32H	1Ah
32-bit operand 1 – signed multiply accumulate low word	MACS32L	1Ch
32-bit operand 1 – signed multiply accumulate high word	MACS32H	1Eh
32-bit operand 2 – low word	OP2L	20h
32-bit operand 2 – high word	OP2H	22h
32 × 32 result 0 – least significant word	RES0	24h
32 × 32 result 1	RES1	26h
32 × 32 result 2	RES2	28h
32 × 32 result 3 – most significant word	RES3	2Ah
MPY32 control register 0	MPY32CTL0	2Ch

Table 6-32. DMA Registers (Base Address DMA General Control: 0500h, DMA Channel 0: 0510h, DMA Channel 1: 0520h, DMA Channel 2: 0530h)

REGISTER DESCRIPTION	REGISTER	OFFSET
DMA channel 0 control	DMA0CTL	00h
DMA channel 0 source address low	DMA0SAL	02h
DMA channel 0 source address high	DMA0SAH	04h
DMA channel 0 destination address low	DMA0DAL	06h
DMA channel 0 destination address high	DMA0DAH	08h
DMA channel 0 transfer size	DMA0SZ	0Ah
DMA channel 1 control	DMA1CTL	00h
DMA channel 1 source address low	DMA1SAL	02h
DMA channel 1 source address high	DMA1SAH	04h
DMA channel 1 destination address low	DMA1DAL	06h
DMA channel 1 destination address high	DMA1DAH	08h
DMA channel 1 transfer size	DMA1SZ	0Ah
DMA channel 2 control	DMA2CTL	00h
DMA channel 2 source address low	DMA2SAL	02h
DMA channel 2 source address high	DMA2SAH	04h
DMA channel 2 destination address low	DMA2DAL	06h
DMA channel 2 destination address high	DMA2DAH	08h
DMA channel 2 transfer size	DMA2SZ	0Ah
DMA module control 0	DMACTL0	00h
DMA module control 1	DMACTL1	02h
DMA module control 2	DMACTL2	04h
DMA module control 3	DMACTL3	06h
DMA module control 4	DMACTL4	08h
DMA interrupt vector	DMAIV	0Eh

Table 6-33. USCI_A0 Registers (Base Address: 05C0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI control 1	UCA0CTL1	00h
USCI control 0	UCA0CTL0	01h
USCI baud rate 0	UCA0BR0	06h
USCI baud rate 1	UCA0BR1	07h
USCI modulation control	UCA0MCTL	08h
USCI status	UCA0STAT	0Ah
USCI receive buffer	UCA0RXBUF	0Ch
USCI transmit buffer	UCA0TXBUF	0Eh
USCI LIN control	UCA0ABCTL	10h
USCI IrDA transmit control	UCA0IRTCTL	12h
USCI IrDA receive control	UCA0IRRCTL	13h
USCI interrupt enable	UCA0IE	1Ch
USCI interrupt flags	UCA0IFG	1Dh
USCI interrupt vector word	UCA0IV	1Eh

Table 6-34. USCI_B0 Registers (Base Address: 05E0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI synchronous control 1	UCB0CTL1	00h
USCI synchronous control 0	UCB0CTL0	01h
USCI synchronous bit rate 0	UCB0BR0	06h
USCI synchronous bit rate 1	UCB0BR1	07h
USCI synchronous status	UCB0STAT	0Ah
USCI synchronous receive buffer	UCB0RXBUF	0Ch
USCI synchronous transmit buffer	UCB0TXBUF	0Eh
USCI I2C own address	UCB0I2COA	10h
USCI I2C slave address	UCB0I2CSA	12h
USCI interrupt enable	UCB0IE	1Ch
USCI interrupt flags	UCB0IFG	1Dh
USCI interrupt vector word	UCB0IV	1Eh

Table 6-35. USCI_A1 Registers (Base Address: 0600h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI control 1	UCA1CTL1	00h
USCI control 0	UCA1CTL0	01h
USCI baud rate 0	UCA1BR0	06h
USCI baud rate 1	UCA1BR1	07h
USCI modulation control	UCA1MCTL	08h
USCI status	UCA1STAT	0Ah
USCI receive buffer	UCA1RXBUF	0Ch
USCI transmit buffer	UCA1TXBUF	0Eh
USCI LIN control	UCA1ABCTL	10h
USCI IrDA transmit control	UCA1IRTCTL	12h
USCI IrDA receive control	UCA1IRRCTL	13h
USCI interrupt enable	UCA1IE	1Ch
USCI interrupt flags	UCA1IFG	1Dh
USCI interrupt vector word	UCA1IV	1Eh

Table 6-36. USCI_B1 Registers (Base Address: 0620h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI synchronous control 1	UCB1CTL1	00h
USCI synchronous control 0	UCB1CTL0	01h
USCI synchronous bit rate 0	UCB1BR0	06h
USCI synchronous bit rate 1	UCB1BR1	07h
USCI synchronous status	UCB1STAT	0Ah
USCI synchronous receive buffer	UCB1RXBUF	0Ch
USCI synchronous transmit buffer	UCB1TXBUF	0Eh
USCI I2C own address	UCB1I2COA	10h
USCI I2C slave address	UCB1I2CSA	12h
USCI interrupt enable	UCB1IE	1Ch
USCI interrupt flags	UCB1IFG	1Dh
USCI interrupt vector word	UCB1IV	1Eh

Table 6-37. USCI_A2 Registers (Base Address: 0640h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI control 1	UCA2CTL1	00h
USCI control 0	UCA2CTL0	01h
USCI baud rate 0	UCA2BR0	06h
USCI baud rate 1	UCA2BR1	07h
USCI modulation control	UCA2MCTL	08h
USCI status	UCA2STAT	0Ah
USCI receive buffer	UCA2RXBUF	0Ch
USCI transmit buffer	UCA2TXBUF	0Eh
USCI LIN control	UCA2ABCTL	10h
USCI IrDA transmit control	UCA2IRTCTL	12h
USCI IrDA receive control	UCA2IRRCTL	13h
USCI interrupt enable	UCA2IE	1Ch
USCI interrupt flags	UCA2IFG	1Dh
USCI interrupt vector word	UCA2IV	1Eh

Table 6-38. USCI_B2 Registers (Base Address: 0660h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI synchronous control 1	UCB2CTL1	00h
USCI synchronous control 0	UCB2CTL0	01h
USCI synchronous bit rate 0	UCB2BR0	06h
USCI synchronous bit rate 1	UCB2BR1	07h
USCI synchronous status	UCB2STAT	0Ah
USCI synchronous receive buffer	UCB2RXBUF	0Ch
USCI synchronous transmit buffer	UCB2TXBUF	0Eh
USCI I2C own address	UCB2I2COA	10h
USCI I2C slave address	UCB2I2CSA	12h
USCI interrupt enable	UCB2IE	1Ch
USCI interrupt flags	UCB2IFG	1Dh
USCI interrupt vector word	UCB2IV	1Eh

Table 6-39. USCI_A3 Registers (Base Address: 0680h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI control 1	UCA3CTL1	00h
USCI control 0	UCA3CTL0	01h
USCI baud rate 0	UCA3BR0	06h
USCI baud rate 1	UCA3BR1	07h
USCI modulation control	UCA3MCTL	08h
USCI status	UCA3STAT	0Ah
USCI receive buffer	UCA3RXBUF	0Ch
USCI transmit buffer	UCA3TXBUF	0Eh
USCI LIN control	UCA3ABCTL	10h
USCI IrDA transmit control	UCA3IRTCTL	12h
USCI IrDA receive control	UCA3IRRCTL	13h
USCI interrupt enable	UCA3IE	1Ch
USCI interrupt flags	UCA3IFG	1Dh
USCI interrupt vector word	UCA3IV	1Eh

Table 6-40. USCI_B3 Registers (Base Address: 06A0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI synchronous control 1	UCB3CTL1	00h
USCI synchronous control 0	UCB3CTL0	01h
USCI synchronous bit rate 0	UCB3BR0	06h
USCI synchronous bit rate 1	UCB3BR1	07h
USCI synchronous status	UCB3STAT	0Ah
USCI synchronous receive buffer	UCB3RXBUF	0Ch
USCI synchronous transmit buffer	UCB3TXBUF	0Eh
USCI I2C own address	UCB3I2COA	10h
USCI I2C slave address	UCB3I2CSA	12h
USCI interrupt enable	UCB3IE	1Ch
USCI interrupt flags	UCB3IFG	1Dh
USCI interrupt vector word	UCB3IV	1Eh

Table 6-41. ADC12_A Registers (Base Address: 0700h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Control register 0	ADC12CTL0	00h
Control register 1	ADC12CTL1	02h
Control register 2	ADC12CTL2	04h
Interrupt-flag register	ADC12IFG	0Ah
Interrupt-enable register	ADC12IE	0Ch
Interrupt-vector-word register	ADC12IV	0Eh
ADC memory-control register 0	ADC12MCTL0	10h
ADC memory-control register 1	ADC12MCTL1	11h
ADC memory-control register 2	ADC12MCTL2	12h
ADC memory-control register 3	ADC12MCTL3	13h
ADC memory-control register 4	ADC12MCTL4	14h
ADC memory-control register 5	ADC12MCTL5	15h
ADC memory-control register 6	ADC12MCTL6	16h
ADC memory-control register 7	ADC12MCTL7	17h
ADC memory-control register 8	ADC12MCTL8	18h
ADC memory-control register 9	ADC12MCTL9	19h
ADC memory-control register 10	ADC12MCTL10	1Ah
ADC memory-control register 11	ADC12MCTL11	1Bh
ADC memory-control register 12	ADC12MCTL12	1Ch
ADC memory-control register 13	ADC12MCTL13	1Dh
ADC memory-control register 14	ADC12MCTL14	1Eh
ADC memory-control register 15	ADC12MCTL15	1Fh
Conversion memory 0	ADC12MEM0	20h
Conversion memory 1	ADC12MEM1	22h
Conversion memory 2	ADC12MEM2	24h
Conversion memory 3	ADC12MEM3	26h
Conversion memory 4	ADC12MEM4	28h
Conversion memory 5	ADC12MEM5	2Ah
Conversion memory 6	ADC12MEM6	2Ch
Conversion memory 7	ADC12MEM7	2Eh
Conversion memory 8	ADC12MEM8	30h
Conversion memory 9	ADC12MEM9	32h
Conversion memory 10	ADC12MEM10	34h
Conversion memory 11	ADC12MEM11	36h
Conversion memory 12	ADC12MEM12	38h
Conversion memory 13	ADC12MEM13	3Ah
Conversion memory 14	ADC12MEM14	3Ch
Conversion memory 15	ADC12MEM15	3Eh

6.10 Input/Output Schematics

6.10.1 Port P1, P1.0 to P1.7, Input/Output With Schmitt Trigger

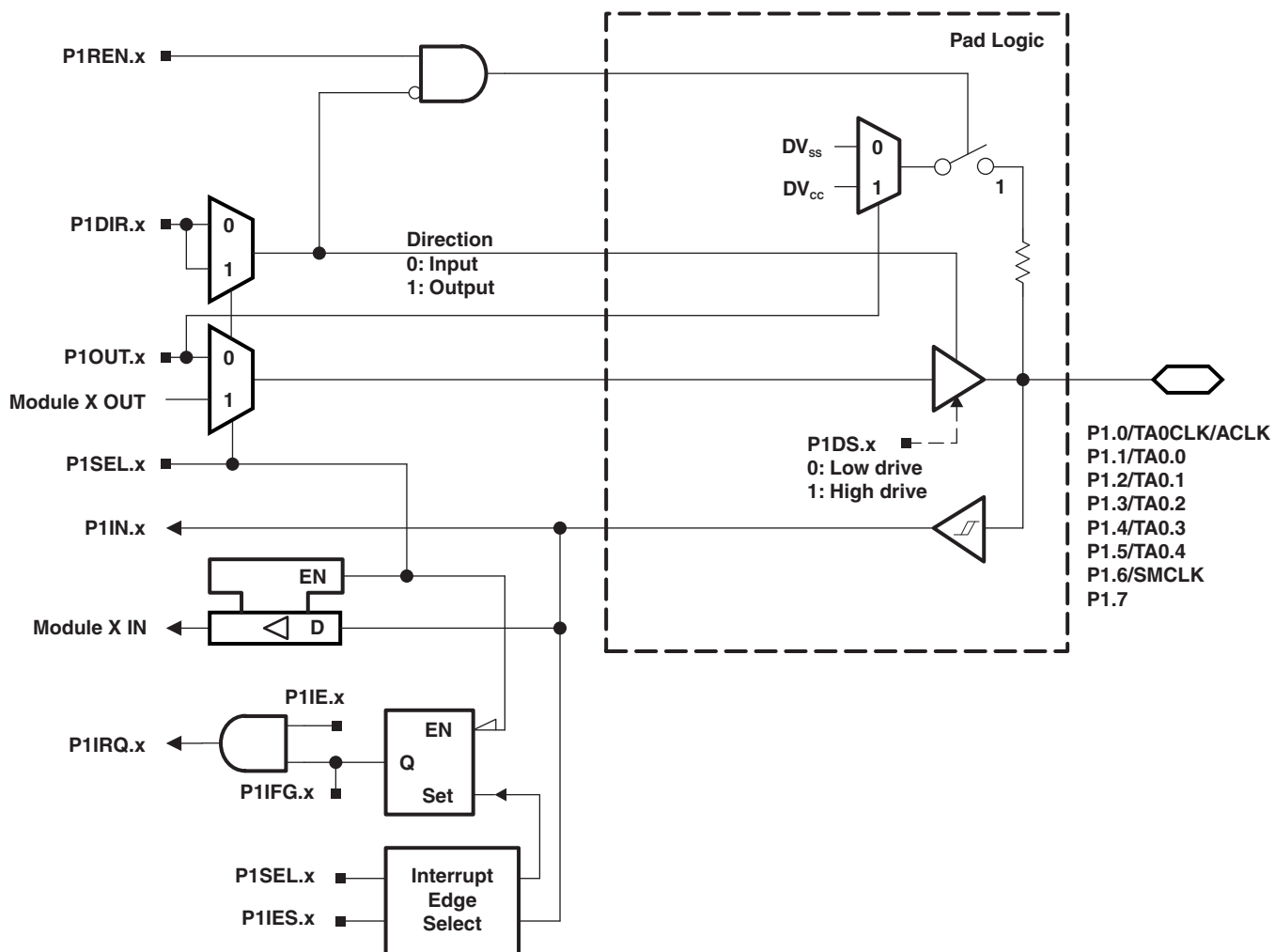


Table 6-42. Port P1 (P1.0 to P1.7) Pin Functions

PIN NAME (P1.x)	x	FUNCTION	CONTROL BITS/SIGNALS	
			P1DIR.x	P1SEL.x
P1.0/TA0CLK/ACLK	0	P1.0 (I/O)	I: 0; O: 1	0
		TA0.TA0CLK	0	1
		ACLK	1	1
P1.1/TA0.0	1	P1.1 (I/O)	I: 0; O: 1	0
		TA0.CCI0A	0	1
		TA0.0	1	1
P1.2/TA0.1	2	P1.2 (I/O)	I: 0; O: 1	0
		TA0.CCI1A	0	1
		TA0.1	1	1
P1.3/TA0.2	3	P1.3 (I/O)	I: 0; O: 1	0
		TA0.CCI2A	0	1
		TA0.2	1	1
P1.4/TA0.3	4	P1.4 (I/O)	I: 0; O: 1	0
		TA0.CCI3A	0	1
		TA0.3	1	1
P1.5/TA0.4	5	P1.5 (I/O)	I: 0; O: 1	0
		TA0.CCI4A	0	1
		TA0.4	1	1
P1.6/SMCLK	6	P1.6 (I/O)	I: 0; O: 1	0
		SMCLK	1	1
P1.7	7	P1.7 (I/O)	I: 0; O: 1	0

6.10.2 Port P2, P2.0 to P2.7, Input/Output With Schmitt Trigger

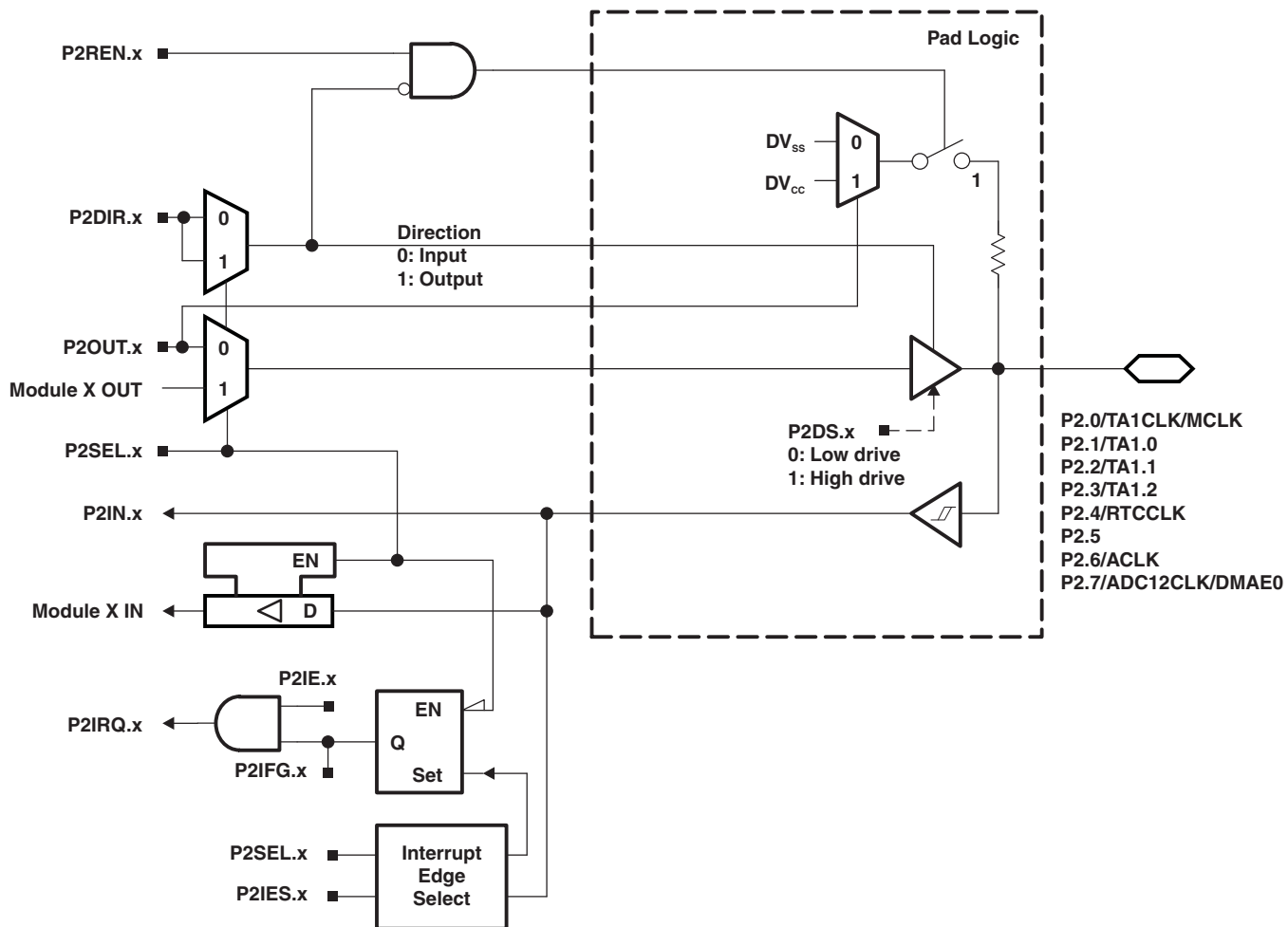


Table 6-43. Port P2 (P2.0 to P2.7) Pin Functions

PIN NAME (P2.x)	x	FUNCTION	CONTROL BITS/SIGNALS	
			P2DIR.x	P2SEL.x
P2.0/TA1CLK/MCLK	0	P2.0 (I/O)	I: 0; O: 1	0
		TA1CLK	0	1
		MCLK	1	1
P2.1/TA1.0	1	P2.1 (I/O)	I: 0; O: 1	0
		TA1.CCI0A	0	1
		TA1.0	1	1
P2.2/TA1.1	2	P2.2 (I/O)	I: 0; O: 1	0
		TA1.CCI1A	0	1
		TA1.1	1	1
P2.3/TA1.2	3	P2.3 (I/O)	I: 0; O: 1	0
		TA1.CCI2A	0	1
		TA1.2	1	1
P2.4/RTCCLK	4	P2.4 (I/O)	I: 0; O: 1	0
		RTCCLK	1	1
P2.5	5	P2.5 (I/O)	I: 0; O: 1	0
P2.6/ACLK	6	P2.6 (I/O)	I: 0; O: 1	0
		ACLK	1	1
P2.7/ADC12CLK/DMAE0	7	P2.7 (I/O)	I: 0; O: 1	0
		DMAE0	0	1
		ADC12CLK	1	1

6.10.3 Port P3, P3.0 to P3.7, Input/Output With Schmitt Trigger

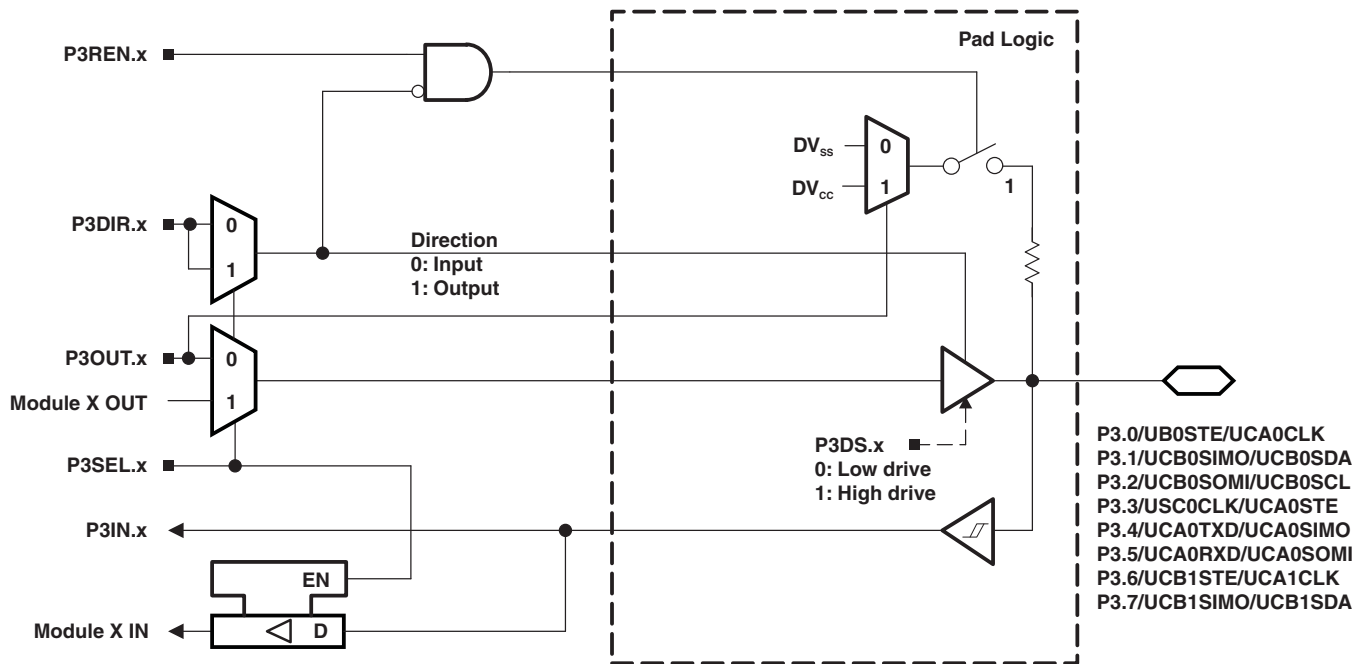


Table 6-44. Port P3 (P3.0 to P3.7) Pin Functions

PIN NAME (P3.x)	x	FUNCTION	CONTROL BITS/SIGNALS ⁽¹⁾	
			P3DIR.x	P3SEL.x
P3.0/UCB0STE/UCA0CLK	0	P3.0 (I/O)	I: 0; O: 1	0
		UCB0STE/UCA0CLK ^{(2) (3)}	X	1
P3.1/UCB0SIMO/UCB0SDA	1	P3.1 (I/O)	I: 0; O: 1	0
		UCB0SIMO/UCB0SDA ^{(2) (4)}	X	1
P3.2/UCB0SOMI/UCB0SCL	2	P3.2 (I/O)	I: 0; O: 1	0
		UCB0SOMI/UCB0SCL ^{(2) (4)}	X	1
P3.3/UCB0CLK/UCA0STE	3	P3.3 (I/O)	I: 0; O: 1	0
		UCB0CLK/UCA0STE ⁽²⁾	X	1
P3.4/UCA0TXD/UCA0SIMO	4	P3.4 (I/O)	I: 0; O: 1	0
		UCA0TXD/UCA0SIMO ⁽²⁾	X	1
P3.5/UCA0RXD/UCA0SOMI	5	P3.5 (I/O)	I: 0; O: 1	0
		UCA0RXD/UCA0SOMI ⁽²⁾	X	1
P3.6/UCB1STE/UCA1CLK	6	P3.6 (I/O)	I: 0; O: 1	0
		UCB1STE/UCA1CLK ^{(2) (5)}	X	1
P3.7/UCB1SIMO/UCB1SDA	7	P3.7 (I/O)	I: 0; O: 1	0
		UCB1SIMO/UCB1SDA ^{(2) (4)}	X	1

(1) X = Don't care

(2) The pin direction is controlled by the USCI module.

(3) UCA0CLK function takes precedence over UCB0STE function. If the pin is required as UCA0CLK input or output, USCI B0 is forced to 3-wire SPI mode if 4-wire SPI mode is selected.

(4) If the I2C functionality is selected, the output drives only the logical 0 to V_{SS} level.

(5) UCA1CLK function takes precedence over UCB1STE function. If the pin is required as UCA1CLK input or output, USCI B1 is forced to 3-wire SPI mode if 4-wire SPI mode is selected.

6.10.4 Port P4, P4.0 to P4.7, Input/Output With Schmitt Trigger

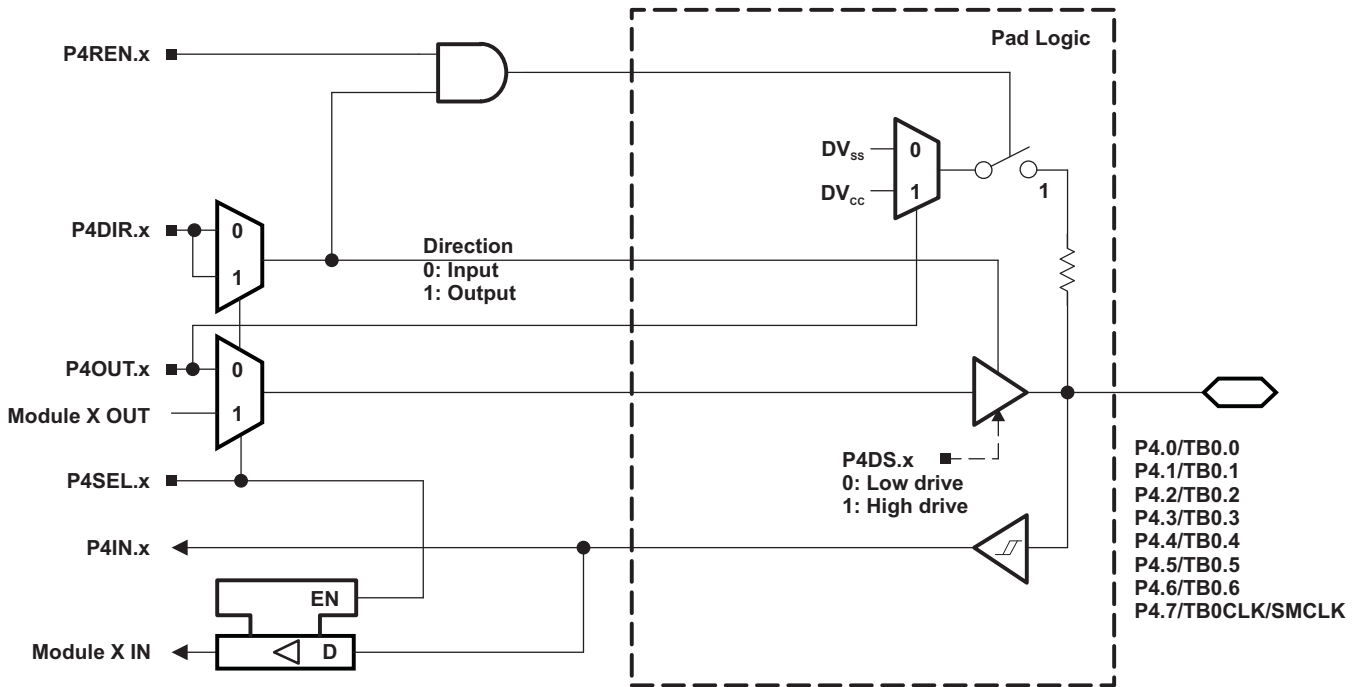


Table 6-45. Port P4 (P4.0 to P4.7) Pin Functions

PIN NAME (P4.x)	x	FUNCTION	CONTROL BITS/SIGNALS	
			P4DIR.x	P4SEL.x
P4.0/TB0.0	0	4.0 (I/O)	I: 0; O: 1	0
		TB0.CCI0A and TB0.CCI0B	0	1
		TB0.0 ⁽¹⁾	1	1
P4.1/TB0.1	1	4.1 (I/O)	I: 0; O: 1	0
		TB0.CCI1A and TB0.CCI1B	0	1
		TB0.1 ⁽¹⁾	1	1
P4.2/TB0.2	2	4.2 (I/O)	I: 0; O: 1	0
		TB0.CCI2A and TB0.CCI2B	0	1
		TB0.2 ⁽¹⁾	1	1
P4.3/TB0.3	3	4.3 (I/O)	I: 0; O: 1	0
		TB0.CCI3A and TB0.CCI3B	0	1
		TB0.3 ⁽¹⁾	1	1
P4.4/TB0.5	4	4.4 (I/O)	I: 0; O: 1	0
		TB0.CCI4A and TB0.CCI4B	0	1
		TB0.4 ⁽¹⁾	1	1
P4.5/TB0.5	5	4.5 (I/O)	I: 0; O: 1	0
		TB0.CCI5A and TB0.CCI5B	0	1
		TB0.5 ⁽¹⁾	1	1
P4.6/TB0.6	6	4.6 (I/O)	I: 0; O: 1	0
		TB0.CCI6A and TB0.CCI6B	0	1
		TB0.6 ⁽¹⁾	1	1
P4.7/TB0CLK/SMCLK	7	4.7 (I/O)	I: 0; O: 1	0
		TB0CLK	0	1
		SMCLK	1	1

(1) Setting TBOUTH causes all Timer_B configured outputs to be set to high impedance.

6.10.5 Port P5, P5.0 and P5.1, Input/Output With Schmitt Trigger

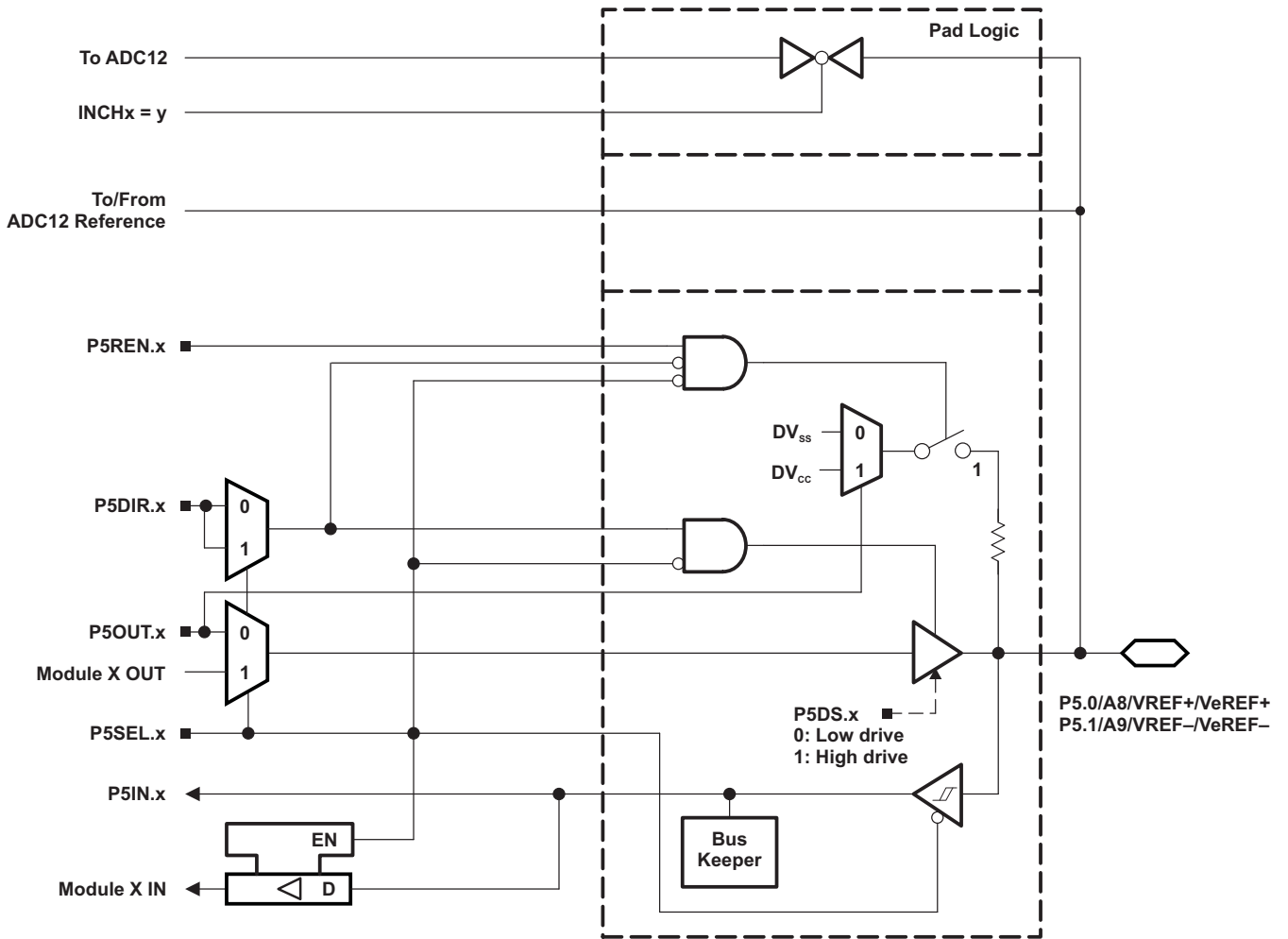
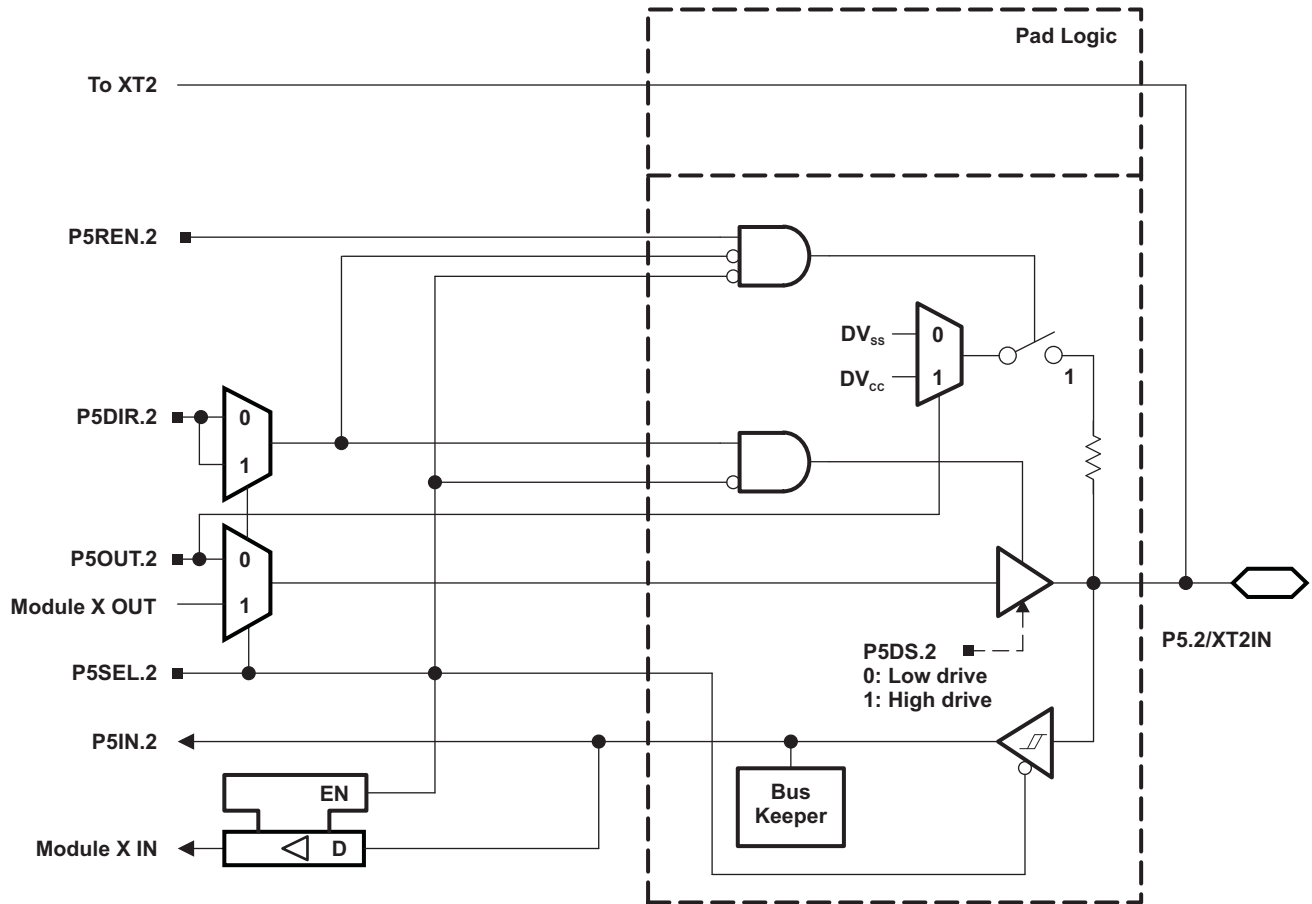


Table 6-46. Port P5 (P5.0 and P5.1) Pin Functions

PIN NAME (P5.x)	x	FUNCTION	CONTROL BITS/SIGNALS ⁽¹⁾		
			P5DIR.x	P5SEL.x	REFOUT
P5.0/A8/VREF+/VeREF+	0	P5.0 (I/O) ⁽²⁾	I: 0; O: 1	0	X
		VeREF+ ⁽³⁾	X	1	0
		VREF+ ⁽⁴⁾	X	1	1
		A8 ⁽⁵⁾	X	1	0
P5.1/A9/VREF–/VeREF–	1	P5.1 (I/O) ⁽²⁾	I: 0; O: 1	0	X
		VeREF– ⁽⁶⁾	X	1	0
		VREF– ⁽⁷⁾	X	1	1
		A9 ⁽⁸⁾	X	1	0

- (1) X = Don't care
- (2) Default condition
- (3) Setting the P5SEL.0 bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals. An external voltage can be applied to VeREF+ and used as the reference for the ADC12_A.
- (4) Setting the P5SEL.0 bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals. The ADC12_A, VREF+ reference is available at the pin.
- (5) When not using an external reference applied to VeREF+ or not outputting the internal reference to VREF+, A8 may be used as an external ADC channel. Setting the P5SEL.0 bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals.
- (6) Setting the P5SEL.1 bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals. An external voltage can be applied to VeREF– and used as the reference for the ADC12_A.
- (7) Setting the P5SEL.1 bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals. The ADC12_A, VREF– reference is available at the pin.
- (8) When not using an external reference applied to VeREF+ or not outputting the internal reference to VREF+, A9 may be used as an external ADC channel. Setting the P5SEL.1 bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals.

6.10.6 Port P5, P5.2, Input/Output With Schmitt Trigger



6.10.7 Port P5, P5.3, Input/Output With Schmitt Trigger

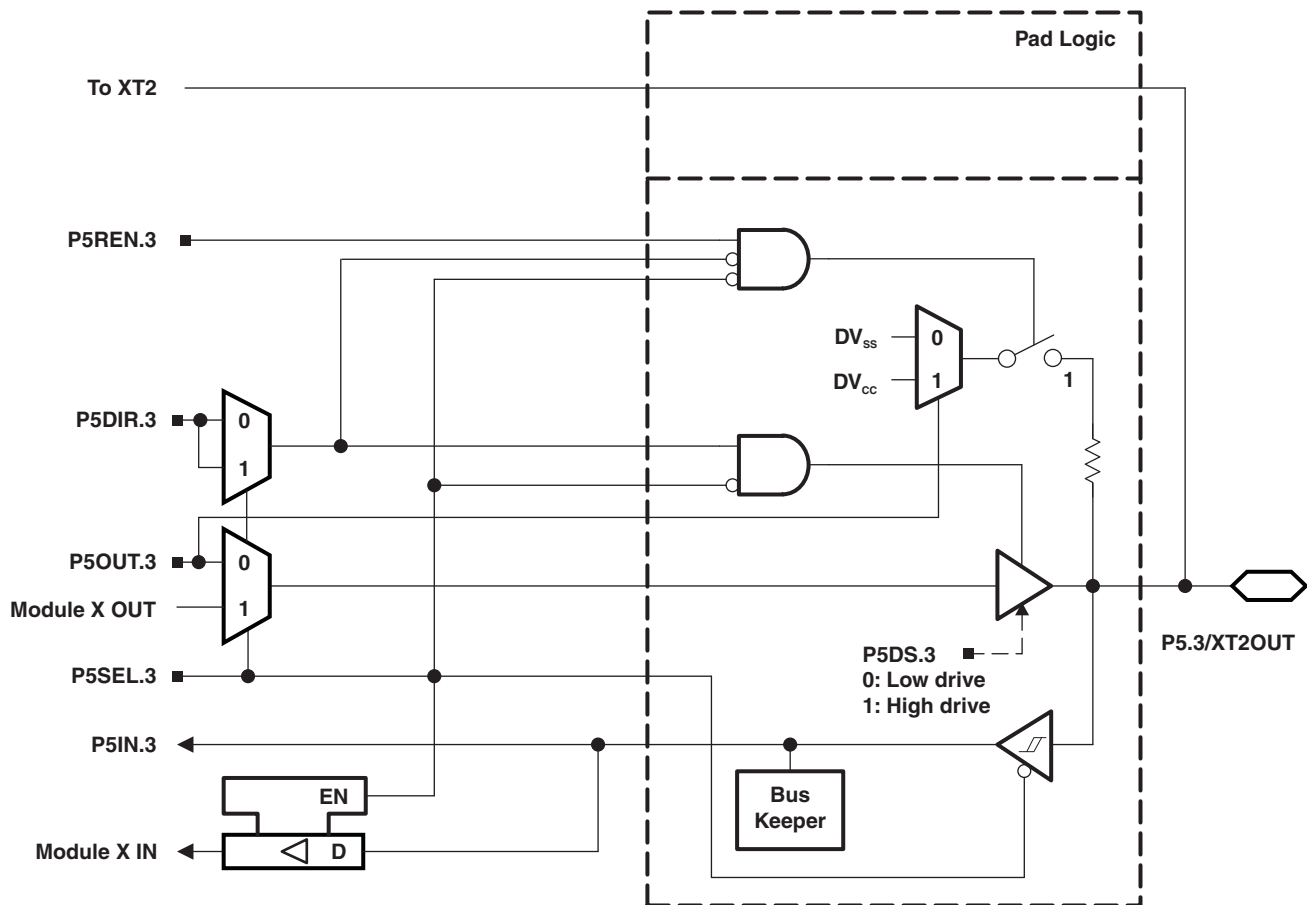


Table 6-47. Port P5 (P5.2) Pin Functions

PIN NAME (P5.x)	x	FUNCTION	CONTROL BITS/SIGNALS ⁽¹⁾			
			P5DIR.x	P5SEL.2	P5SEL.3	XT2BYPASS
P5.2/XT2IN	2	P5.2 (I/O)	I: 0; O: 1	0	X	X
		XT2IN crystal mode ⁽²⁾	X	1	X	0
		XT2IN bypass mode ⁽²⁾	X	1	X	1
P5.3/XT2OUT	3	P5.3 (I/O)	I: 0; O: 1	0	X	X
		XT2OUT crystal mode ⁽³⁾	X	1	X	0
		P5.3 (I/O) ⁽³⁾	X	1	X	1

- (1) X = Don't care
(2) Setting P5SEL.2 causes the general-purpose I/O to be disabled. Pending the setting of XT2BYPASS, P5.2 is configured for crystal mode or bypass mode.
(3) Setting P5SEL.2 causes the general-purpose I/O to be disabled in crystal mode. When using bypass mode, P5.3 can be used as general-purpose I/O.

6.10.8 Port P5, P5.4 to P5.7, Input/Output With Schmitt Trigger

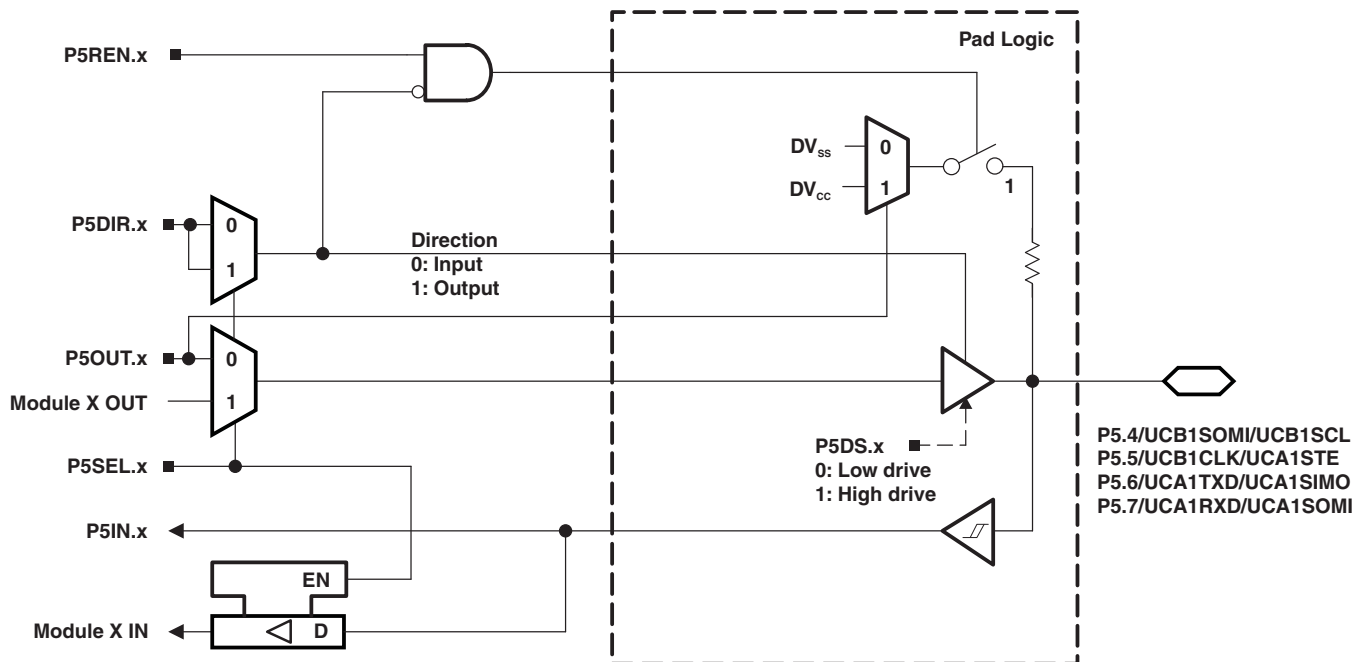


Table 6-48. Port P5 (P5.4 to P5.7) Pin Functions

PIN NAME (P5.x)	x	FUNCTION	CONTROL BITS/SIGNALS ⁽¹⁾	
			P5DIR.x	P5SEL.x
P5.4/UCB1SOMI/UCB1SCL	4	P5.4 (I/O)	I: 0; O: 1	0
		UCB1SOMI/UCB1SCL ^{(2) (3)}	X	1
P5.5/UCB1CLK/UCA1STE	5	P5.5 (I/O)	I: 0; O: 1	0
		UCB1CLK/UCA1STE ⁽²⁾	X	1
P5.6/UCA1TXD/UCA1SIMO	6	P5.6 (I/O)	I: 0; O: 1	0
		UCA1TXD/UCA1SIMO ⁽²⁾	X	1
P5.7/UCA1RXD/UCA1SOMI	7	P5.7 (I/O)	I: 0; O: 1	0
		UCA1RXD/UCA1SOMI ⁽²⁾	X	1

(1) X = Don't care

(2) The pin direction is controlled by the USCI module.

(3) If the I2C functionality is selected, the output drives only the logical 0 to V_{SS} level.

6.10.9 Port P6, P6.0 to P6.7, Input/Output With Schmitt Trigger

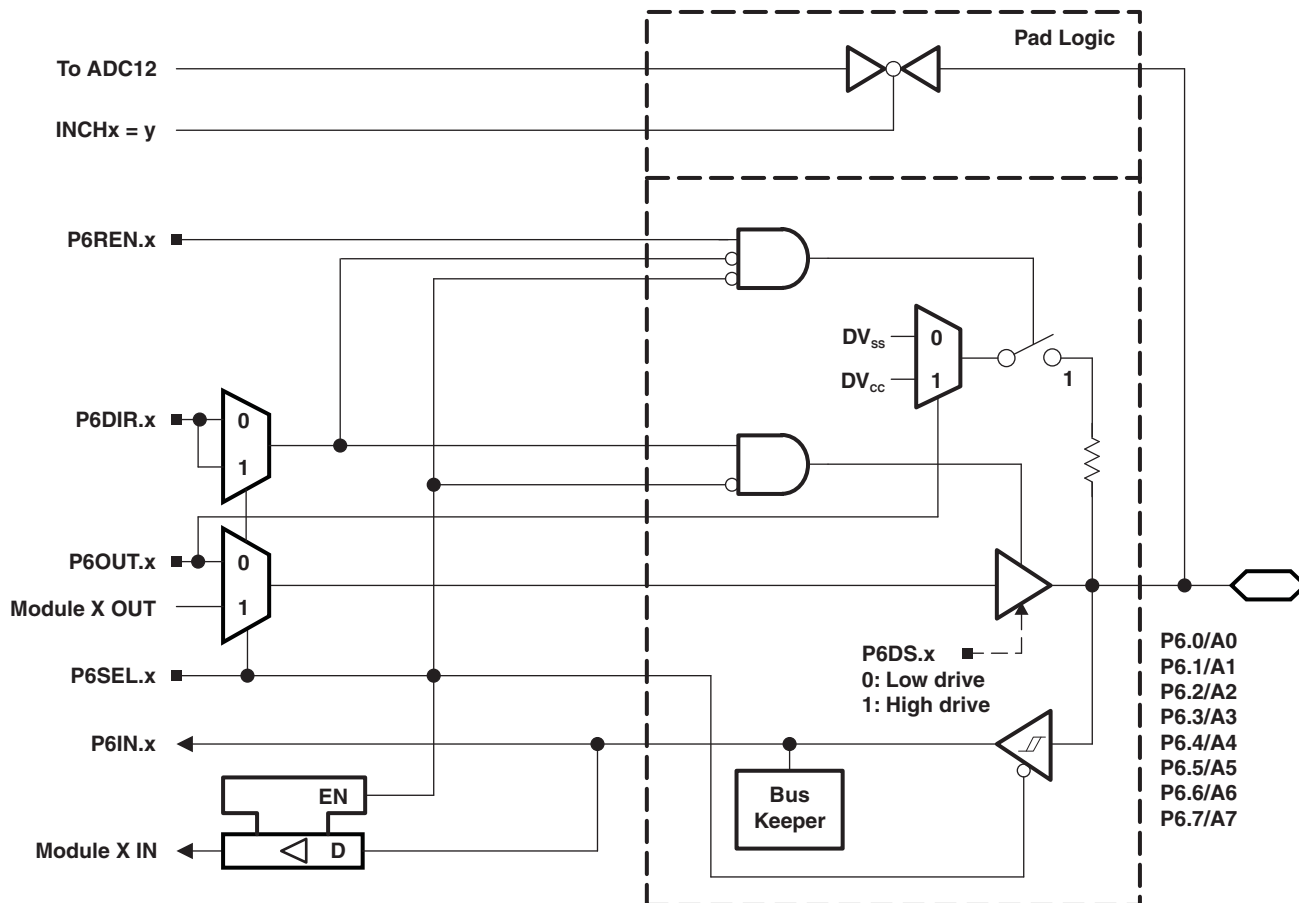


Table 6-49. Port P6 (P6.0 to P6.7) Pin Functions

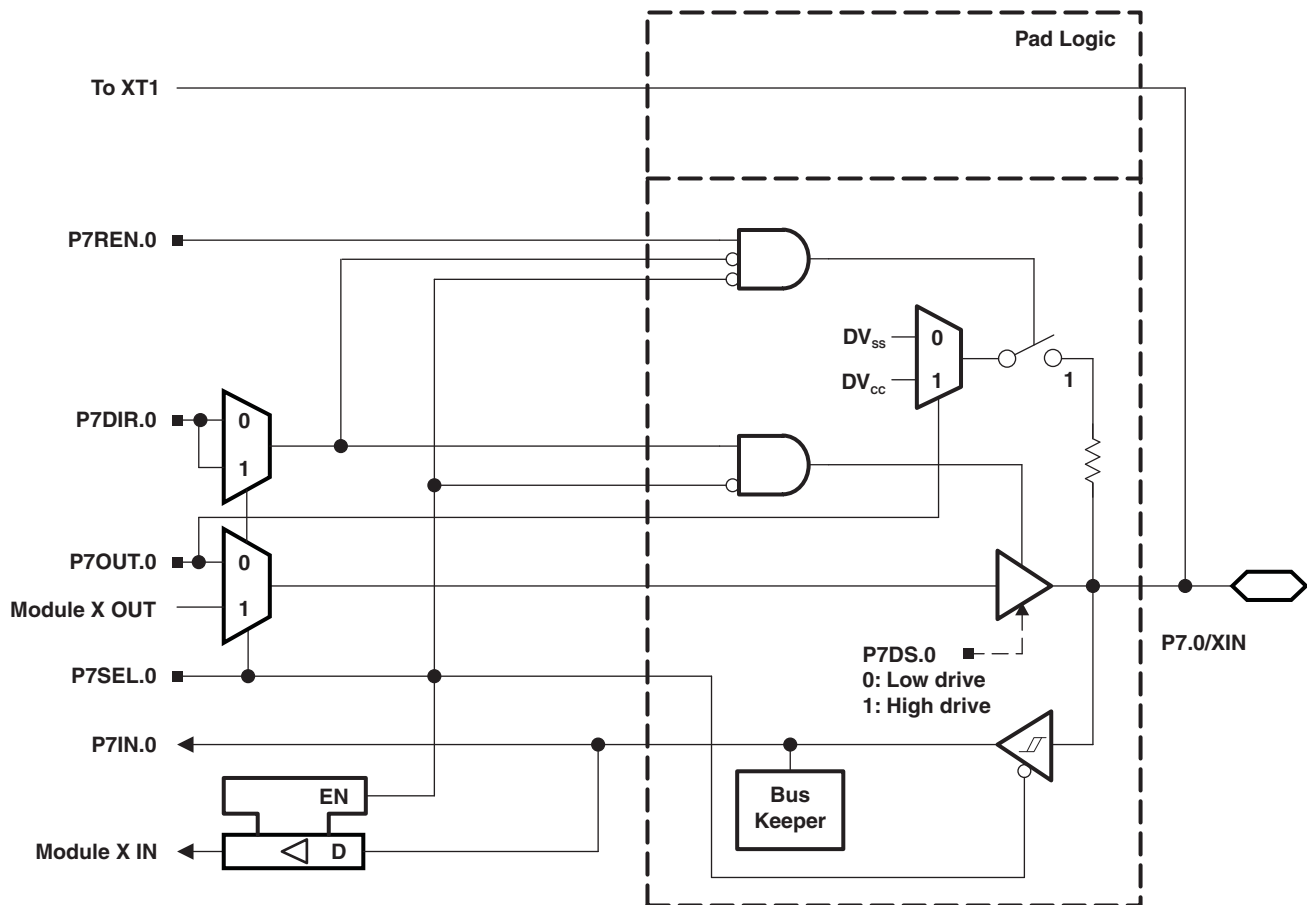
PIN NAME (P6.x)	x	FUNCTION	CONTROL BITS/SIGNALS ⁽¹⁾		
			P6DIR.x	P6SEL.x	INCHx
P6.0/A0	0	P6.0 (I/O)	I: 0; O: 1	0	X
		A0 ^{(2) (3)}	X	X	0
P6.1/A1	1	P6.1 (I/O)	I: 0; O: 1	0	X
		A1 ^{(2) (3)}	X	X	1
P6.2/A2	2	P6.2 (I/O)	I: 0; O: 1	0	X
		A2 ^{(2) (3)}	X	X	2
P6.3/A3	3	P6.3 (I/O)	I: 0; O: 1	0	X
		A3 ^{(2) (3)}	X	X	3
P6.4/A4	4	P6.4 (I/O)	I: 0; O: 1	0	X
		A4 ^{(2) (3)}	X	X	4
P6.5/A5	5	P6.5 (I/O)	I: 0; O: 1	0	X
		A5 ^{(1) (2) (3)}	X	X	5
P6.6/A6	6	P6.6 (I/O)	I: 0; O: 1	0	X
		A6 ^{(2) (3)}	X	X	6
P6.7/A7	7	P6.7 (I/O)	I: 0; O: 1	0	X
		A7 ^{(2) (3)}	X	X	7

(1) X = Don't care

(2) Setting the P6SEL.x bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals.

(3) The ADC12_A channel Ax is connected internally to AV_{SS} if not selected via the respective INCHx bits.

6.10.10 Port P7, P7.0, Input/Output With Schmitt Trigger



6.10.11 Port P7, P7.1, Input/Output With Schmitt Trigger

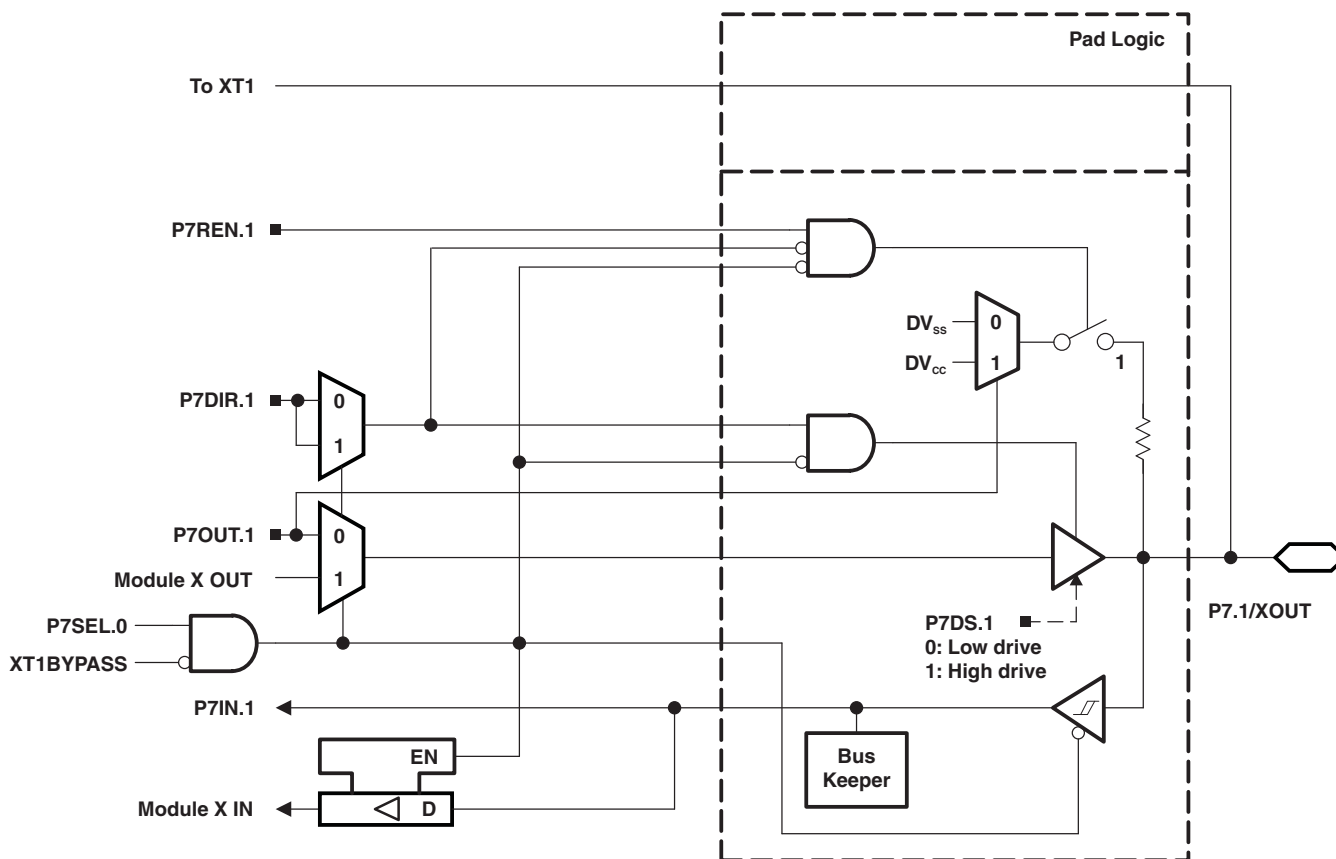


Table 6-50. Port P7 (P7.0 and P7.1) Pin Functions

PIN NAME (P7.x)	x	FUNCTION	CONTROL BITS/SIGNALS ⁽¹⁾			
			P7DIR.x	P7SEL.0	P7SEL.1	XT1BYPASS
P7.0/XIN	0	P7.0 (I/O)	I: 0; O: 1	0	X	X
		XIN crystal mode ⁽²⁾	X	1	X	0
		XIN bypass mode ⁽²⁾	X	1	X	1
P7.1/XOUT	1	P7.1 (I/O)	I: 0; O: 1	0	X	X
		XOUT crystal mode ⁽³⁾	X	1	X	0
		P7.1 (I/O) ⁽³⁾	X	1	X	1

(1) X = Don't care

(2) Setting P7SEL.0 causes the general-purpose I/O to be disabled. Pending the setting of XT1BYPASS, P7.0 is configured for crystal mode or bypass mode.

(3) Setting P7SEL.0 causes the general-purpose I/O to be disabled in crystal mode. When using bypass mode, P7.1 can be used as general-purpose I/O.

6.10.12 Port P7, P7.2 and P7.3, Input/Output With Schmitt Trigger

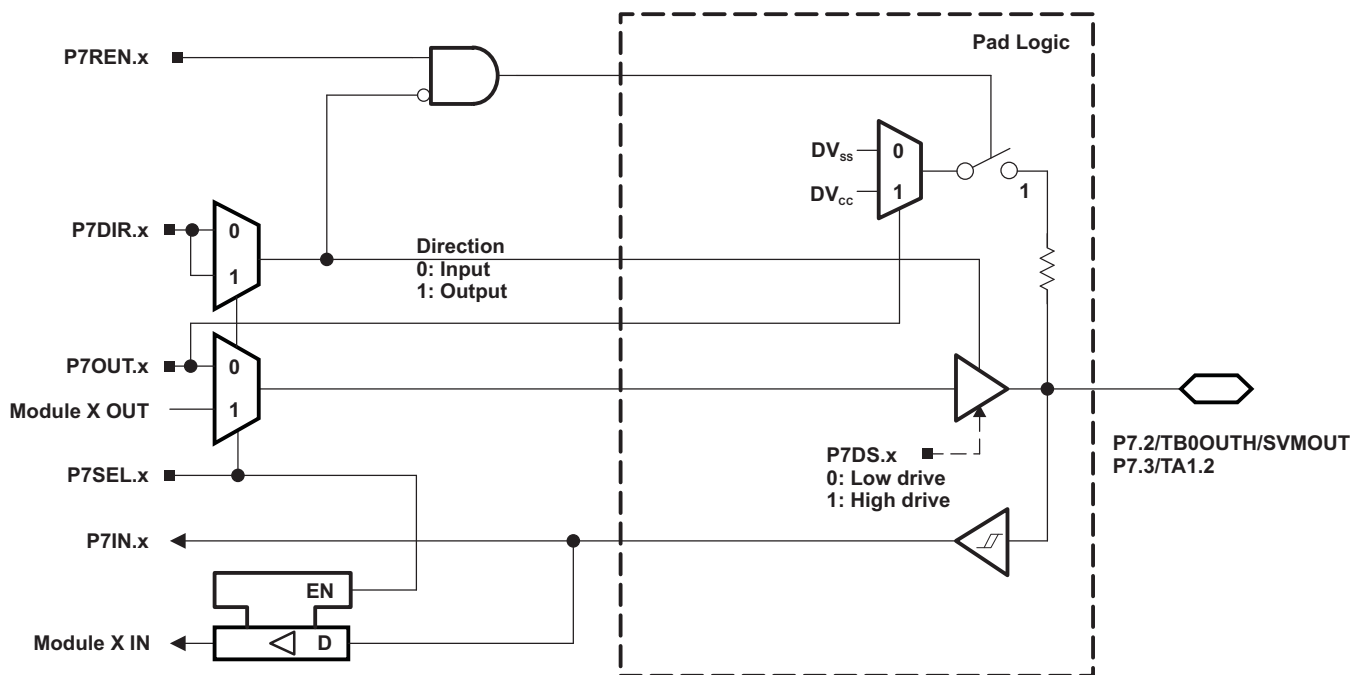


Table 6-51. Port P7 (P7.2 and P7.3) Pin Functions

PIN NAME (P7.x)	x	FUNCTION	CONTROL BITS/SIGNALS	
			P7DIR.x	P7SEL.x
P7.2/TB0OUTH/SVMOUT	2	P7.2 (I/O)	I: 0; O: 1	0
		TB0OUTH	0	1
		SVMOUT	1	1
P7.3/TA1.2	3	P7.3 (I/O)	I: 0; O: 1	0
		TA1.CCI2B	0	1
		TA1.2	1	1

6.10.13 Port P7, P7.4 to P7.7, Input/Output With Schmitt Trigger

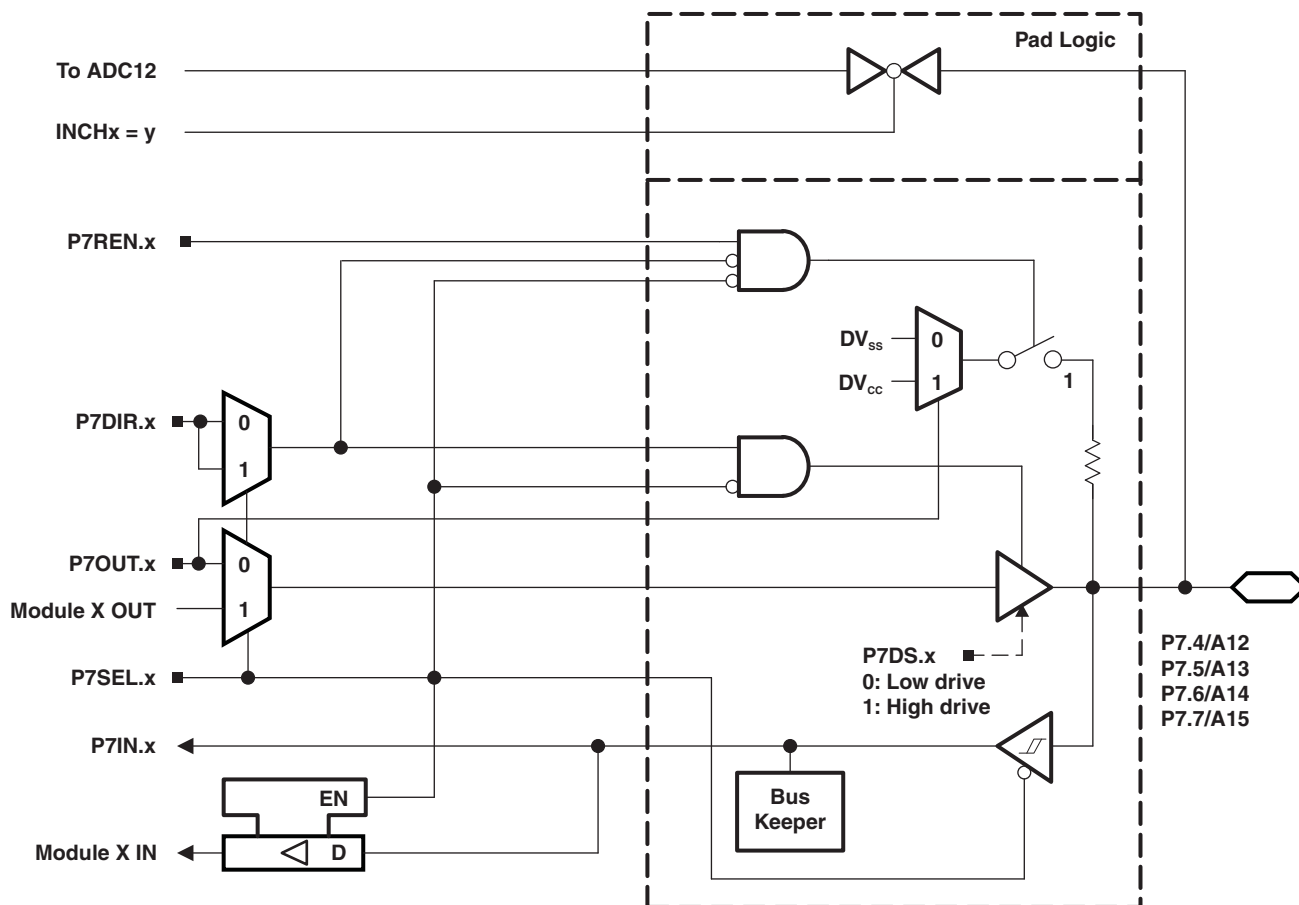


Table 6-52. Port P7 (P7.4 to P7.7) Pin Functions

PIN NAME (P7.x)	x	FUNCTION	CONTROL BITS/SIGNALS ⁽¹⁾		
			P7DIR.x	P7SEL.x	INCHx
P7.4/A12	4	P7.4 (I/O)	I: 0; O: 1	0	X
		A12 ⁽²⁾ (3)	X	X	12
P7.5/A13	5	P7.5 (I/O)	I: 0; O: 1	0	X
		A13 ⁽⁴⁾ (5)	X	X	13
P7.6/A14	6	P7.6 (I/O)	I: 0; O: 1	0	X
		A14 ⁽⁴⁾ (5)	X	X	14
P7.7/A15	7	P7.7 (I/O)	I: 0; O: 1	0	X
		A15 ⁽⁴⁾ (5)	X	X	15

- (1) X = Don't care
- (2) Setting the P7SEL.x bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals.
- (3) The ADC12_A channel Ax is connected internally to AV_{SS} if not selected via the respective INCHx bits.
- (4) Setting the P7SEL.x bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals.
- (5) The ADC12_A channel Ax is connected internally to AV_{SS} if not selected via the respective INCHx bits.

6.10.14 Port P8, P8.0 to P8.7, Input/Output With Schmitt Trigger

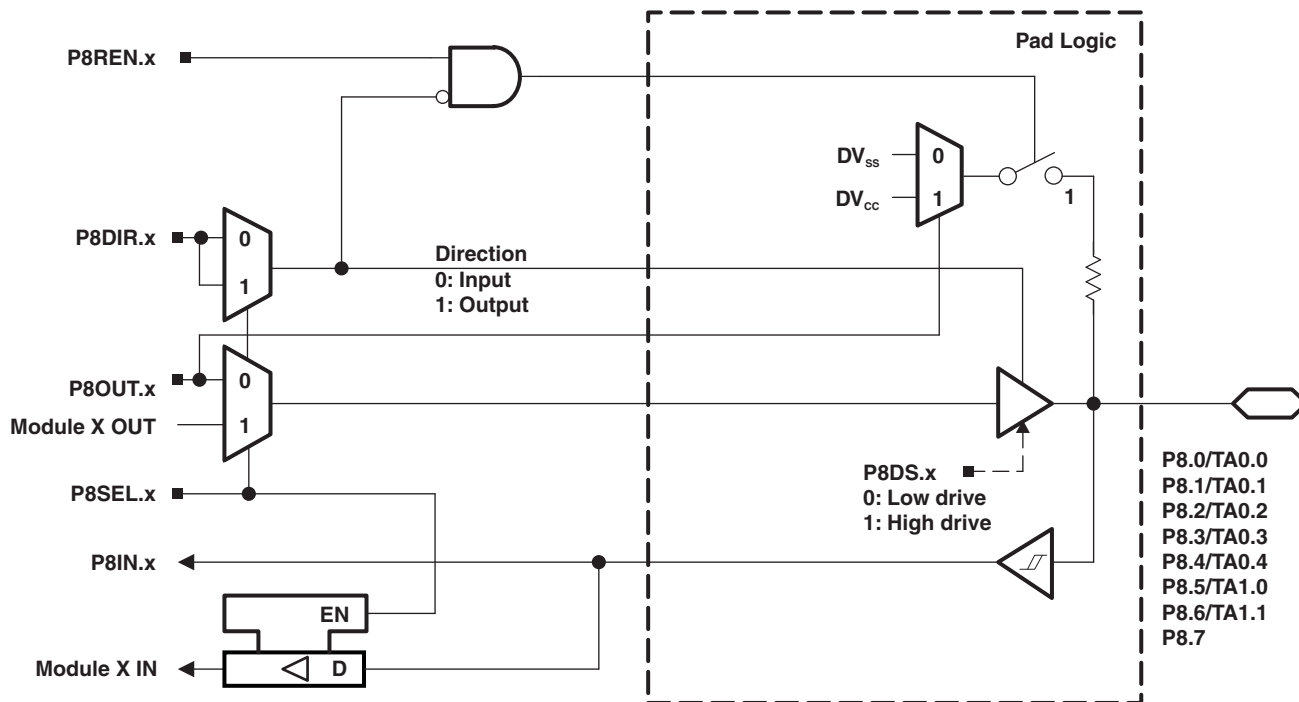


Table 6-53. Port P8 (P8.0 to P8.7) Pin Functions

PIN NAME (P8.x)	x	FUNCTION	CONTROL BITS/SIGNALS	
			P8DIR.x	P8SEL.x
P8.0/TA0.0	0	P8.0 (I/O)	I: 0; O: 1	0
		TA0.CCI0B	0	1
		TA0.0	1	1
P8.1/TA0.1	1	P8.1 (I/O)	I: 0; O: 1	0
		TA0.CCI1B	0	1
		TA0.1	1	1
P8.2/TA0.2	2	P8.2 (I/O)	I: 0; O: 1	0
		TA0.CCI2B	0	1
		TA0.2	1	1
P8.3/TA0.3	3	P8.3 (I/O)	I: 0; O: 1	0
		TA0.CCI3B	0	1
		TA0.3	1	1
P8.4/TA0.4	4	P8.4 (I/O)	I: 0; O: 1	0
		TA0.CCI4B	0	1
		TA0.4	1	1
P8.5/TA1.0	5	P8.5 (I/O)	I: 0; O: 1	0
		TA1.CCI0B	0	1
		TA1.0	1	1
P8.6/TA1.1	6	P8.6 (I/O)	I: 0; O: 1	0
		TA1.CCI1B	0	1
		TA1.1	1	1
P8.7	7	P8.7 (I/O)	I: 0; O: 1	0

6.10.15 Port P9, P9.0 to P9.7, Input/Output With Schmitt Trigger

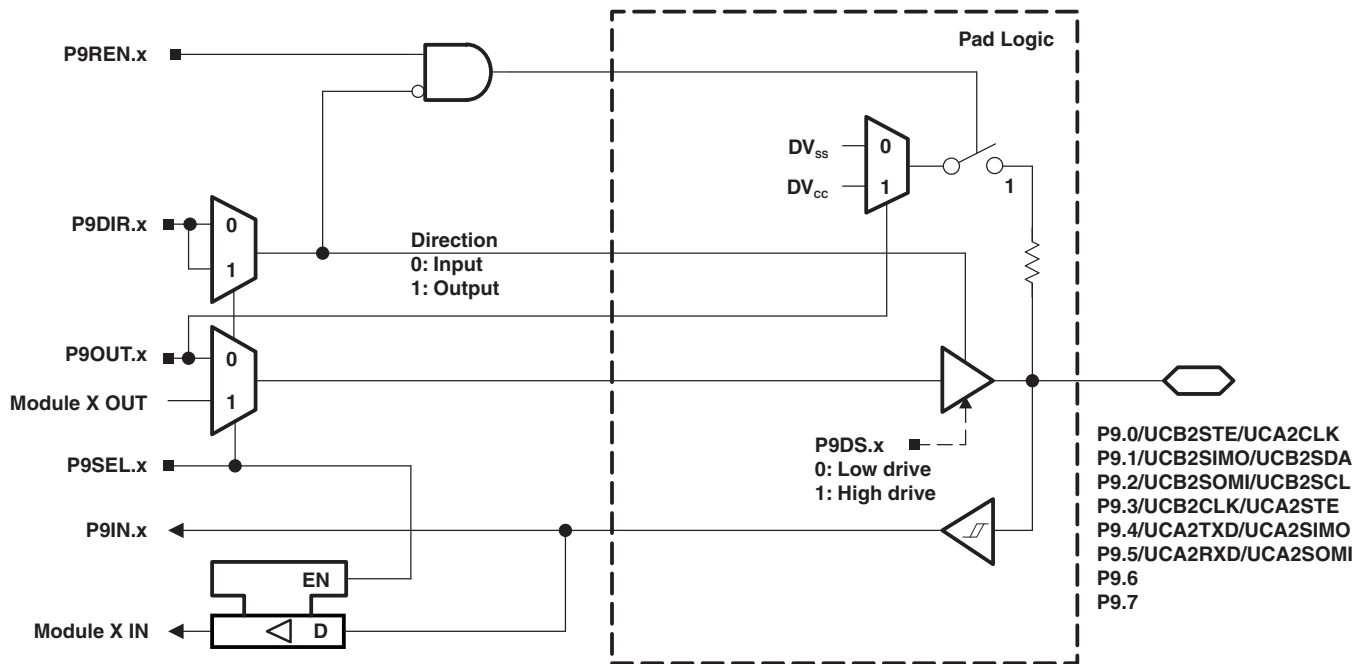


Table 6-54. Port P9 (P9.0 to P9.7) Pin Functions

PIN NAME (P9.x)	x	FUNCTION	CONTROL BITS/SIGNALS ⁽¹⁾	
			P9DIR.x	P9SEL.x
P9.0/UCB2STE/UCA2CLK	0	P9.0 (I/O)	I: 0; O: 1	0
		UCB2STE/UCA2CLK ^{(2) (3)}	X	1
P9.1/UCB2SIMO/UCB2SDA	1	P9.1 (I/O)	I: 0; O: 1	0
		UCB2SIMO/UCB2SDA ^{(2) (4)}	X	1
P9.2/UCB2SOMI/UCB2SCL	2	P9.2 (I/O)	I: 0; O: 1	0
		UCB2SOMI/UCB2SCL ^{(2) (4)}	X	1
P9.3/UCB2CLK/UCA2STE	3	P9.3 (I/O)	I: 0; O: 1	0
		UCB2CLK/UCA2STE ⁽²⁾	X	1
P9.4/UCA2TXD/UCA2SIMO	4	P9.4 (I/O)	I: 0; O: 1	0
		UCA2TXD/UCA2SIMO ⁽²⁾	X	1
P9.5/UCA2RXD/UCA2SOMI	5	P9.5 (I/O)	I: 0; O: 1	0
		UCA2RXD/UCA2SOMI ⁽²⁾	X	1
P9.6	6	P9.6 (I/O)	I: 0; O: 1	0
P9.7	7	P9.7 (I/O)	I: 0; O: 1	0

(1) X = Don't care

(2) The pin direction is controlled by the USCI module.

(3) UCB2CLK function takes precedence over UCA2STE function. If the pin is required as UCB2CLK input or output, USCI_A2 is forced to 3-wire SPI mode if 4-wire SPI mode is selected.

(4) If the I2C functionality is selected, the output drives only the logical 0 to V_{SS} level.

6.10.16 Port P10, P10.0 to P10.7, Input/Output With Schmitt Trigger

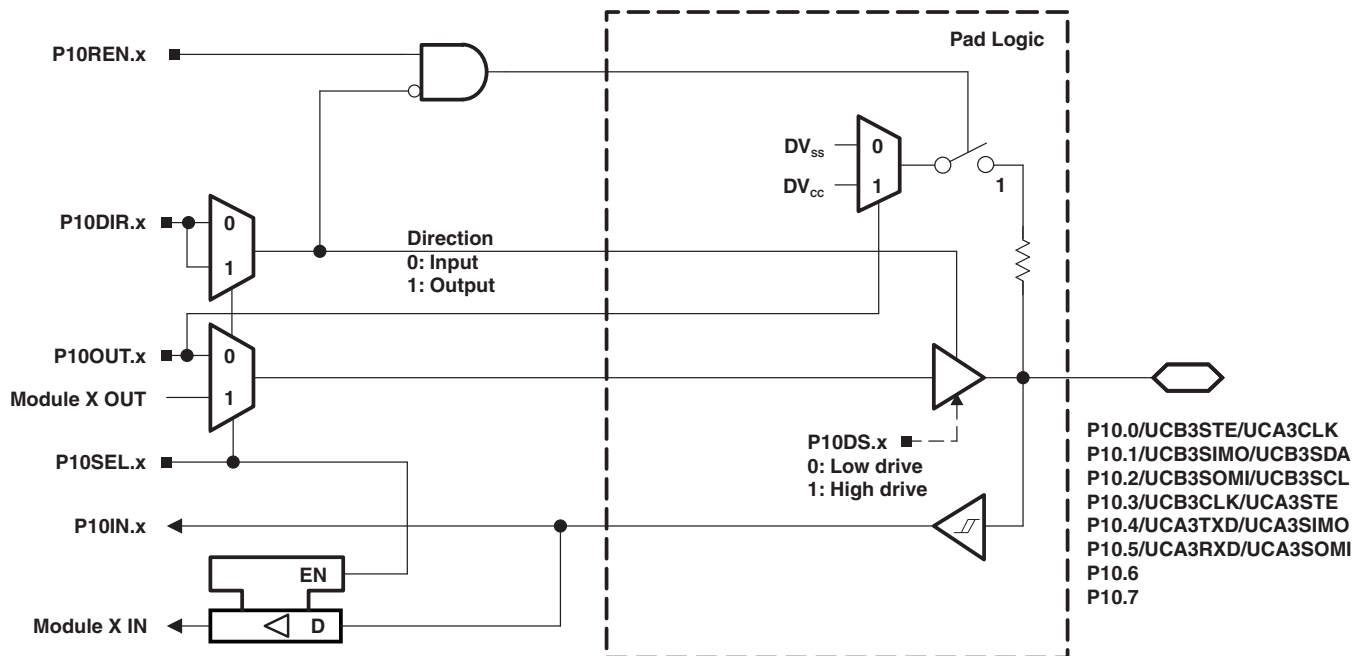


Table 6-55. Port P10 (P10.0 to P10.7) Pin Functions

PIN NAME (P10.x)	x	FUNCTION	CONTROL BITS/SIGNALS ⁽¹⁾	
			P10DIR.x	P10SEL.x
P10.0/UCB3STE/UCA3CLK	0	P10.0 (I/O)	I: 0; O: 1	0
		UCB3STE/UCA3CLK ^{(2) (3)}	X	1
P10.1/UCB3SIMO/UCB3SDA	1	P10.1 (I/O)	I: 0; O: 1	0
		UCB3SIMO/UCB3SDA ^{(2) (4)}	X	1
P10.2/UCB3SOMI/UCB3SCL	2	P10.2 (I/O)	I: 0; O: 1	0
		UCB3SOMI/UCB3SCL ^{(2) (4)}	X	1
P10.3/UCB3CLK/UCA3STE	3	P10.3 (I/O)	I: 0; O: 1	0
		UCB3CLK/UCA3STE ⁽²⁾	X	1
P10.4/UCA3TXD/UCA3SIMO	4	P10.4 (I/O)	I: 0; O: 1	0
		UCA3TXD/UCA3SIMO ⁽²⁾	X	1
P10.5/UCA3RXD/UCA3SOMI	5	P10.5 (I/O)	I: 0; O: 1	0
		UCA3RXD/UCA3SOMI ⁽²⁾	X	1
P10.6	6	P10.6 (I/O)	I: 0; O: 1	0
		Reserved ⁽⁵⁾	X	1
P10.7	7	P10.7 (I/O)	I: 0; O: 1	0
		Reserved ⁽⁵⁾	x	1

- (1) X = Don't care
- (2) The pin direction is controlled by the USCI module.
- (3) UCA3CLK function takes precedence over UCB3STE function. If the pin is required as UCA3CLK input or output, USCI_B3 is forced to 3-wire SPI mode if 4-wire SPI mode is selected.
- (4) If the I2C functionality is selected, the output drives only the logical 0 to V_{SS} level.
- (5) The secondary functions on these pins are reserved for factory test purposes. Application should keep the P10SEL.x of these ports cleared to prevent potential conflicts with the application.

6.10.17 Port P11, P11.0 to P11.2, Input/Output With Schmitt Trigger

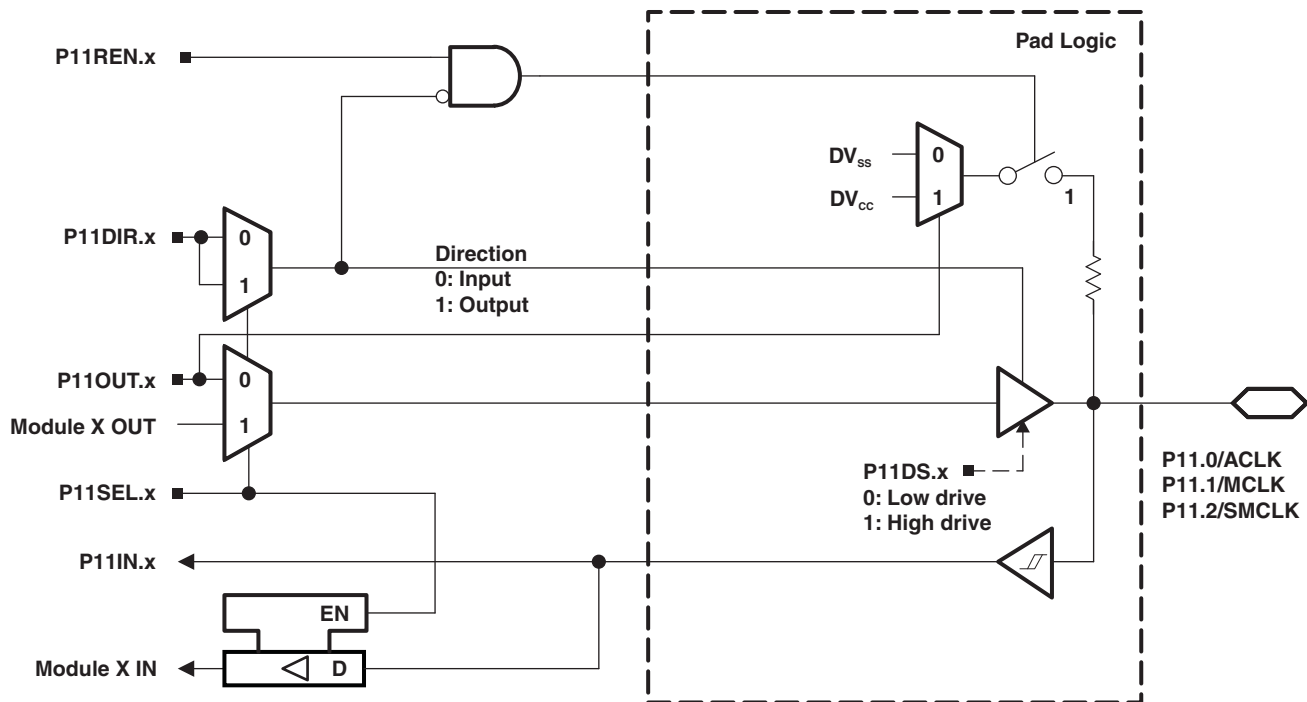
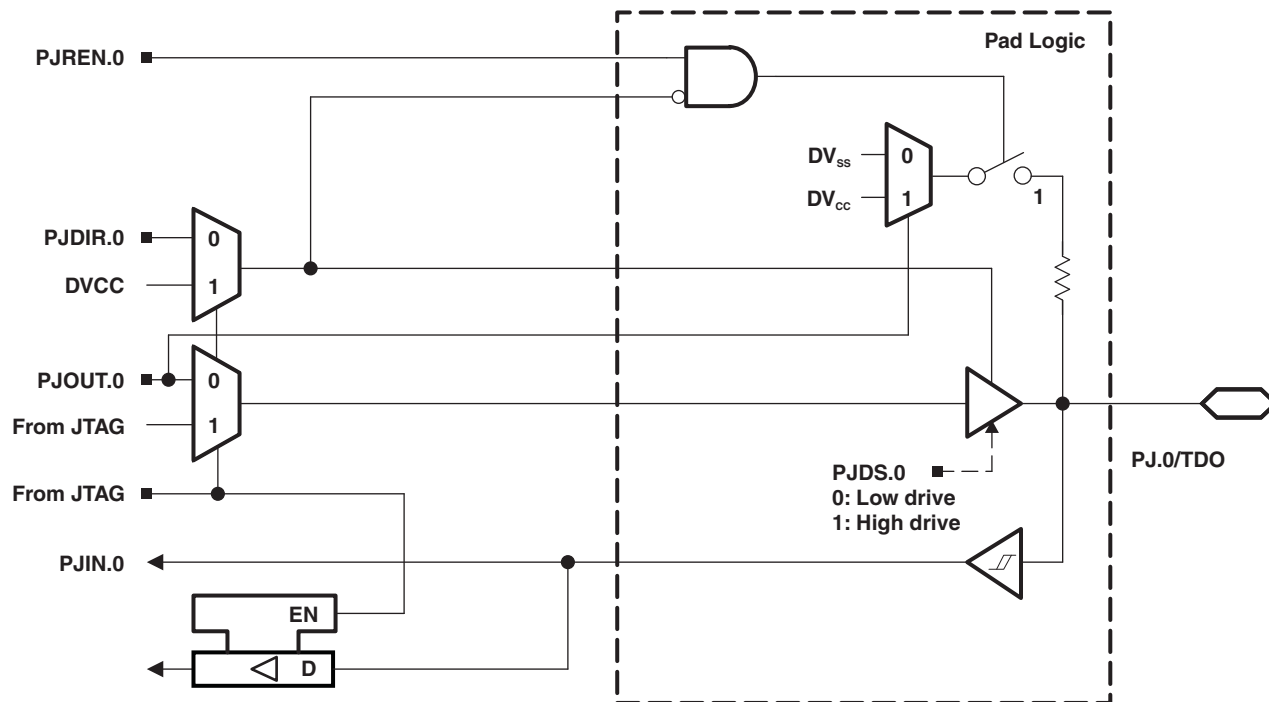


Table 6-56. Port P11 (P11.0 to P11.2) Pin Functions

PIN NAME (P11.x)	x	FUNCTION	CONTROL BITS/SIGNALS	
			P11DIR.x	P11SEL.x
P11.0/ACLK	0	P11.0 (I/O)	I: 0; O: 1	0
		ACLK	1	1
P11.1/MCLK	1	P11.1 (I/O)	I: 0; O: 1	0
		MCLK	1	1
P11.2/SMCLK	2	P11.2 (I/O)	I: 0; O: 1	0
		SMCLK	1	1

6.10.18 Port J, J.0 JTAG pin TDO, Input/Output With Schmitt Trigger or Output



6.10.19 Port J, J.1 to J.3 JTAG pins TMS, TCK, TDI/TCLK, Input/Output With Schmitt Trigger or Output

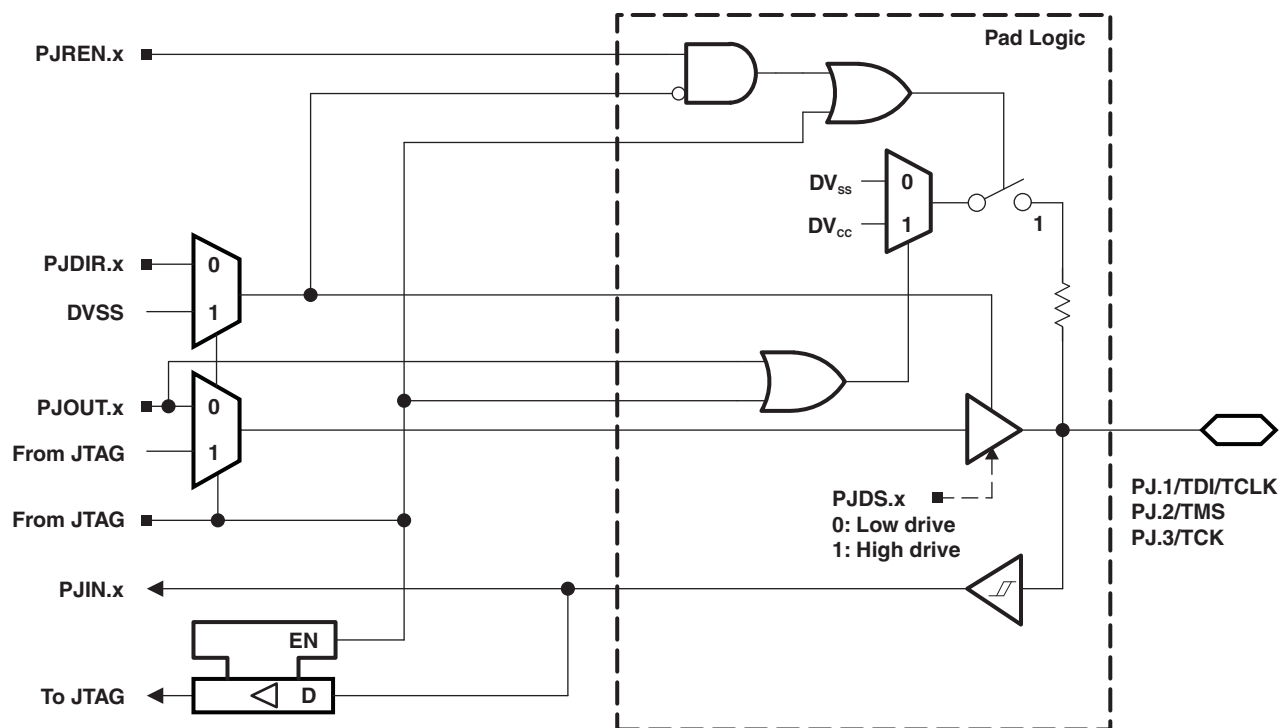


Table 6-57. Port PJ (PJ.0 to PJ.3) Pin Functions

PIN NAME (PJ.x)	x	FUNCTION	CONTROL BITS/ SIGNALS ⁽¹⁾
			PJDIR.x
PJ.0/TDO	0	PJ.0 (I/O) ⁽²⁾	I: 0; O: 1
		TDO ⁽³⁾	X
PJ.1/TDI/TCLK	1	PJ.1 (I/O) ⁽²⁾	I: 0; O: 1
		TDI/TCLK ^{(3) (4)}	X
PJ.2/TMS	2	PJ.2 (I/O) ⁽²⁾	I: 0; O: 1
		TMS ^{(3) (4)}	X
PJ.3/TCK	3	PJ.3 (I/O) ⁽²⁾	I: 0; O: 1
		TCK ^{(3) (4)}	X

(1) X = Don't care

(2) Default condition

(3) The pin direction is controlled by the JTAG module.

(4) In JTAG mode, pullups are activated automatically on TMS, TCK, and TDI/TCLK. PJREN.x are do not care.

6.11 TLV (Device Descriptor) Structures

Table 6-58 lists the complete contents of the device descriptor tag-length-value (TLV) structure.

Table 6-58. Device Descriptor Table⁽¹⁾

	Description	Address	Size bytes	F5438	F5437	F5436	F5435	F5419	F5418
				Value	Value	Value	Value	Value	Value
Info Block	Info length	01A00h	1	06h	06h	06h	06h	06h	06h
	CRC length	01A01h	1	06h	06h	06h	06h	06h	06h
	CRC value	01A02h	2	per unit	per unit	per unit	per unit	per unit	per unit
	Device ID	01A04h	1	54h	54h	54h	54h	54h	54h
	Device ID	01A05h	1	38h	37h	36h	35h	19h	18h
	Hardware revision	01A06h	1	per unit	per unit	per unit	per unit	per unit	per unit
	Firmware revision	01A07h	1	per unit	per unit	per unit	per unit	per unit	per unit
Die Record	Die Record Tag	01A08h	1	08h	08h	08h	08h	08h	08h
	Die Record length	01A09h	1	0Ah	0Ah	0Ah	0Ah	0Ah	0Ah
	Lot/Wafer ID	01A0Ah	4	per unit	per unit	per unit	per unit	per unit	per unit
	Die X position	01A0Eh	2	per unit	per unit	per unit	per unit	per unit	per unit
	Die Y position	01A10h	2	per unit	per unit	per unit	per unit	per unit	per unit
	Test results	01A12h	2	per unit	per unit	per unit	per unit	per unit	per unit
	ADC12 Calibration	ADC12 Calibration Tag	01A14h	1	10h	10h	10h	10h	10h
ADC12 Calibration length		01A15h	1	10h	10h	10h	10h	10h	10h
ADC Gain Factor		01A16h	2	per unit	per unit	per unit	per unit	per unit	per unit
ADC Offset		01A18h	2	per unit	per unit	per unit	per unit	per unit	per unit
ADC 1.5-V Reference Factor		01A1Ah	2	per unit	per unit	per unit	per unit	per unit	per unit
ADC 1.5-V Reference Temp. Sensor 30°C		01A1Ch	2	per unit	per unit	per unit	per unit	per unit	per unit
ADC 1.5-V Reference Temp. Sensor 85°C		01A1Eh	2	per unit	per unit	per unit	per unit	per unit	per unit
ADC 2.5-V Reference Factor		01A20h	2	per unit	per unit	per unit	per unit	per unit	per unit
ADC 2.5-V Reference Temp. Sensor 30°C		01A22h	2	per unit	per unit	per unit	per unit	per unit	per unit
ADC 2.5-V Reference Temp. Sensor 85°C	01A24h	2	per unit	per unit	per unit	per unit	per unit	per unit	
Peripheral Descriptor	Peripheral Descriptor Tag	01A26h	1	02h	02h	02h	02h	02h	02h
	Peripheral Descriptor Length	01A27h	1	5Dh	55h	5Eh	56h	5Dh	55h
	Memory 1		2	08h 8Ah	08h 8Ah	08h 8Ah	08h 8Ah	08h 8Ah	08h 8Ah
	Memory 2		2	0Ch 86h	0Ch 86h	0Ch 86h	0Ch 86h	0Ch 86h	0Ch 86h
	Memory 3		2	0Eh 30h	0Eh 30h	0Eh 30h	0Eh 30h	0Eh 30h	0Eh 30h

(1) NA = Not applicable

Table 6-58. Device Descriptor Table⁽¹⁾ (continued)

	Description	Address	Size bytes	F5438	F5437	F5436	F5435	F5419	F5418
				Value	Value	Value	Value	Value	Value
	Memory 4		2	2Eh 98h	2Eh 98h	2Eh 97h	2Eh 97h	2Eh 96h	2Eh 96h
	Memory 5		0/1	NA	NA	94h	94h	NA	NA
	delimiter		1	00h	00h	00h	00h	00h	00h
	Peripheral count		1	1Fh	1Bh	1Fh	1Fh	1Fh	1Bh
	MSP430CPUXV2		2	00h 23h	00h 23h	00h 23h	00h 23h	00h 23h	00h 23h
	SBW		2	00h 0Fh	00h 0Fh	00h 0Fh	00h 0Fh	00h 0Fh	00h 0Fh
	EEM-8		2	00h 05h	00h 05h	00h 05h	00h 05h	00h 05h	00h 05h
	TI BSL		2	00h FCh	00h FCh	00h FCh	00h FCh	00h FCh	00h FCh
	Package		2	00h 1Fh	00h 1Fh	00h 1Fh	00h 1Fh	00h 1Fh	00h 1Fh
	SFR		2	10h 41h	10h 41h	10h 41h	10h 41h	10h 41h	10h 41h
	PMM		2	02h 30h	02h 30h	02h 30h	02h 30h	02h 30h	02h 30h
	FCTL		2	02h 38h	02h 38h	02h 38h	02h 38h	02h 38h	02h 38h
	CRC16		2	01h 3Dh	01h 3Dh	01h 3Dh	01h 3Dh	01h 3Dh	01h 3Dh
	RAMCTL		2	00h 44h	00h 44h	00h 44h	00h 44h	00h 44h	00h 44h
	WDT_A		2	00h 40h	00h 40h	00h 40h	00h 40h	00h 40h	00h 40h
	UCS		2	01h 48h	01h 48h	01h 48h	01h 48h	01h 48h	01h 48h
	SYS		2	02h 42h	02h 42h	02h 42h	02h 42h	02h 42h	02h 42h
	Port 1/2		2	08h 51h	08h 51h	08h 51h	08h 51h	08h 51h	08h 51h
	Port 3/4		2	02h 52h	02h 52h	02h 52h	02h 52h	02h 52h	02h 52h
	Port 5/6		2	02h 53h	02h 53h	02h 53h	02h 53h	02h 53h	02h 53h
	Port 7/8		2	02h 54h	02h 54h	02h 54h	02h 54h	02h 54h	02h 54h
	Port 9/10		2	02h 55h	NA	02h 55h	NA	02h 55h	NA
	Port 11/12		2	02h 56h	NA	02h 56h	NA	02h 56h	NA
	JTAG		2	08h 5Fh	0Ch 5F	08h 5Fh	0Ch 5F	08h 5Fh	0Ch 5F
	TA0		2	02h 62h	02h 62h	02h 62h	02h 62h	02h 62h	02h 62h
	TA1		2	04h 61h	04h 61h	04h 61h	04h 61h	04h 61h	04h 61h
	TB0		2	04h 67h	04h 67h	04h 67h	04h 67h	04h 67h	04h 67h
	RTC		2	0Eh 68h	0Eh 68h	0Eh 68h	0Eh 68h	0Eh 68h	0Eh 68h

Table 6-58. Device Descriptor Table⁽¹⁾ (continued)

	Description	Address	Size bytes	F5438	F5437	F5436	F5435	F5419	F5418
				Value	Value	Value	Value	Value	Value
	MPY32		2	02h 85h	02h 85h	02h 85h	02h 85h	02h 85h	02h 85h
	DMA-3		2	04h 47h	04h 47h	04h 47h	04h 47h	04h 47h	04h 47h
	USCI_A/B		2	0Ch 90h	0Ch 90h	0Ch 90h	0Ch 90h	0Ch 90h	0Ch 90h
	USCI_A/B		2	04h 90h	04h 90h	04h 90h	04h 90h	04h 90h	04h 90h
	USCI_A/B		2	04h 90h	NA	04h 90h	NA	04h 90h	NA
	USCI_A/B		2	04h 90h	NA	04h 90h	NA	04h 90h	NA
	ADC12_A		2	08h D0h	10h D0h	08h D0h	10h D0h	08h D0h	10h D0h
Interrupts	TB0.CCIFG0		1	64h	64h	64h	64h	64h	64h
	TB0.CCIFG1..6		1	65h	65h	65h	65h	65h	65h
	WDTIFG		1	40h	40h	40h	40h	40h	40h
	USCI_A0		1	90h	90h	90h	90h	90h	90h
	USCI_B0		1	91h	91h	91h	91h	91h	91h
	ADC12_A		1	D0h	D0h	D0h	D0h	D0h	D0h
	TA0.CCIFG0		1	60h	60h	60h	60h	60h	60h
	TA0.CCIFG1..4		1	61h	61h	61h	61h	61h	61h
	USCI_A2		1	94h	01h	94h	01h	94h	01h
	USCI_B2		1	95h	01h	95h	01h	95h	01h
	DMA		1	46h	46h	46h	46h	46h	46h
	TA1.CCIFG0		1	62h	62h	62h	62h	62h	62h
	TA1.CCIFG1..2		1	63h	63h	63h	63h	63h	63h
	P1		1	50h	50h	50h	50h	50h	50h
	USCI_A1		1	92h	92h	92h	92h	92h	92h
	USCI_B1		1	93h	93h	93h	93h	93h	93h
	USCI_A3		1	96h	01h	96h	01h	96h	01h
	USCI_B3		1	97h	01h	97h	01h	97h	01h
	P2		1	51h	51h	51h	51h	51h	51h
	RTC_A		1	68h	68h	68h	68h	68h	68h
	delimiter		1	00h	00h	00h	00h	00h	00h

7 Device and Documentation Support

7.1 Device Support

7.1.1 Getting Started and Next Steps

For more information on the MSP430™ family of devices and the tools and libraries that are available to help with your development, visit the [Getting Started](#) page.

7.1.2 Development Tools Support

All MSP430 microcontrollers are supported by a wide variety of software and hardware development tools. Tools are available from TI and various third parties. See them all at www.ti.com/msp430tools.

7.1.2.1 Hardware Features

See the *Code Composer Studio for MSP430 User's Guide* ([SLAU157](#)) for details on the available features.

MSP430 Architecture	4-Wire JTAG	2-Wire JTAG	Break-points (N)	Range Break-points	Clock Control	State Sequencer	Trace Buffer	LPMx.5 Debugging Support
MSP430Xv2	Yes	Yes	8	Yes	Yes	Yes	Yes	No

7.1.2.2 Recommended Hardware Options

7.1.2.2.1 Target Socket Boards

The target socket boards allow easy programming and debugging of the device using JTAG. They also feature header pin outs for prototyping. Target socket boards are orderable individually or as a kit with the JTAG programmer and debugger included. The following table shows the compatible target boards and the supported packages.

Package	Target Board and Programmer Bundle	Target Board Only
100-pin LQFP (PZ)	MSP-FET430U5x100	MSP-TS430PZ5x100

7.1.2.2.2 Experimenter Boards

Experimenter Boards and Evaluation kits are available for some MSP430 devices. These kits feature additional hardware components and connectivity for full system evaluation and prototyping. See www.ti.com/msp430tools for details.

7.1.2.2.3 Debugging and Programming Tools

Hardware programming and debugging tools are available from TI and from its third party suppliers. See the full list of available tools at www.ti.com/msp430tools.

7.1.2.2.4 Production Programmers

The production programmers expedite loading firmware to devices by programming several devices simultaneously.

Part Number	PC Port	Features	Provider
MSP-GANG	Serial and USB	Program up to eight devices at a time. Works with PC or standalone.	Texas Instruments

7.1.2.3 Recommended Software Options

7.1.2.3.1 Integrated Development Environments

Software development tools are available from TI or from third parties. Open source solutions are also available.

This device is supported by Code Composer Studio™ IDE (CCS).

7.1.2.3.2 MSP430Ware

[MSP430Ware](#) is a collection of code examples, data sheets, and other design resources for all MSP430 devices delivered in a convenient package. In addition to providing a complete collection of existing MSP430 design resources, MSP430Ware also includes a high-level API called MSP430 Driver Library. This library makes it easy to program MSP430 hardware. MSP430Ware is available as a component of CCS or as a standalone package.

7.1.2.3.3 SYS/BIOS

[SYS/BIOS](#) is an advanced real-time operating system for the MSP430 microcontrollers. It features preemptive deterministic multi-tasking, hardware abstraction, memory management, and real-time analysis. SYS/BIOS is available free of charge and is provided with full source code.

7.1.2.3.4 Command-Line Programmer

[MSP430 Flasher](#) is an open-source, shell-based interface for programming MSP430 microcontrollers through a FET programmer or eZ430 using JTAG or Spy-Bi-Wire (SBW) communication. MSP430 Flasher can be used to download binary files (.txt or .hex) files directly to the MSP430 microcontroller without the need for an IDE.

7.1.3 Device and Development Tool Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP430 MCU devices and support tools. Each MSP430 MCU commercial family member has one of three prefixes: MSP, PMS, or XMS (for example, MSP430F5259). Texas Instruments recommends two of three possible prefix designators for its support tools: MSP and MSPX. These prefixes represent evolutionary stages of product development from engineering prototypes (with XMS for devices and MSPX for tools) through fully qualified production devices and tools (with MSP for devices and MSP for tools).

Device development evolutionary flow:

XMS – Experimental device that is not necessarily representative of the final device's electrical specifications

PMS – Final silicon die that conforms to the device's electrical specifications but has not completed quality and reliability verification

MSP – Fully qualified production device

Support tool development evolutionary flow:

MSPX – Development-support product that has not yet completed Texas Instruments internal qualification testing.

MSP – Fully-qualified development-support product

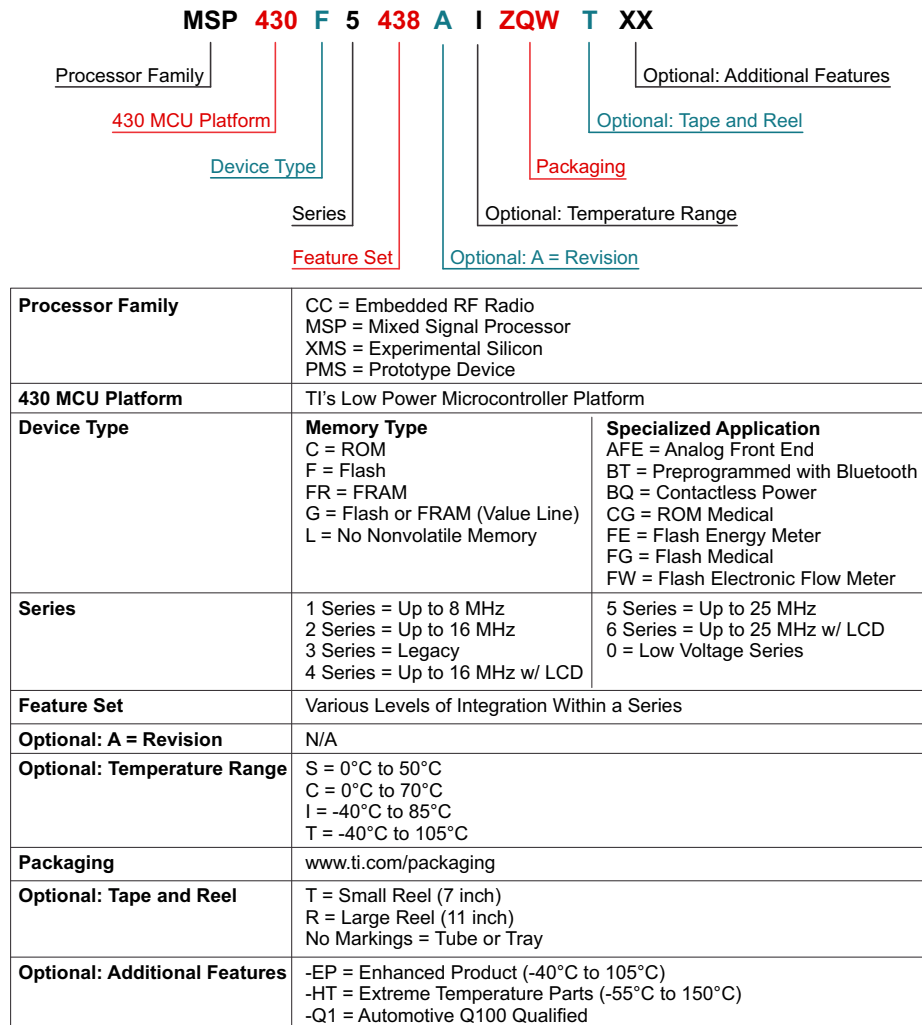
XMS and PMS devices and MSPX development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices and MSP development-support tools have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (XMS and PMS) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the package type (for example, PZP) and temperature range (for example, T). [Figure 7-1](#) provides a legend for reading the complete device name for any family member.


Figure 7-1. Device Nomenclature

7.2 Documentation Support

The following documents describe the MSP430F543x and MSP430F541x devices. Copies of these documents are available on the Internet at www.ti.com.

- [SLAU208](#) **MSP430x5xx and MSP430x6xx Family User's Guide.** Detailed information on the modules and peripherals available in this device family.
- [SLAZ289](#) **MSP430F5438 Device Erratasheet.** Describes the known exceptions to the functional specifications for this device.
- [SLAZ287](#) **MSP430F5437 Device Erratasheet.** Describes the known exceptions to the functional specifications for this device.
- [SLAZ285](#) **MSP430F5436 Device Erratasheet.** Describes the known exceptions to the functional specifications for this device.
- [SLAZ283](#) **MSP430F5435 Device Erratasheet.** Describes the known exceptions to the functional specifications for this device.
- [SLAZ281](#) **MSP430F5419 Device Erratasheet.** Describes the known exceptions to the functional specifications for this device.
- [SLAZ279](#) **MSP430F5418 Device Erratasheet.** Describes the known exceptions to the functional specifications for this device.

7.3 Related Links

[Table 7-1](#) lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 7-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
MSP430F5438	Click here	Click here	Click here	Click here	Click here
MSP430F5437	Click here	Click here	Click here	Click here	Click here
MSP430F5436	Click here	Click here	Click here	Click here	Click here
MSP430F5435	Click here	Click here	Click here	Click here	Click here
MSP430F5419	Click here	Click here	Click here	Click here	Click here
MSP430F5418	Click here	Click here	Click here	Click here	Click here

7.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

[TI E2E™ Community](#)

TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas, and help solve problems with fellow engineers.

[TI Embedded Processors Wiki](#)

Texas Instruments Embedded Processors Wiki. Established to help developers get started with embedded processors from Texas Instruments and to foster innovation and growth of general knowledge about the hardware and software surrounding these devices.

7.5 Trademarks

MSP430, Code Composer Studio, E2E are trademarks of Texas Instruments. All other trademarks are the property of their respective owners.

7.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.7 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

8 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MSP430F5418IPN	NRND	LQFP	PN	80	119	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5418	
MSP430F5418IPNR	NRND	LQFP	PN	80	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5418	
MSP430F5419IPZ	NRND	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5419	
MSP430F5419IPZR	NRND	LQFP	PZ	100	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5419	
MSP430F5435IPN	NRND	LQFP	PN	80	119	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5435	
MSP430F5435IPNR	NRND	LQFP	PN	80	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5435	
MSP430F5436IPN	NRND	LQFP	PN	80		TBD	Call TI	Call TI	-40 to 85		
MSP430F5436IPNR	NRND	LQFP	PN	80		TBD	Call TI	Call TI	-40 to 85		
MSP430F5436IPZ	NRND	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5436 REV #	
MSP430F5436IPZR	NRND	LQFP	PZ	100	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5436 REV #	
MSP430F5436TPN	NRND	LQFP	PN	80		TBD	Call TI	Call TI	-40 to 105		
MSP430F5436TPZ	NRND	LQFP	PZ	100		TBD	Call TI	Call TI	-40 to 105		
MSP430F5437IPN	NRND	LQFP	PN	80	119	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5437	
MSP430F5437IPNR	NRND	LQFP	PN	80	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5437	
MSP430F5438CYS	NRND	WAFERSALE	YS	0		TBD	Call TI	Call TI	-40 to 85		
MSP430F5438IPN	NRND	LQFP	PN	80		TBD	Call TI	Call TI	-40 to 85		
MSP430F5438IPNR	NRND	LQFP	PN	80		TBD	Call TI	Call TI	-40 to 85		
MSP430F5438IPZ	NRND	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5438 REV #	
MSP430F5438IPZR	NRND	LQFP	PZ	100	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5438 REV #	
MSP430F5438IRGC	NRND	VQFN	RGC	64		TBD	Call TI	Call TI	-40 to 85		
MSP430F5438IRGZ	NRND	VQFN	RGZ	48		TBD	Call TI	Call TI	-40 to 85		

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MSP430F5438IZQW	NRND	BGA MICROSTAR JUNIOR	ZQW	113		TBD	Call TI	Call TI	-40 to 85		
MSP430F5438IZQWR	NRND	BGA MICROSTAR JUNIOR	ZQW	113		TBD	Call TI	Call TI	-40 to 85		
MSP430F5438TPN	NRND	LQFP	PN	80		TBD	Call TI	Call TI	-40 to 105		
MSP430F5438TPNR	NRND	LQFP	PN	80		TBD	Call TI	Call TI	-40 to 105		
MSP430F5438TPZ	NRND	LQFP	PZ	100		TBD	Call TI	Call TI	-40 to 105		
MSP430F5438TPZR	NRND	LQFP	PZ	100		TBD	Call TI	Call TI	-40 to 105		
XMS430F5438IPZ	NRND	LQFP	PZ	100		TBD	Call TI	Call TI	-40 to 85		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MSP430F5418IPNR	LQFP	PN	80	1000	330.0	24.4	15.0	15.0	2.1	20.0	24.0	Q2
MSP430F5419IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2
MSP430F5435IPNR	LQFP	PN	80	1000	330.0	24.4	15.0	15.0	2.1	20.0	24.0	Q2
MSP430F5436IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2
MSP430F5437IPNR	LQFP	PN	80	1000	330.0	24.4	15.0	15.0	2.1	20.0	24.0	Q2
MSP430F5438IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2

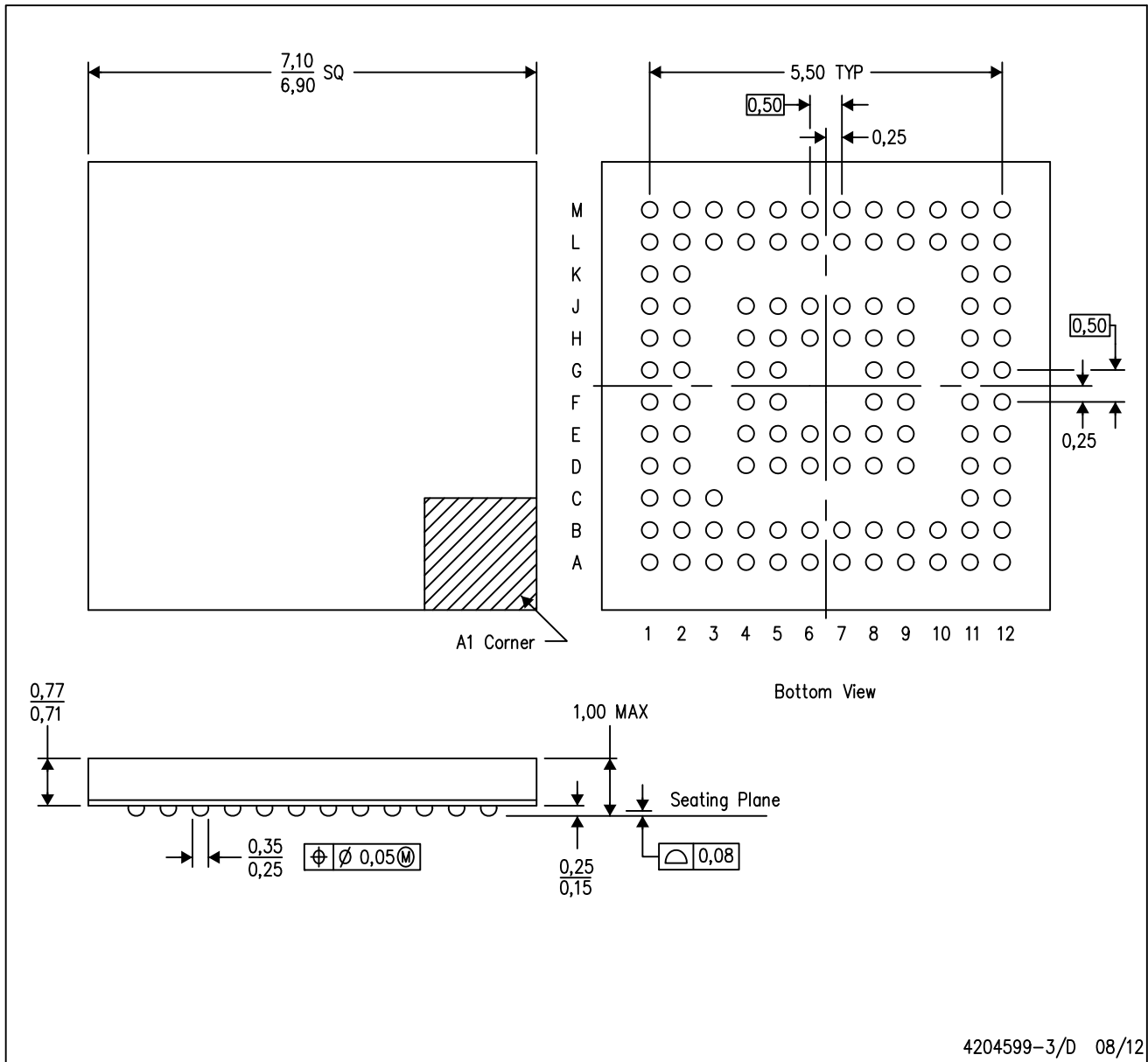
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MSP430F5418IPNR	LQFP	PN	80	1000	367.0	367.0	45.0
MSP430F5419IPZR	LQFP	PZ	100	1000	367.0	367.0	45.0
MSP430F5435IPNR	LQFP	PN	80	1000	367.0	367.0	45.0
MSP430F5436IPZR	LQFP	PZ	100	1000	367.0	367.0	45.0
MSP430F5437IPNR	LQFP	PN	80	1000	367.0	367.0	45.0
MSP430F5438IPZR	LQFP	PZ	100	1000	367.0	367.0	45.0

ZQW (S-PBGA-N113)

PLASTIC BALL GRID ARRAY

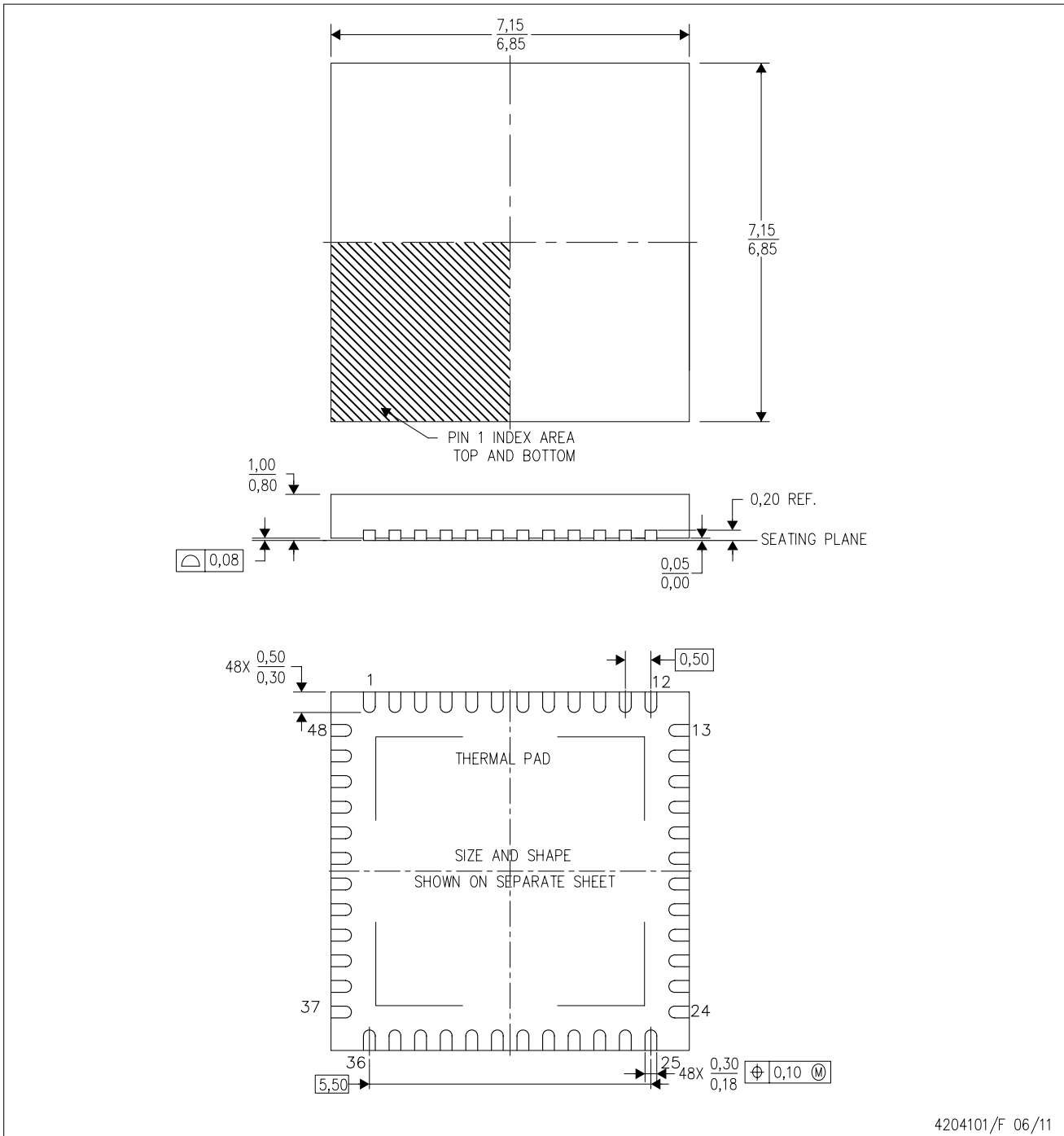


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RGZ (S-PVQFN-N48)

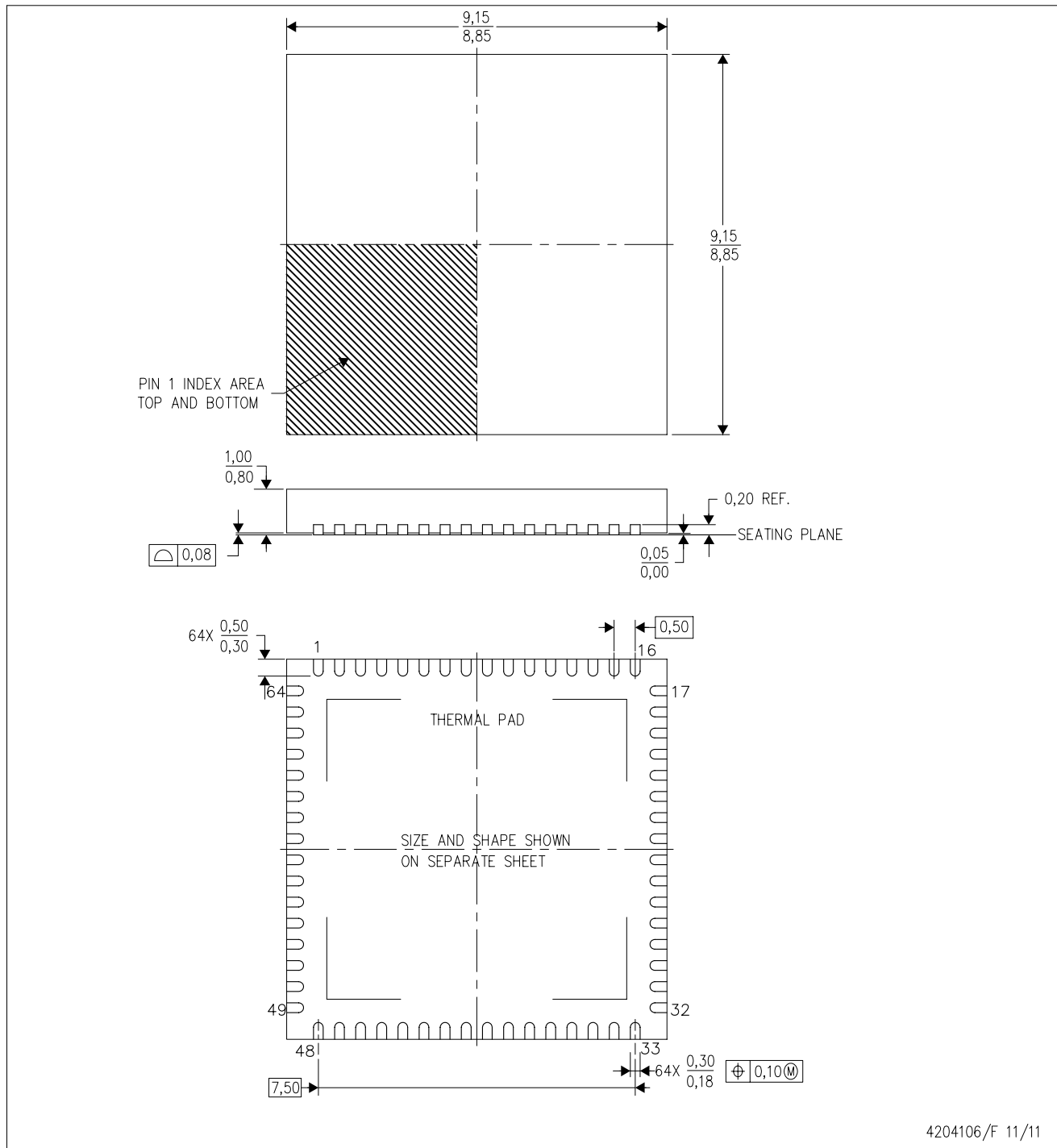
PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Quad Flatpack, No-leads (QFN) package configuration.
 - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - F. Falls within JEDEC MO-220.

MECHANICAL DATA

RGC(S-PVQFN-N64) CUSTOM DEVICE PLASTIC QUAD FLATPACK NO-LEAD

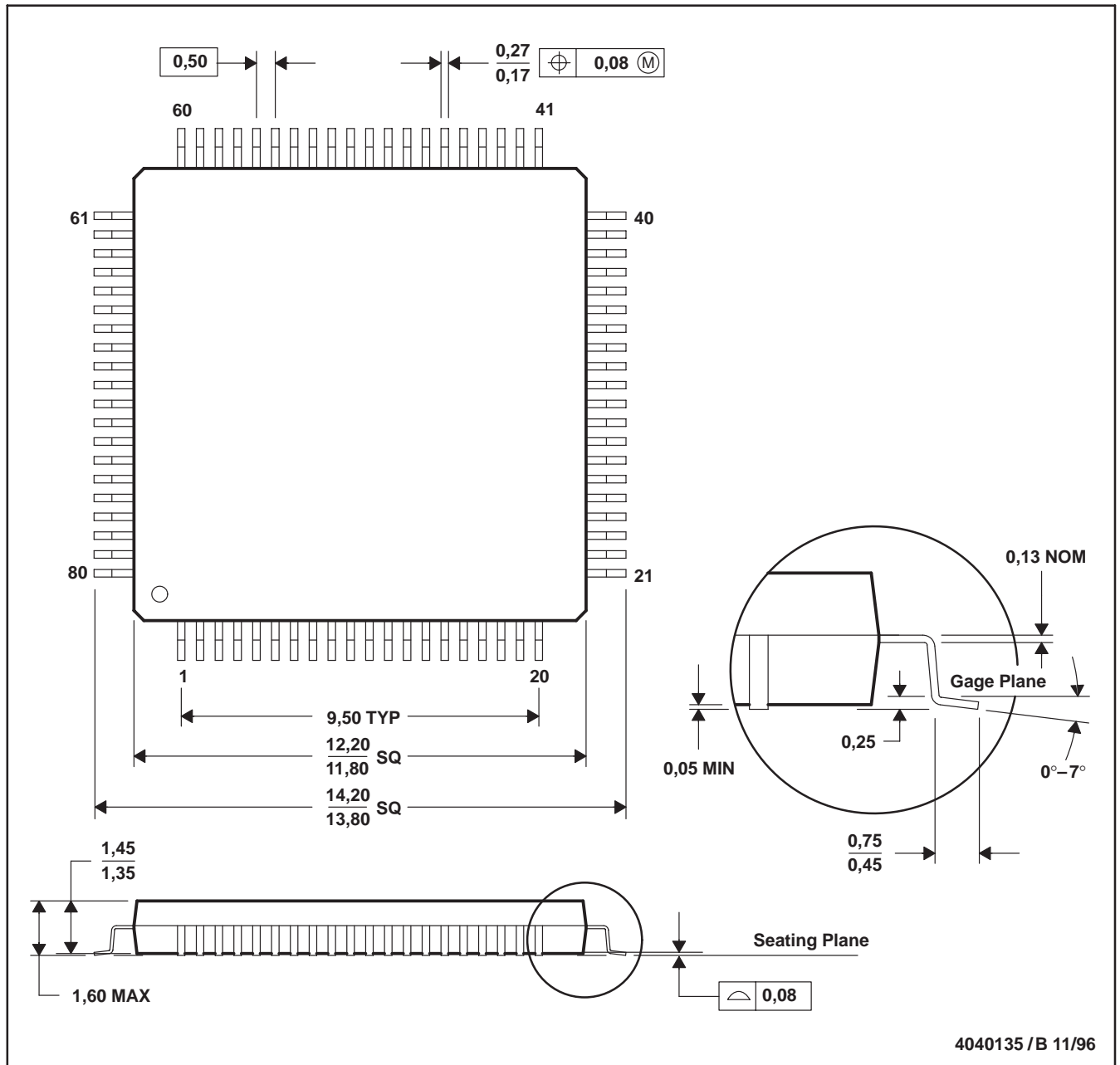


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- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5-1994.
 - This drawing is subject to change without notice.
 - Quad Flatpack, No-leads (QFN) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

PN (S-PQFP-G80)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-026

PZ (S-PQFP-G100)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-026

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